



High Slew Rate, Wide Bandwidth, Single Supply Operational Amplifiers

Quality bipolar fabrication with innovative design concepts are employed for the MC33071/72/74, MC34071/72/74 series of monolithic operational amplifiers. This series of operational amplifiers offer 4.5 MHz of gain bandwidth product, 13 V/μs slew rate and fast setting time without the use of JFET device technology. Although this series can be operated from split supplies, it is particularly suited for single supply operation, since the common mode input voltage range includes ground potential (VEE). With A Darlington input stage, this series exhibits high input resistance, low input offset voltage and high gain. The all NPN output stage, characterized by no deadband crossover distortion and large output voltage swing, provides high capacitance drive capability, excellent phase and gain margins, low open loop high frequency output impedance and symmetrical source/sink AC frequency response.

The MC33071/72/74, MC34071/72/73 series of devices are available in standard or prime performance (A Suffix) grades and are specified over the commercial, industrial/vehicular or military temperature ranges. The complete series of single, dual and quad operational amplifiers are available in plastic DIP and SOIC surface mount packages.

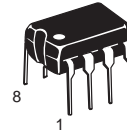
- Wide Bandwidth: 4.5 MHz
- High Slew Rate: 13 V/μs
- Fast Settling Time: 1.1 μs to 0.1%
- Wide Single Supply Operation: 3.0 V to 44 V
- Wide Input Common Mode Voltage Range: Includes Ground (VEE)
- Low Input Offset Voltage: 3.0 mV Maximum (A Suffix)
- Large Output Voltage Swing: -14.7 V to +14 V (with ±15 V Supplies)
- Large Capacitance Drive Capability: 0 pF to 10,000 pF
- Low Total Harmonic Distortion: 0.02%
- Excellent Phase Margin: 60°
- Excellent Gain Margin: 12 dB
- Output Short Circuit Protection
- ESD Diodes/Clamps Provide Input Protection for Dual and Quad

ORDERING INFORMATION

Op Amp Function	Device	Operating Temperature Range	Package
Single	MC34071P, AP MC34071D, AD	T _A = 0° to +70°C	Plastic DIP SO-8
	MC33071P, AP MC33071D, AD	T _A = -40° to +85°C	Plastic DIP SO-8
Dual	MC34072P, AP MC34072D, AD	T _A = 0° to +70°C	Plastic DIP SO-8
	MC33072P, AP MC33072D, AD	T _A = -40° to +85°C	Plastic DIP SO-8
Quad	MC34074P, AP MC34074D, AD	T _A = 0° to +70°C	Plastic DIP SO-14
	MC33074P, AP MC33074D, AD	T _A = -40° to +85°C	Plastic DIP SO-14

MC34071,2,4,A MC33071,2,4,A

HIGH BANDWIDTH SINGLE SUPPLY OPERATIONAL AMPLIFIERS

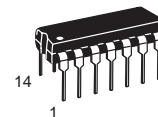
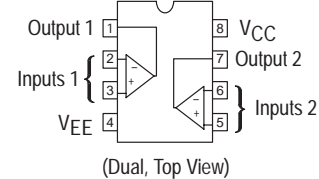
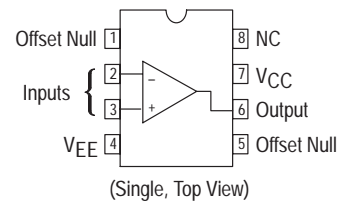


P SUFFIX
PLASTIC PACKAGE
CASE 626

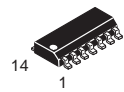


D SUFFIX
PLASTIC PACKAGE
CASE 751
(SO-8)

PIN CONNECTIONS

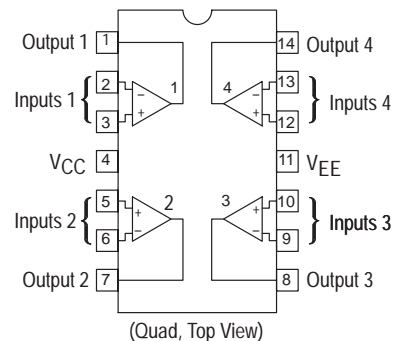


P SUFFIX
PLASTIC PACKAGE
CASE 646



D SUFFIX
PLASTIC PACKAGE
CASE 751A
(SO-14)

PIN CONNECTIONS



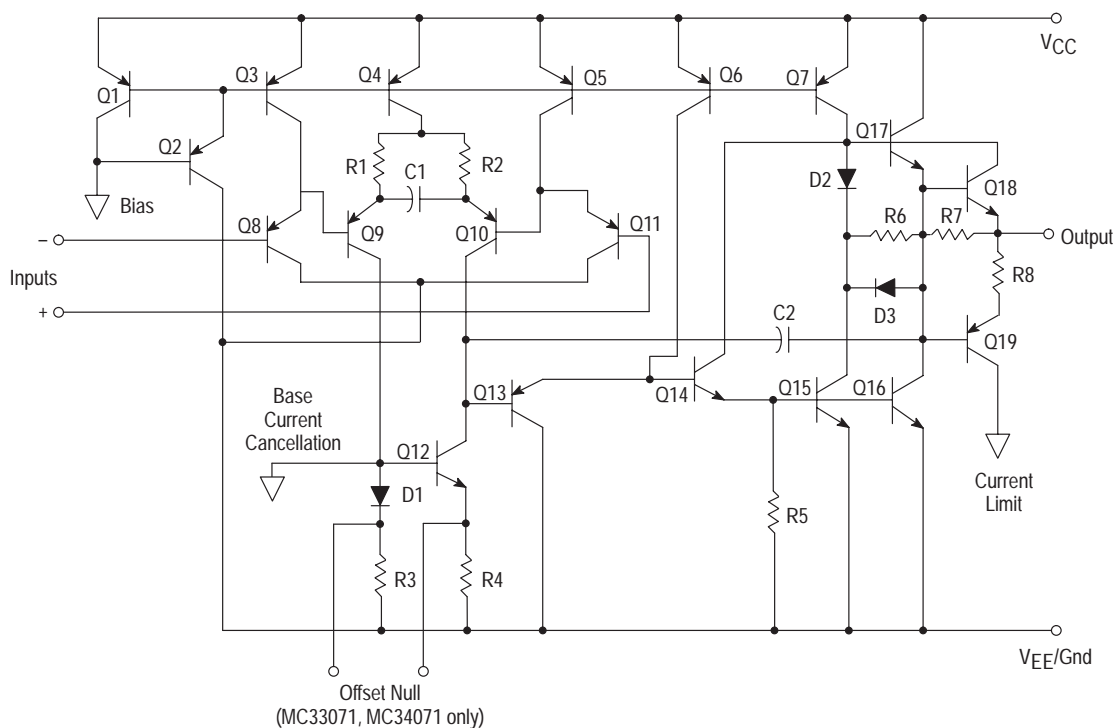
MC34071,2,4,A MC33071,2,4,A

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Supply Voltage (from V_{EE} to V_{CC})	V_S	+44	V
Input Differential Voltage Range	V_{IDR}	Note 1	V
Input Voltage Range	V_{IR}	Note 1	V
Output Short Circuit Duration (Note 2)	t_{SC}	Indefinite	sec
Operating Junction Temperature	T_J	+150	°C
Storage Temperature Range	T_{stg}	-60 to +150	°C

NOTES: 1. Either or both input voltages should not exceed the magnitude of V_{CC} or V_{EE} .
 2. Power dissipation must be considered to ensure maximum junction temperature (T_J) is not exceeded (see Figure 1).

Representative Schematic Diagram
(Each Amplifier)



MC34071,2,4,A MC33071,2,4,A

ELECTRICAL CHARACTERISTICS ($V_{CC} = +15\text{ V}$, $V_{EE} = -15\text{ V}$, R_L = connected to ground, unless otherwise noted. See Note 3 for $T_A = T_{low}$ to T_{high})

Characteristics	Symbol	A Suffix			Non-Suffix			Unit
		Min	Typ	Max	Min	Typ	Max	
Input Offset Voltage ($R_S = 100\ \Omega$, $V_{CM} = 0\text{ V}$, $V_O = 0\text{ V}$) $V_{CC} = +15\text{ V}$, $V_{EE} = -15\text{ V}$, $T_A = +25^\circ\text{C}$ $V_{CC} = +5.0\text{ V}$, $V_{EE} = 0\text{ V}$, $T_A = +25^\circ\text{C}$ $V_{CC} = +15\text{ V}$, $V_{EE} = -15\text{ V}$, $T_A = T_{low}$ to T_{high}	V_{IO}	— — —	0.5 0.5 —	3.0 3.0 5.0	— — —	1.0 1.5 —	5.0 5.0 7.0	mV
Average Temperature Coefficient of Input Offset Voltage $R_S = 10\ \Omega$, $V_{CM} = 0\text{ V}$, $V_O = 0\text{ V}$, $T_A = T_{low}$ to T_{high}	$\Delta V_{IO}/\Delta T$	—	10	—	—	10	—	$\mu\text{V}/^\circ\text{C}$
Input Bias Current ($V_{CM} = 0\text{ V}$, $V_O = 0\text{ V}$) $T_A = +25^\circ\text{C}$ $T_A = T_{low}$ to T_{high}	I_{IB}	— —	100 —	500 700	— —	100 —	500 700	nA
Input Offset Current ($V_{CM} = 0\text{ V}$, $V_O = 0\text{ V}$) $T_A = +25^\circ\text{C}$ $T_A = T_{low}$ to T_{high}	I_{IO}	— —	6.0 —	50 300	— —	6.0 —	75 300	nA
Input Common Mode Voltage Range $T_A = +25^\circ\text{C}$ $T_A = T_{low}$ to T_{high}	V_{ICR}	V_{EE} to $(V_{CC} - 1.8)$ V_{EE} to $(V_{CC} - 2.2)$			V_{EE} to $(V_{CC} - 1.8)$ V_{EE} to $(V_{CC} - 2.2)$			V
Large Signal Voltage Gain ($V_O = \pm 10\text{ V}$, $R_L = 2.0\text{ k}\Omega$) $T_A = +25^\circ\text{C}$ $T_A = T_{low}$ to T_{high}	A_{VOL}	50 25	100 —	— —	25 20	100 —	— —	V/mV
Output Voltage Swing ($V_{ID} = \pm 1.0\text{ V}$) $V_{CC} = +5.0\text{ V}$, $V_{EE} = 0\text{ V}$, $R_L = 2.0\text{ k}\Omega$, $T_A = +25^\circ\text{C}$ $V_{CC} = +15\text{ V}$, $V_{EE} = -15\text{ V}$, $R_L = 10\text{ k}\Omega$, $T_A = +25^\circ\text{C}$ $V_{CC} = +15\text{ V}$, $V_{EE} = -15\text{ V}$, $R_L = 2.0\text{ k}\Omega$, $T_A = T_{low}$ to T_{high}	V_{OH}	3.7 13.6 13.4	4.0 14 —	— — —	3.7 13.6 13.4	4.0 14 —	— — —	V
$V_{CC} = +5.0\text{ V}$, $V_{EE} = 0\text{ V}$, $R_L = 2.0\text{ k}\Omega$, $T_A = +25^\circ\text{C}$ $V_{CC} = +15\text{ V}$, $V_{EE} = -15\text{ V}$, $R_L = 10\text{ k}\Omega$, $T_A = +25^\circ\text{C}$ $V_{CC} = +15\text{ V}$, $V_{EE} = -15\text{ V}$, $R_L = 2.0\text{ k}\Omega$, $T_A = T_{low}$ to T_{high}	V_{OL}	— — —	0.1 -14.7 —	0.3 -14.3 -13.5	— — —	0.1 -14.7 —	0.3 -14.3 -13.5	V
Output Short Circuit Current ($V_{ID} = 1.0\text{ V}$, $V_O = 0\text{ V}$, $T_A = 25^\circ\text{C}$) Source Sink	I_{SC}	10 20	30 30	— —	10 20	30 30	— —	mA
Common Mode Rejection $R_S \leq 10\text{ k}\Omega$, $V_{CM} = V_{ICR}$, $T_A = 25^\circ\text{C}$	CMR	80	97	—	70	97	—	dB
Power Supply Rejection ($R_S = 100\ \Omega$) $V_{CC}/V_{EE} = +16.5\text{ V}/-16.5\text{ V}$ to $+13.5\text{ V}/-13.5\text{ V}$, $T_A = 25^\circ\text{C}$	PSR	80	97	—	70	97	—	dB
Power Supply Current (Per Amplifier, No Load) $V_{CC} = +5.0\text{ V}$, $V_{EE} = 0\text{ V}$, $V_O = +2.5\text{ V}$, $T_A = +25^\circ\text{C}$ $V_{CC} = +15\text{ V}$, $V_{EE} = -15\text{ V}$, $V_O = 0\text{ V}$, $T_A = +25^\circ\text{C}$ $V_{CC} = +15\text{ V}$, $V_{EE} = -15\text{ V}$, $V_O = 0\text{ V}$, $T_A = T_{low}$ to T_{high}	I_D	— — —	1.6 1.9 —	2.0 2.5 2.8	— — —	1.6 1.9 —	2.0 2.5 2.8	mA

NOTES: 3. $T_{low} = -40^\circ\text{C}$ for MC33071, 2, 4, /A
= 0°C for MC34071, 2, 4, /A

$T_{high} = +85^\circ\text{C}$ for MC33071, 2, 4, /A
= $+70^\circ\text{C}$ for MC34071, 2, 4, /A

MC34071,2,4,A MC33071,2,4,A

AC ELECTRICAL CHARACTERISTICS ($V_{CC} = +15\text{ V}$, $V_{EE} = -15\text{ V}$, $R_L =$ connected to ground. $T_A = +25^\circ\text{C}$, unless otherwise noted.)

Characteristics	Symbol	A Suffix			Non-Suffix			Unit
		Min	Typ	Max	Min	Typ	Max	
Slew Rate ($V_{in} = -10\text{ V}$ to $+10\text{ V}$, $R_L = 2.0\text{ k}\Omega$, $C_L = 500\text{ pF}$) $A_V = +1.0$ $A_V = -1.0$	SR	8.0 —	10 13	— —	8.0 —	10 13	— —	V/ μs
Setting Time (10 V Step, $A_V = -1.0$) To 0.1% (+1/2 LSB of 9-Bits) To 0.01% (+1/2 LSB of 12-Bits)	t_s	— —	1.1 2.2	— —	— —	1.1 2.2	— —	μs
Gain Bandwidth Product ($f = 100\text{ kHz}$)	GBW	3.5	4.5	—	3.5	4.5	—	MHz
Power Bandwidth $A_V = +1.0$, $R_L = 2.0\text{ k}\Omega$, $V_O = 20\text{ V}_{pp}$, THD = 5.0%	BW	—	160	—	—	160	—	kHz
Phase margin $R_L = 2.0\text{ k}\Omega$ $R_L = 2.0\text{ k}\Omega$, $C_L = 300\text{ pF}$	f_m	— —	60 40	— —	— —	60 40	— —	Deg
Gain Margin $R_L = 2.0\text{ k}\Omega$ $R_L = 2.0\text{ k}\Omega$, $C_L = 300\text{ pF}$	A_m	— —	12 4.0	— —	— —	12 4.0	— —	dB
Equivalent Input Noise Voltage $R_S = 100\ \Omega$, $f = 1.0\text{ kHz}$	e_n	—	32	—	—	32	—	nV/ $\sqrt{\text{Hz}}$
Equivalent Input Noise Current $f = 1.0\text{ kHz}$	i_n	—	0.22	—	—	0.22	—	pA/ $\sqrt{\text{Hz}}$
Differential Input Resistance $V_{CM} = 0\text{ V}$	R_{in}	—	150	—	—	150	—	M Ω
Differential Input Capacitance $V_{CM} = 0\text{ V}$	C_{in}	—	2.5	—	—	2.5	—	pF
Total Harmonic Distortion $A_V = +10$, $R_L = 2.0\text{ k}\Omega$, $2.0\text{ V}_{pp} \leq V_O \leq 20\text{ V}_{pp}$, $f = 10\text{ kHz}$	THD	—	0.02	—	—	0.02	—	%
Channel Separation ($f = 10\text{ kHz}$)	—	—	120	—	—	120	—	dB
Open Loop Output Impedance ($f = 1.0\text{ MHz}$)	$ Z_O $	—	30	—	—	30	—	W

Figure 1. Power Supply Configurations

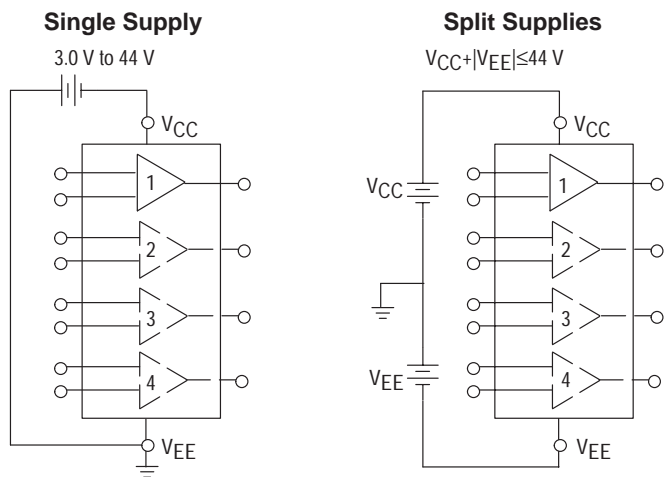
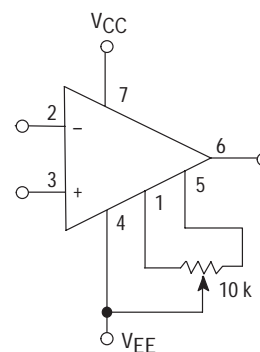


Figure 2. Offset Null Circuit



Offset nulling range is approximately $\pm 80\text{ mV}$ with a 10 k potentiometer (MC33071, MC34071 only).

Figure 3. Maximum Power Dissipation versus Temperature for Package Types

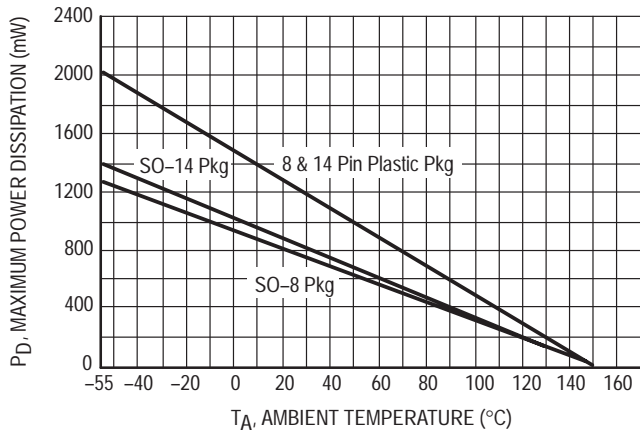


Figure 4. Input Offset Voltage versus Temperature for Representative Units

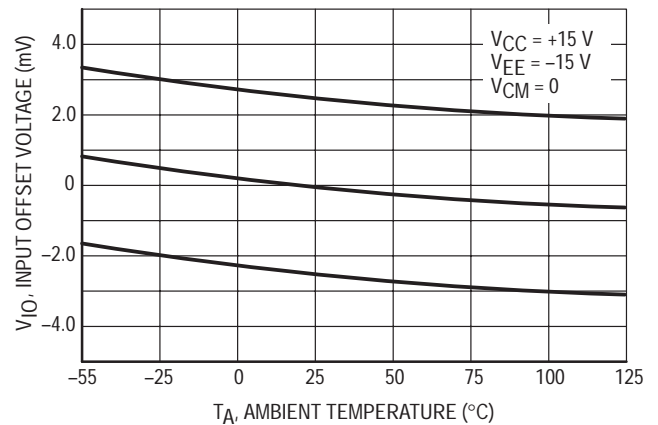


Figure 5. Input Common Mode Voltage Range versus Temperature

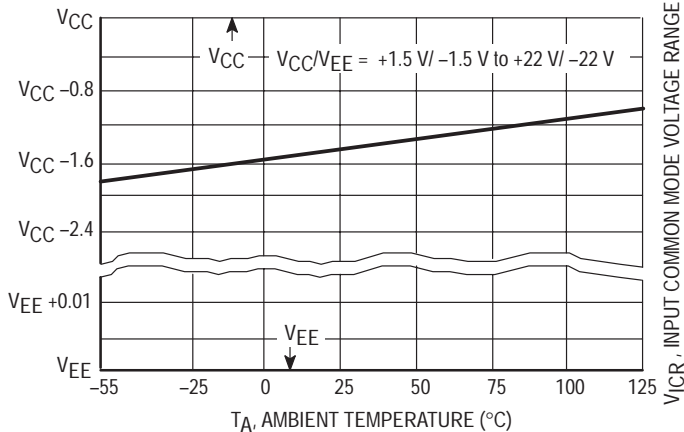


Figure 6. Normalized Input Bias Current versus Temperature

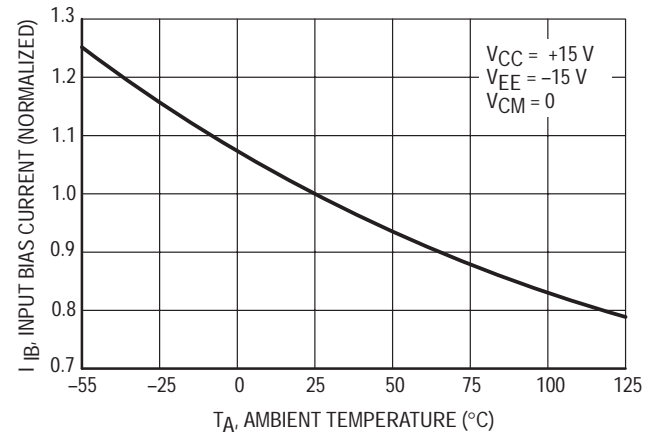


Figure 7. Normalized Input Bias Current versus Input Common Mode Voltage

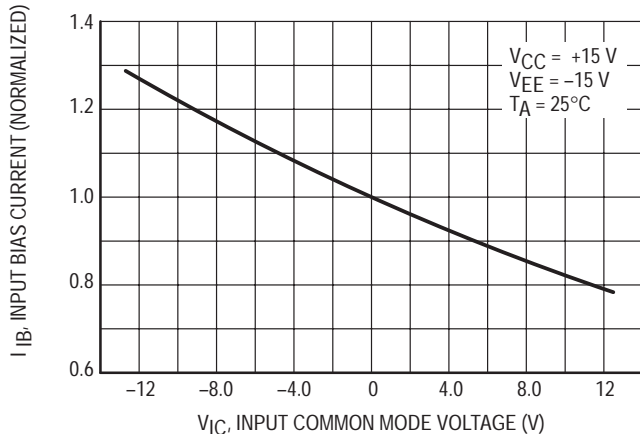


Figure 8. Split Supply Output Voltage Swing versus Supply Voltage

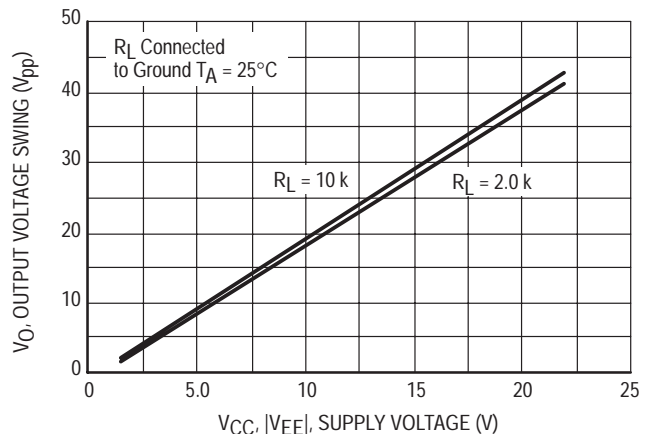


Figure 9. Single Supply Output Saturation versus Load Resistance to V_{CC}

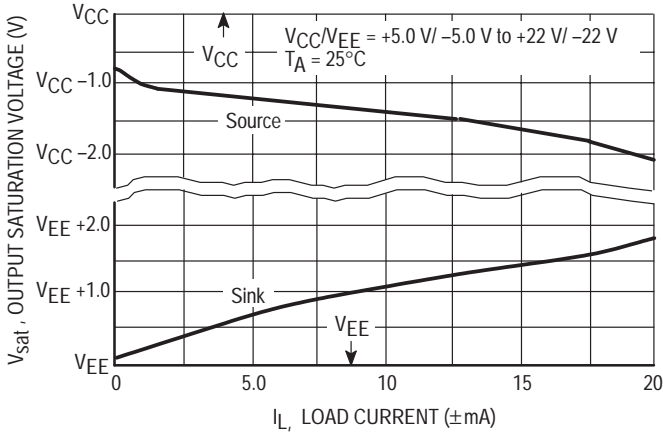


Figure 10. Split Supply Output Saturation versus Load Current

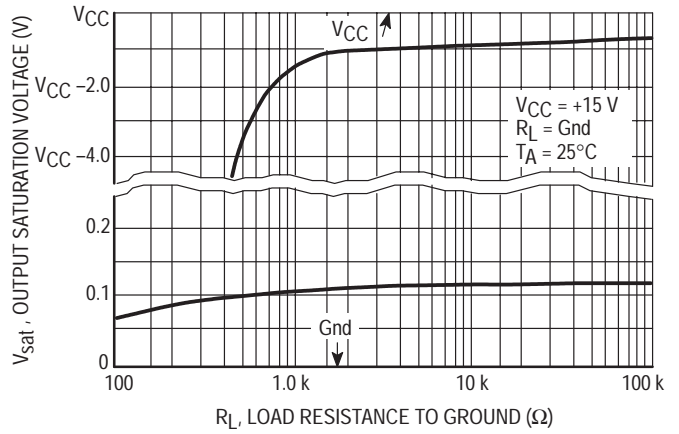


Figure 11. Single Supply Output Saturation versus Load Resistance to Ground

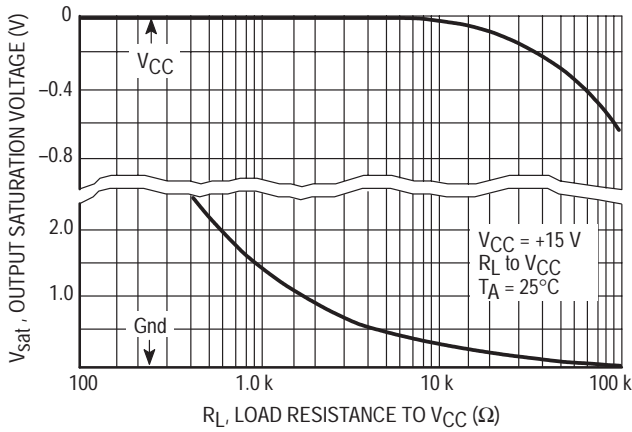


Figure 12. Output Short Circuit Current versus Temperature

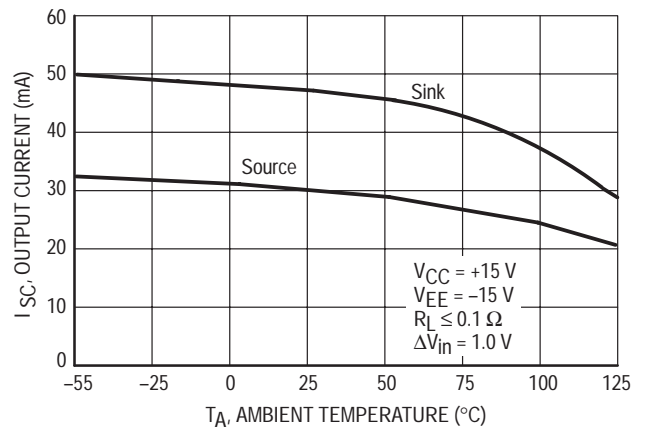


Figure 13. Output Impedance versus Frequency

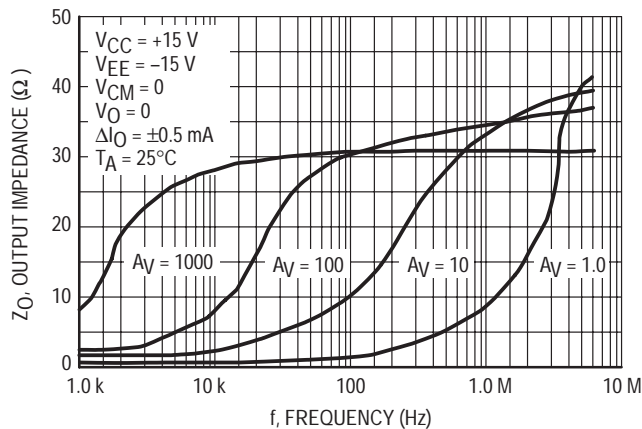


Figure 14. Output Voltage Swing versus Frequency

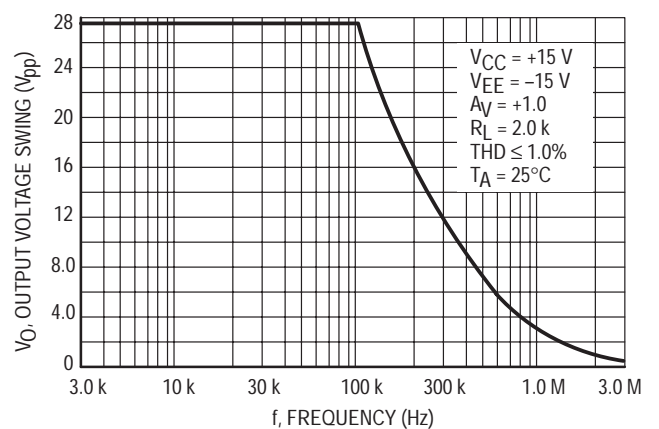


Figure 15. Total Harmonic Distortion versus Frequency

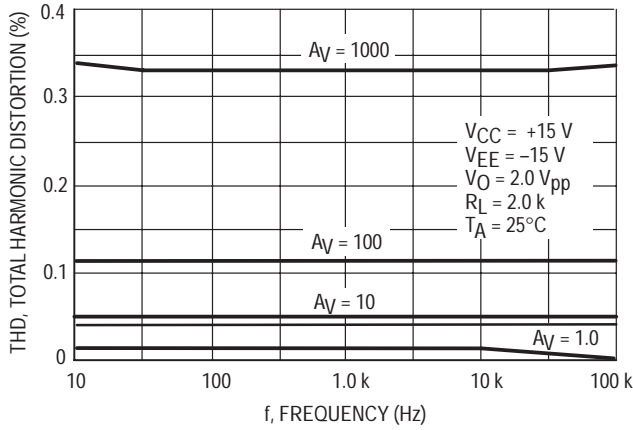


Figure 16. Total Harmonic Distortion versus Output Voltage Swing

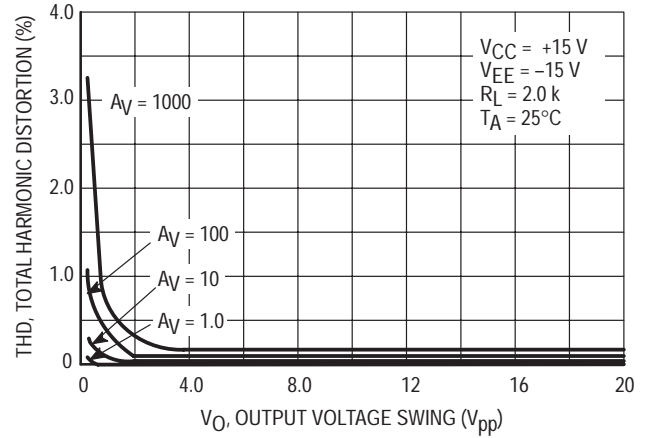


Figure 17. Open Loop Voltage Gain versus Temperature

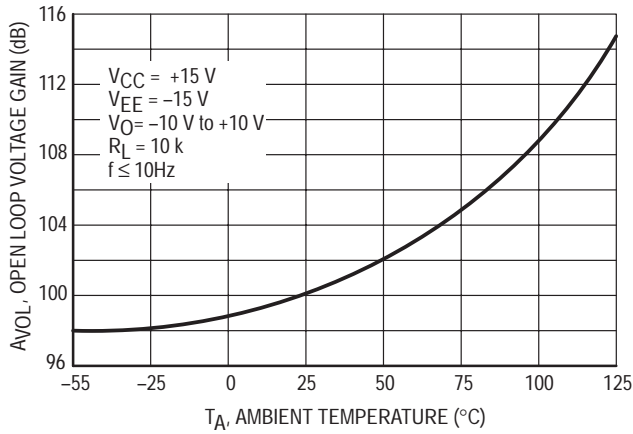


Figure 18. Open Loop Voltage Gain and Phase versus Frequency

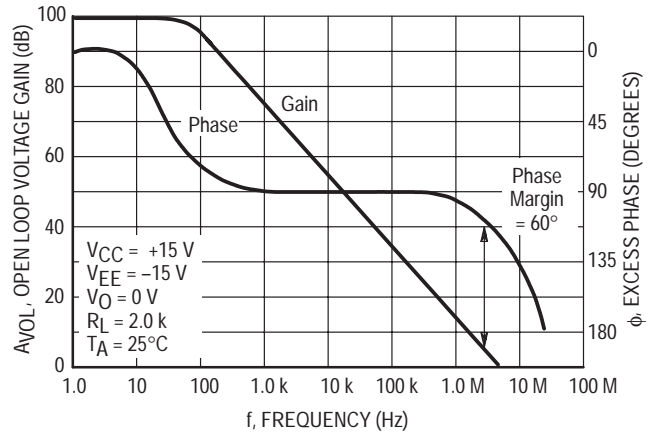


Figure 19. Open Loop Voltage Gain and Phase versus Frequency

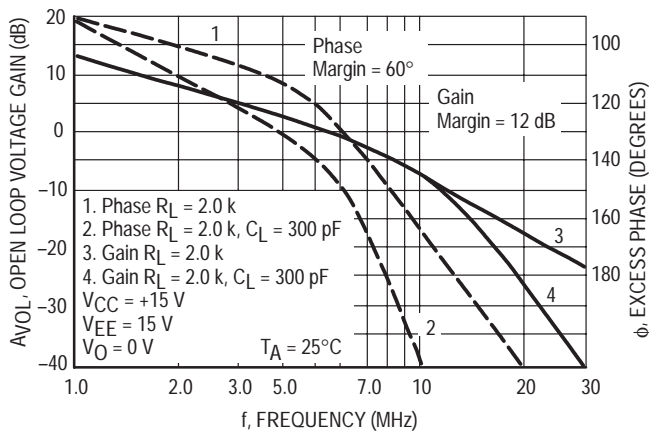


Figure 20. Normalized Gain Bandwidth Product versus Temperature

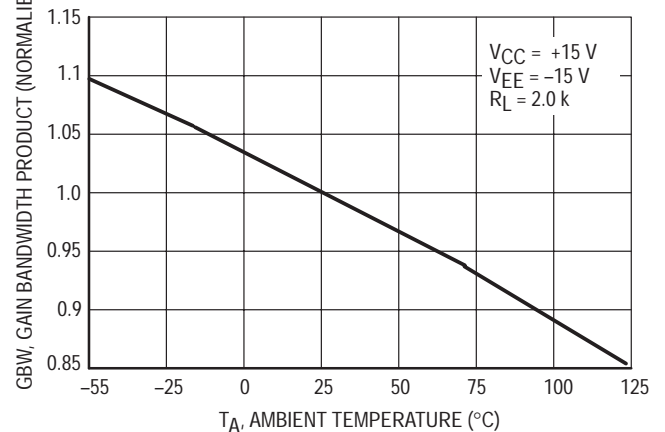


Figure 21. Percent Overshoot versus Load Capacitance

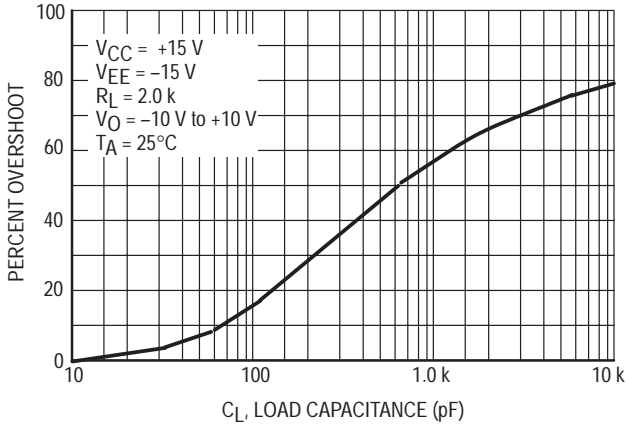


Figure 22. Phase Margin versus Load Capacitance

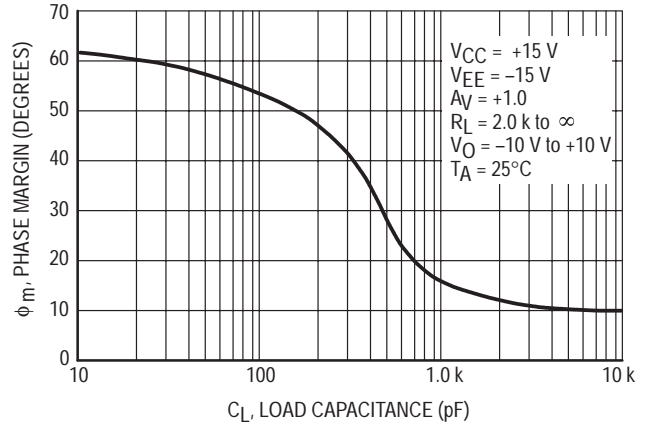


Figure 23. Gain Margin versus Load Capacitance

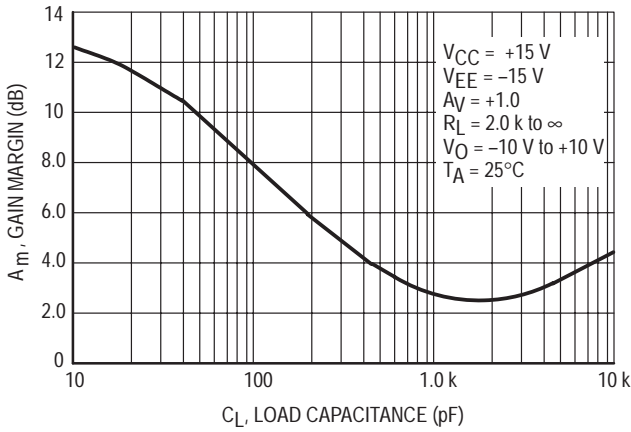


Figure 24. Phase Margin versus Temperature

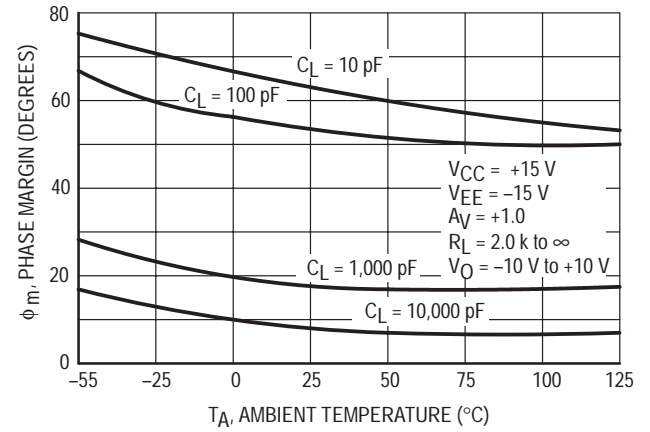


Figure 25. Gain Margin versus Temperature

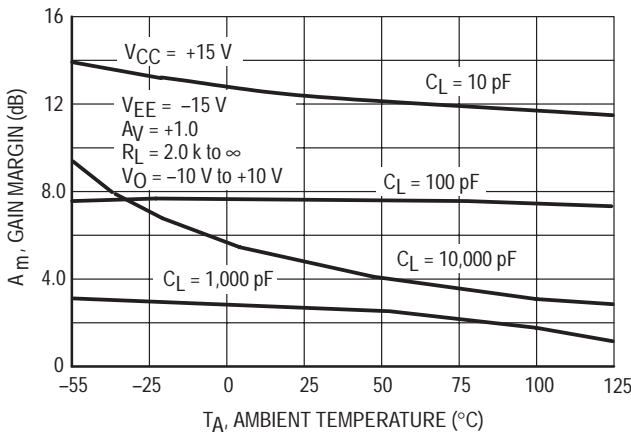


Figure 26. Phase Margin and Gain Margin versus Differential Source Resistance

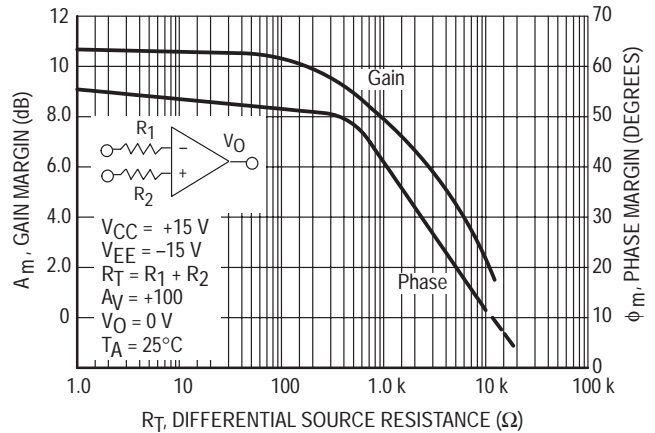


Figure 27. Normalized Slew Rate versus Temperature

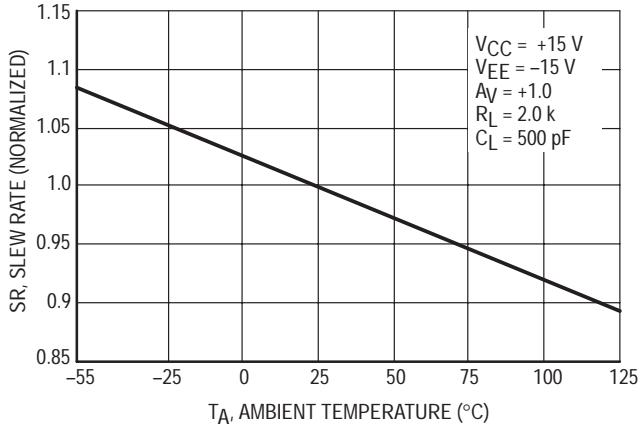


Figure 28. Output Settling Time

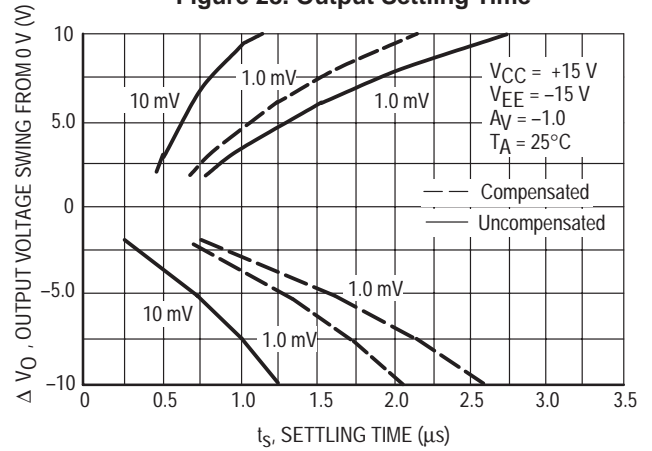


Figure 29. Small Signal Transient Response

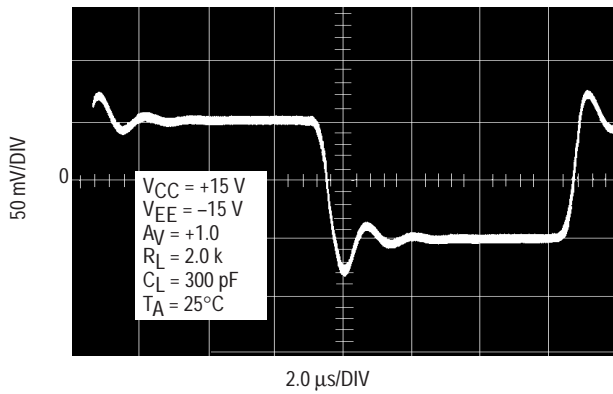


Figure 30. Large Signal Transient Response

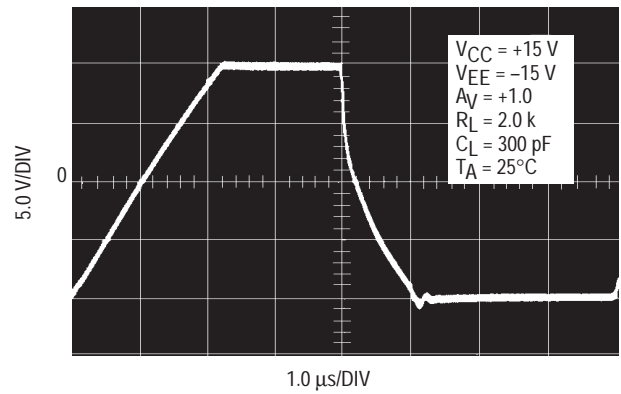


Figure 31. Common Mode Rejection versus Frequency

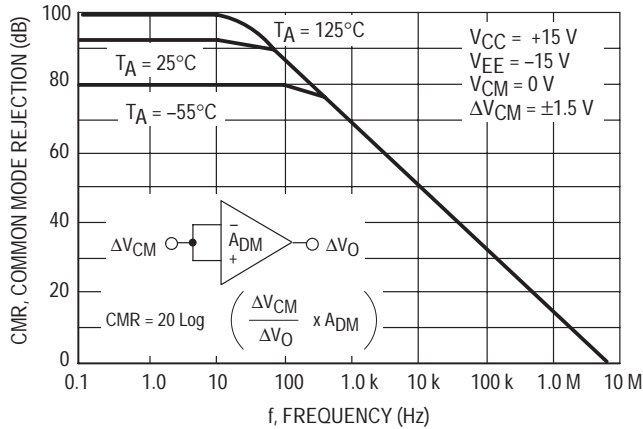


Figure 32. Power Supply Rejection versus Frequency

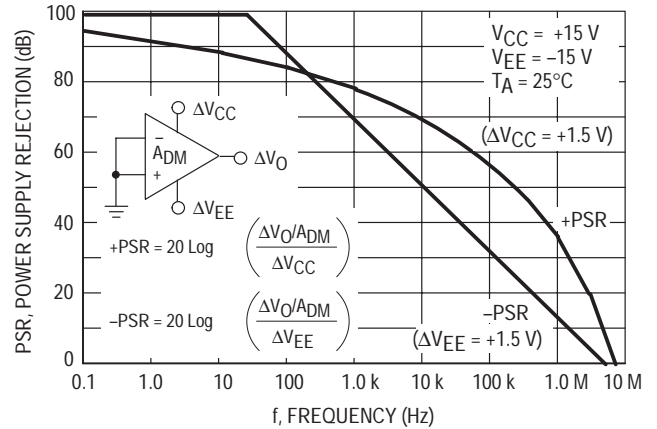


Figure 33. Supply Current versus Supply Voltage

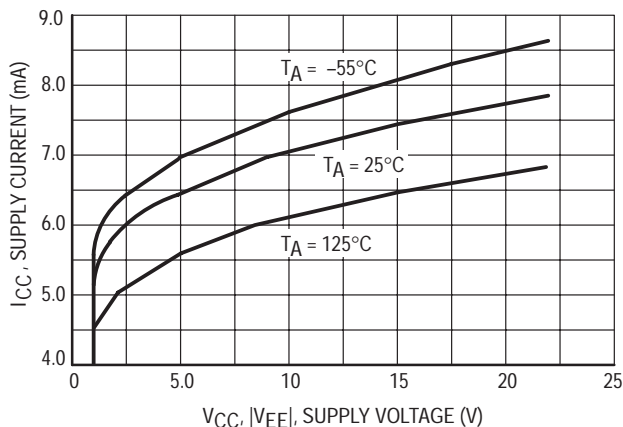


Figure 34. Power Supply Rejection versus Temperature

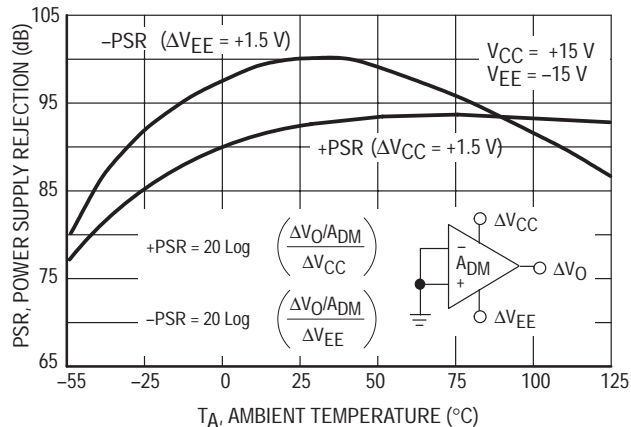


Figure 35. Channel Separation versus Frequency

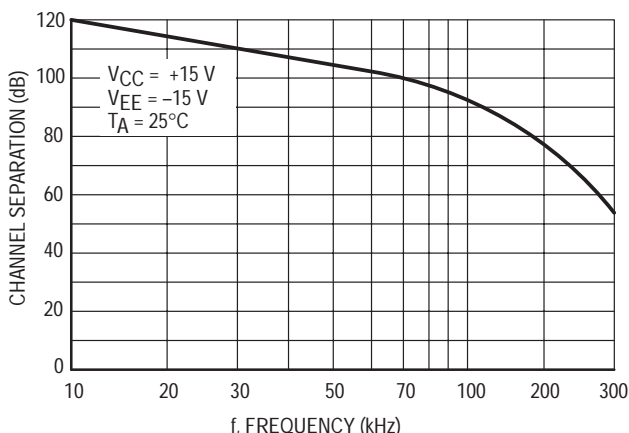
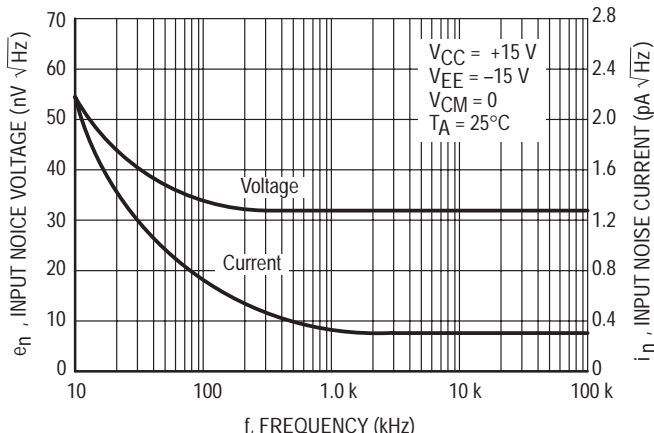


Figure 36. Input Noise versus Frequency



APPLICATIONS INFORMATION
CIRCUIT DESCRIPTION/PERFORMANCE FEATURES

Although the bandwidth, slew rate, and settling time of the MC34071 amplifier series are similar to op amp products utilizing JFET input devices, these amplifiers offer other additional distinct advantages as a result of the PNP transistor differential input stage and an all NPN transistor output stage.

Since the input common mode voltage range of this input stage includes the V_{EE} potential, single supply operation is feasible to as low as 3.0 V with the common mode input voltage at ground potential.

The input stage also allows differential input voltages up to $\pm 44\text{ V}$, provided the maximum input voltage range is not exceeded. Specifically, the input voltages must range

between V_{EE} and V_{CC} supply voltages as shown by the maximum rating table. In practice, although not recommended, the input voltages can exceed the V_{CC} voltage by approximately 3.0 V and decrease below the V_{EE} voltage by 0.3 V without causing product damage, although output phase reversal may occur. It is also possible to source up to approximately 5.0 mA of current from V_{EE} through either inputs clamping diode without damage or latching, although phase reversal may again occur.

If one or both inputs exceed the upper common mode voltage limit, the amplifier output is readily predictable and may be in a low or high state depending on the existing input bias conditions.

Since the input capacitance associated with the small geometry input device is substantially lower (2.5 pF) than the typical JFET input gate capacitance (5.0 pF), better frequency response for a given input source resistance can be achieved using the MC34071 series of amplifiers. This performance feature becomes evident, for example, in fast settling D-to-A current to voltage conversion applications where the feedback resistance can form an input pole with the input capacitance of the op amp. This input pole creates a 2nd order system with the single pole op amp and is therefore detrimental to its settling time. In this context, lower input capacitance is desirable especially for higher values of feedback resistances (lower current DACs). This input pole can be compensated for by creating a feedback zero with a capacitance across the feedback resistance, if necessary, to reduce overshoot. For 2.0 k Ω of feedback resistance, the MC34071 series can settle to within 1/2 LSB of 8 bits in 1.0 μ s, and within 1/2 LSB of 12-bits in 2.2 μ s for a 10 V step. In a inverting unity gain fast settling configuration, the symmetrical slew rate is ± 13 V/ μ s. In the classic noninverting unity gain configuration, the output positive slew rate is +10 V/ μ s, and the corresponding negative slew rate will exceed the positive slew rate as a function of the fall time of the input waveform.

Since the bipolar input device matching characteristics are superior to that of JFETs, a low untrimmed maximum offset voltage of 3.0 mV prime and 5.0 mV downgrade can be economically offered with high frequency performance characteristics. This combination is ideal for low cost precision, high speed quad op amp applications.

The all NPN output stage, shown in its basic form on the equivalent circuit schematic, offers unique advantages over the more conventional NPN/PNP transistor Class AB output stage. A 10 k Ω load resistance can swing within 1.0 V of the positive rail (V_{CC}), and within 0.3 V of the negative rail (V_{EE}), providing a 28.7 V_{pp} swing from ± 15 V supplies. This large output swing becomes most noticeable at lower supply voltages.

The positive swing is limited by the saturation voltage of the current source transistor Q₇, and V_{BE} of the NPN pull up transistor Q₁₇, and the voltage drop associated with the short circuit resistance, R₇. The negative swing is limited by the saturation voltage of the pull-down transistor Q₁₆, the voltage drop $I_L R_6$, and the voltage drop associated with resistance R₇, where I_L is the sink load current. For small valued sink currents, the above voltage drops are negligible, allowing the negative swing voltage to approach within millivolts of V_{EE} . For large valued sink currents (>5.0 mA), diode D₃ clamps the voltage across R₆, thus limiting the negative swing to the saturation voltage of Q₁₆, plus the forward diode drop of D₃ ($\approx V_{EE} + 1.0$ V). Thus for a given supply voltage, unprecedented peak-to-peak output voltage swing is possible as indicated by the output swing specifications.

If the load resistance is referenced to V_{CC} instead of ground for single supply applications, the maximum possible output swing can be achieved for a given supply voltage. For

light load currents, the load resistance will pull the output to V_{CC} during the positive swing and the output will pull the load resistance near ground during the negative swing. The load resistance value should be much less than that of the feedback resistance to maximize pull up capability.

Because the PNP output emitter-follower transistor has been eliminated, the MC34071 series offers a 20 mA minimum current sink capability, typically to an output voltage of ($V_{EE} + 1.8$ V). In single supply applications the output can directly source or sink base current from a common emitter NPN transistor for fast high current switching applications.

In addition, the all NPN transistor output stage is inherently fast, contributing to the bipolar amplifier's high gain bandwidth product and fast settling capability. The associated high frequency low output impedance (30 Ω typ @ 1.0 MHz) allows capacitive drive capability from 0 pF to 10,000 pF without oscillation in the unity closed loop gain configuration. The 60° phase margin and 12 dB gain margin as well as the general gain and phase characteristics are virtually independent of the source/sink output swing conditions. This allows easier system phase compensation, since output swing will not be a phase consideration. The high frequency characteristics of the MC34071 series also allow excellent high frequency active filter capability, especially for low voltage single supply applications.

Although the single supply specifications is defined at 5.0 V, these amplifiers are functional to 3.0 V @ 25°C although slight changes in parametrics such as bandwidth, slew rate, and DC gain may occur.

If power to this integrated circuit is applied in reverse polarity or if the IC is installed backwards in a socket, large unlimited current surges will occur through the device that may result in device destruction.

Special static precautions are not necessary for these bipolar amplifiers since there are no MOS transistors on the die.

As with most high frequency amplifiers, proper lead dress, component placement, and PC board layout should be exercised for optimum frequency performance. For example, long unshielded input or output leads may result in unwanted input-output coupling. In order to preserve the relatively low input capacitance associated with these amplifiers, resistors connected to the inputs should be immediately adjacent to the input pin to minimize additional stray input capacitance. This not only minimizes the input pole for optimum frequency response, but also minimizes extraneous "pick up" at this node. Supply decoupling with adequate capacitance immediately adjacent to the supply pin is also important, particularly over temperature, since many types of decoupling capacitors exhibit great impedance changes over temperature.

The output of any one amplifier is current limited and thus protected from a direct short to ground. However, under such conditions, it is important not to allow the device to exceed the maximum junction temperature rating. Typically for ± 15 V supplies, any one output can be shorted continuously to ground without exceeding the maximum temperature rating.

MC34071,2,4,A MC33071,2,4,A

(Typical Single Supply Applications $V_{CC} = 5.0\text{ V}$)

Figure 37. AC Coupled Noninverting Amplifier

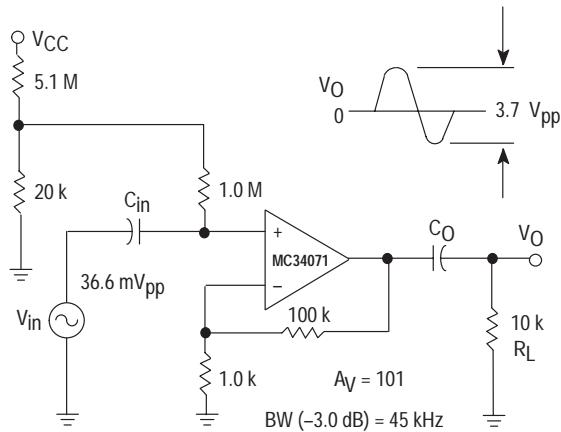
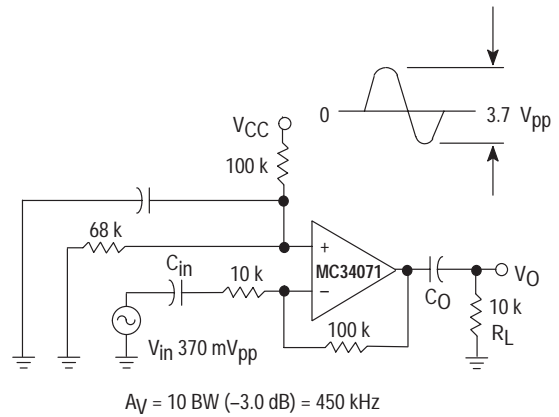


Figure 38. AC Coupled Inverting Amplifier



**Figure 39. DC Coupled Inverting Amplifier
Maximum Output Swing**

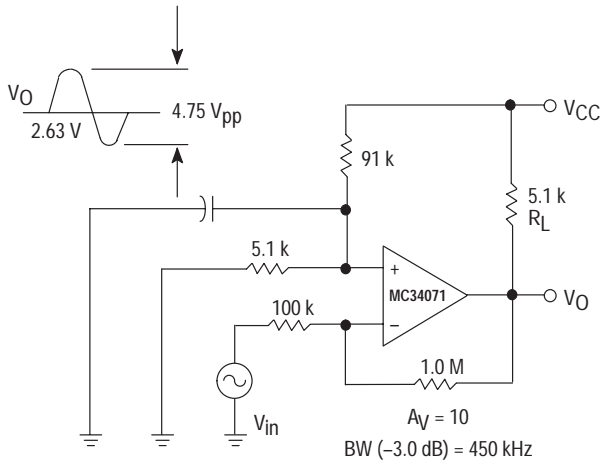


Figure 40. Unity Gain Buffer TTL Driver

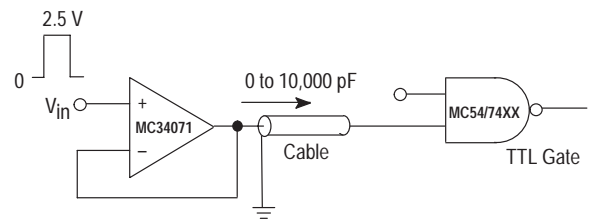


Figure 41. Active High-Q Notch Filter

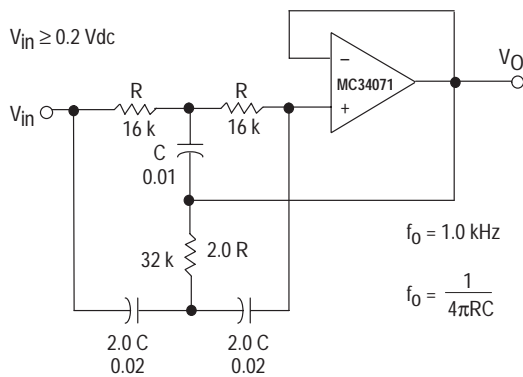
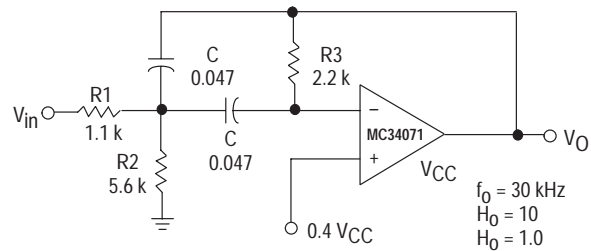


Figure 42. Active Bandpass Filter



Given f_0 = Center Frequency
 A_0 = Gain at Center Frequency
 Choose Value f_0 , Q , A_0 , C

Then:

$$R_3 = \frac{Q}{\pi f_0 C} \quad R_1 = \frac{R_3}{2H_0} \quad R_2 = \frac{R_1 R_3}{4Q^2 R_1 - R_3}$$

For less than 10% error from operational amplifier $\frac{Q_0 f_0}{GBW} < 0.1$

where f_0 and GBW are expressed in Hz.
 $GBW = 4.5\text{ MHz Typ.}$

Figure 43. Low Voltage Fast D/A Converter

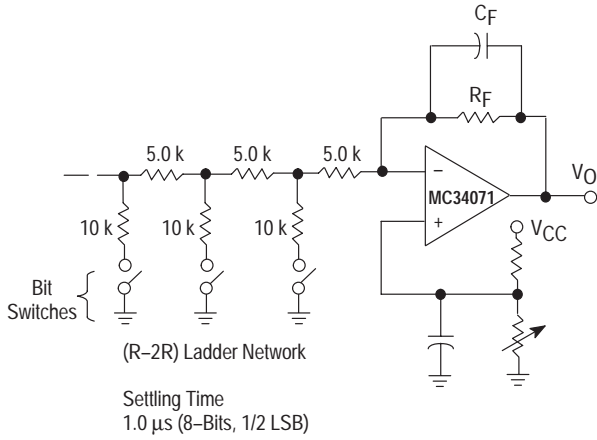


Figure 44. High Speed Low Voltage Comparator

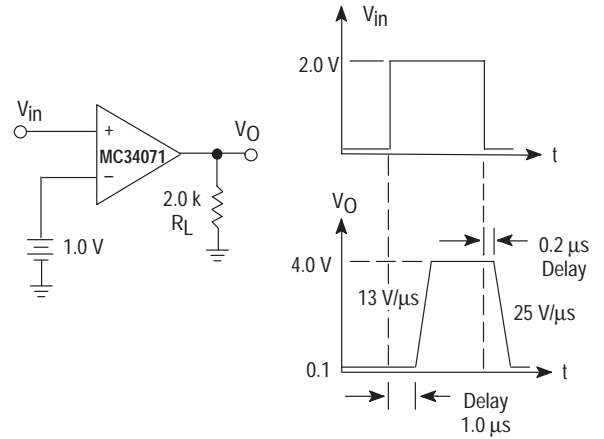


Figure 45. LED Driver

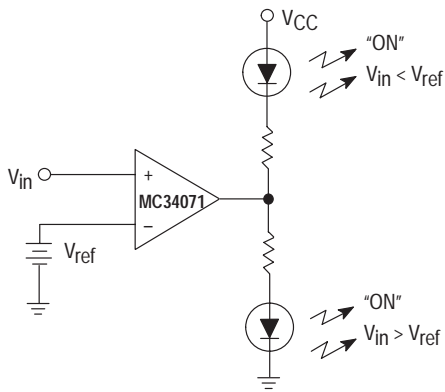


Figure 46. Transistor Driver

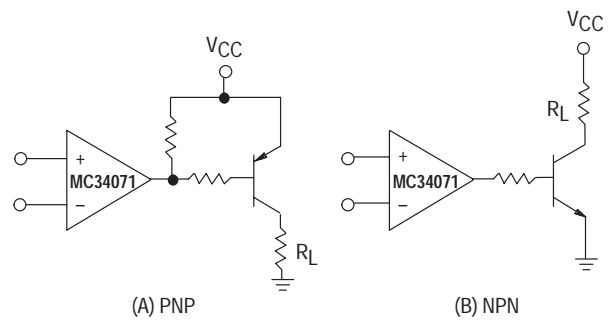


Figure 47. AC/DC Ground Current Monitor

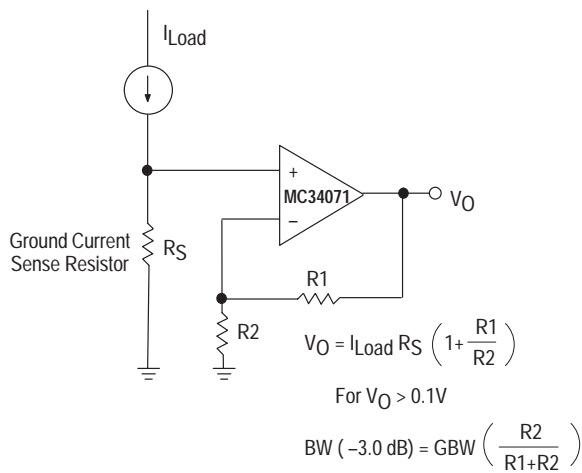


Figure 48. Photovoltaic Cell Amplifier

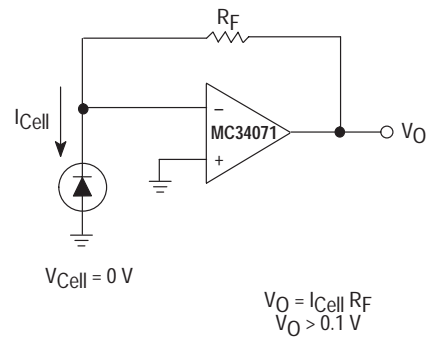


Figure 49. Low Input Voltage Comparator with Hysteresis

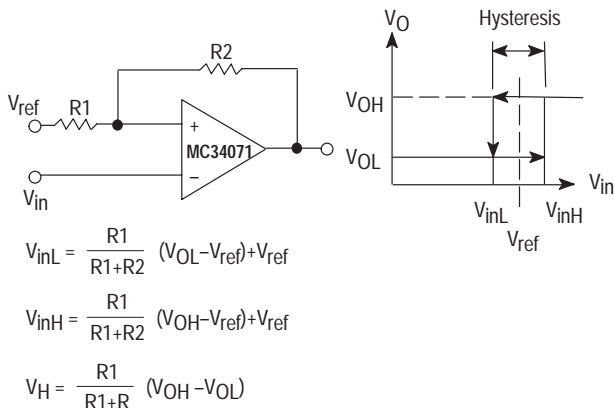


Figure 50. High Compliance Voltage to Sink Current Converter

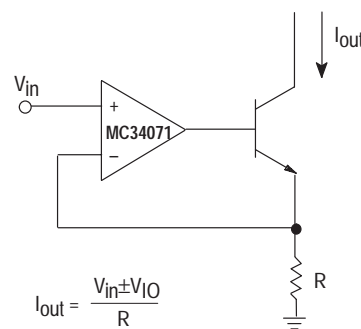


Figure 51. High Input Impedance Differential Amplifier

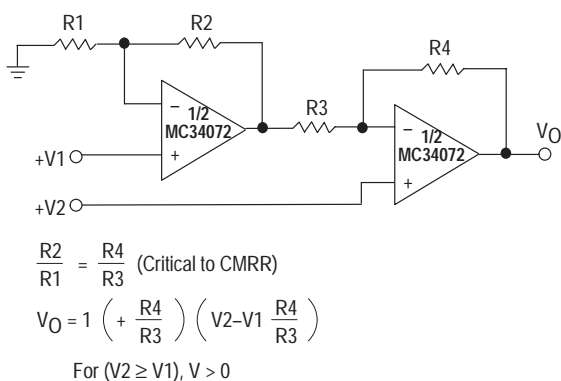


Figure 52. Bridge Current Amplifier

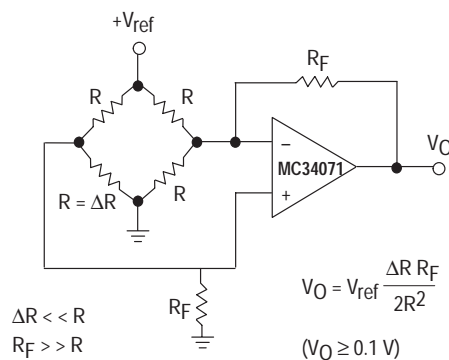


Figure 53. Low Voltage Peak Detector

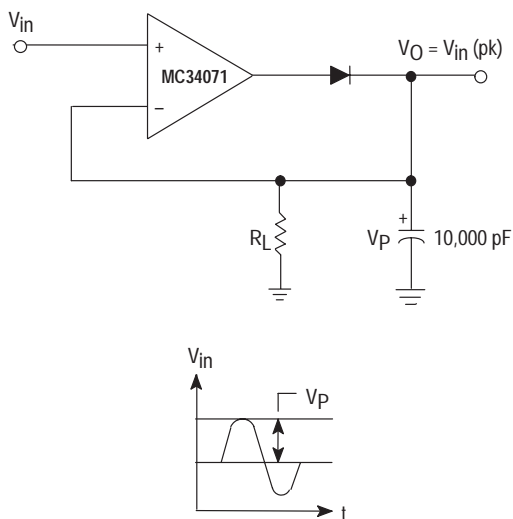
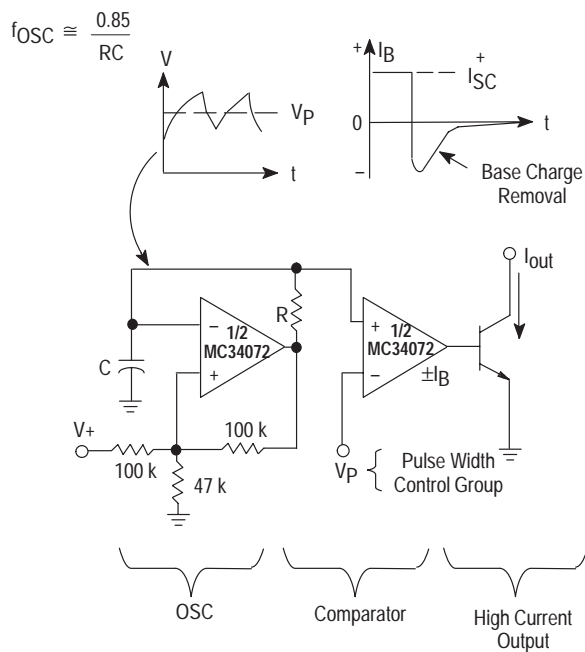


Figure 54. High Frequency Pulse Width Modulation



GENERAL ADDITIONAL APPLICATIONS INFORMATION $V_S = \pm 15.0\text{ V}$

Figure 55. Second Order Low-Pass Active Filter

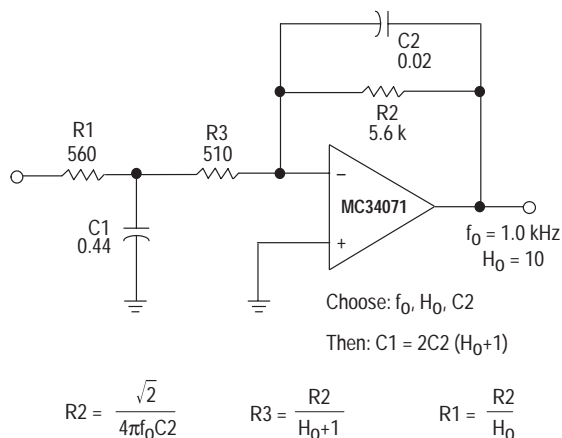


Figure 56. Second Order High-Pass Active Filter

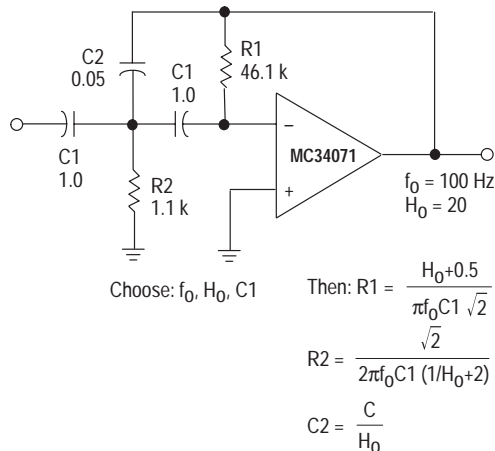


Figure 57. Fast Settling Inverter

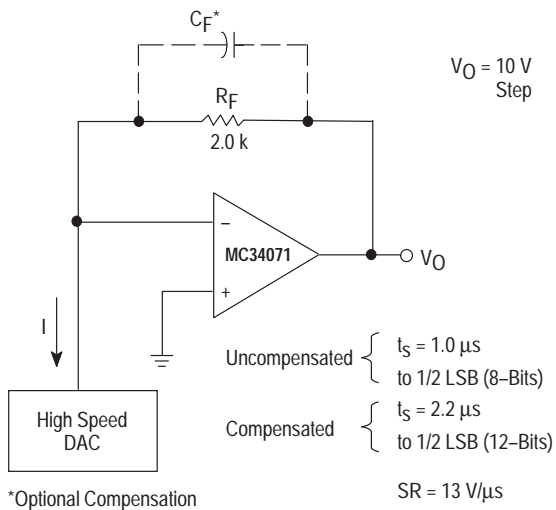


Figure 58. Basic Inverting Amplifier

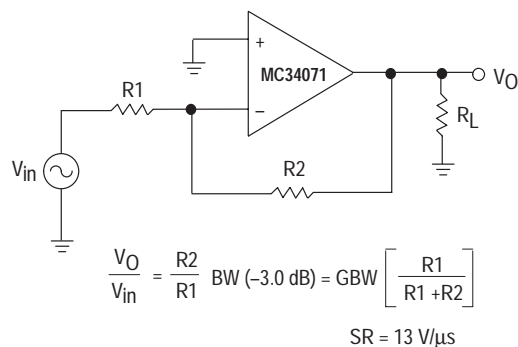


Figure 59. Basic Noninverting Amplifier

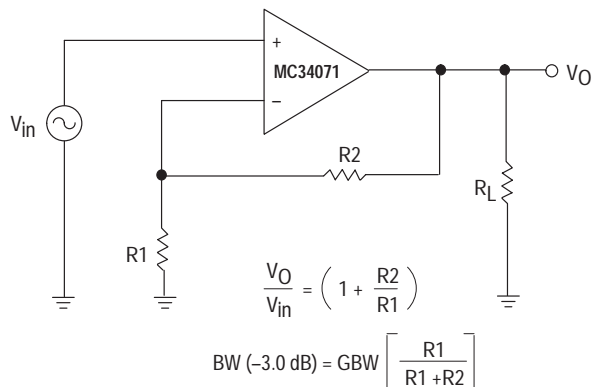
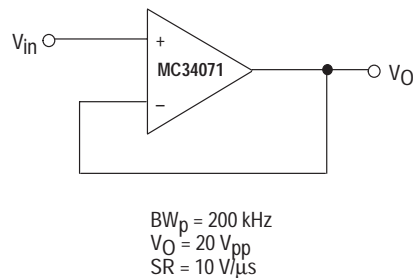


Figure 60. Unity Gain Buffer ($A_V = +1.0$)



MC34071,2,4,A MC33071,2,4,A

Figure 61. High Impedance Differential Amplifier

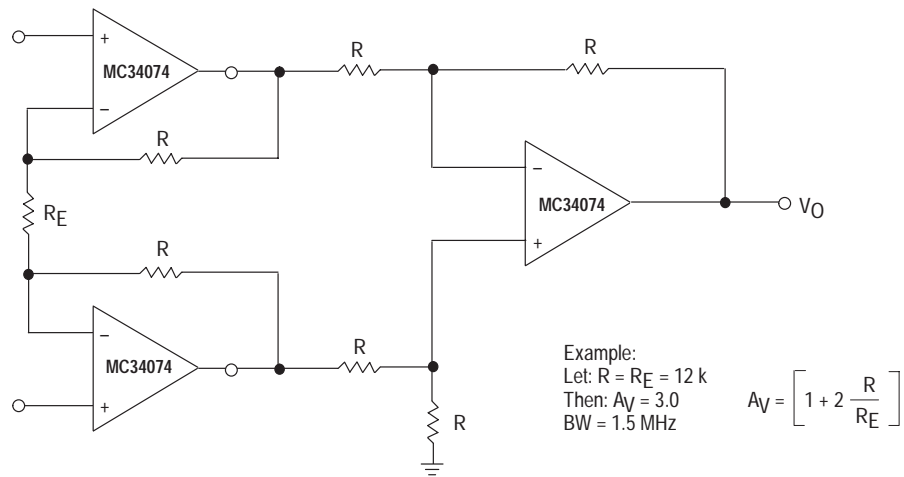
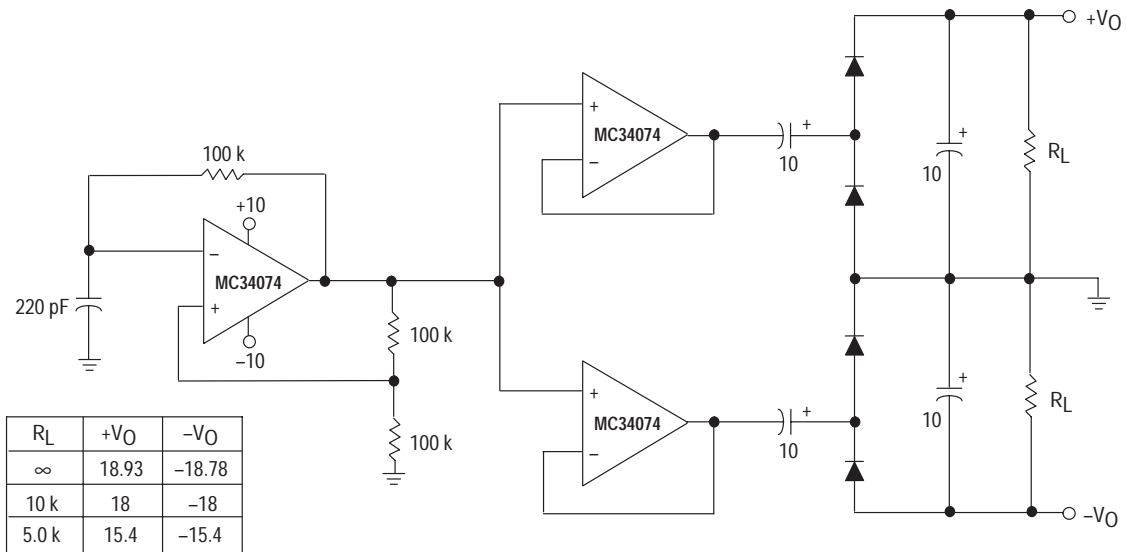


Figure 62. Dual Voltage Doubler

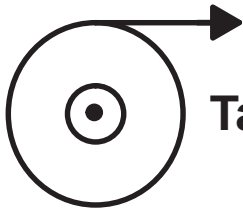


Tape and Reel Options

In Brief . . .

Motorola offers the convenience of Tape and Reel packaging for our growing family of standard integrated circuit products. Reels are available to support the requirements of both first and second generation pick-and-place equipment. The packaging fully conforms to the latest EIA-481A specification. The antistatic embossed tape provides a secure cavity, sealed with a peel-back cover tape.

	Page
Tape and Reel Configurations	12-2
Tape and Reel Information Table	12-4
Analog MPQ Table	12-5

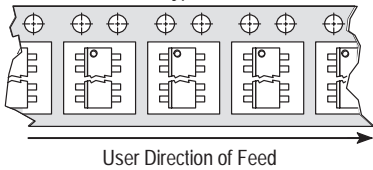


Tape and Reel Configurations

Mechanical Polarization

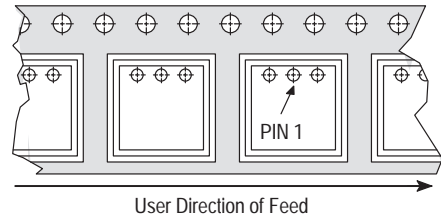
SOIC and Micro-8 DEVICES

Typical



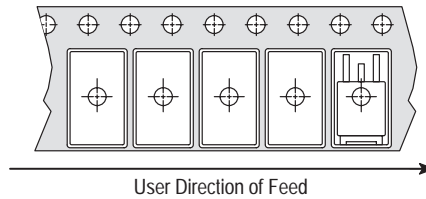
PLCC DEVICES

Typical



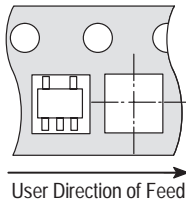
DPAK and D²PAK DEVICES

Typical



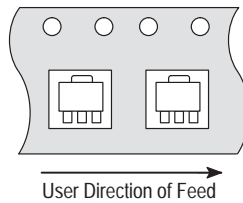
SOT-23 (5 Pin) DEVICES

Typical



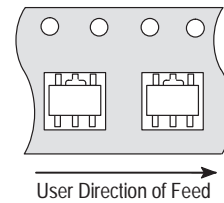
SOT-89 (3 Pin) DEVICES

Typical



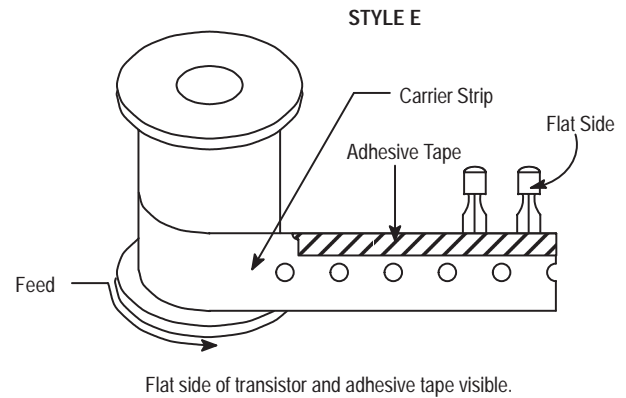
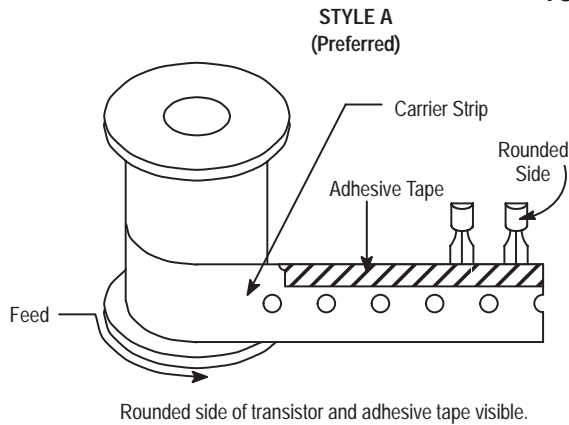
SOT-89 (5 Pin) DEVICES

Typical

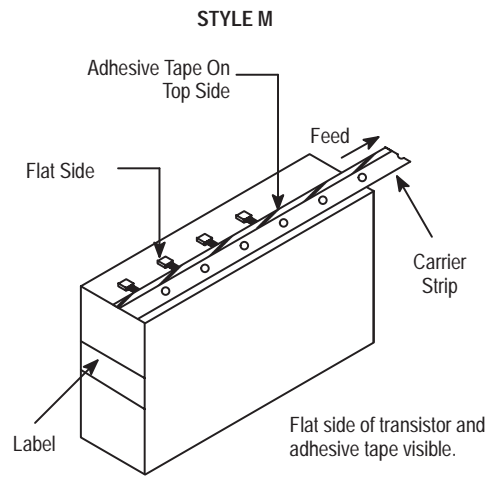
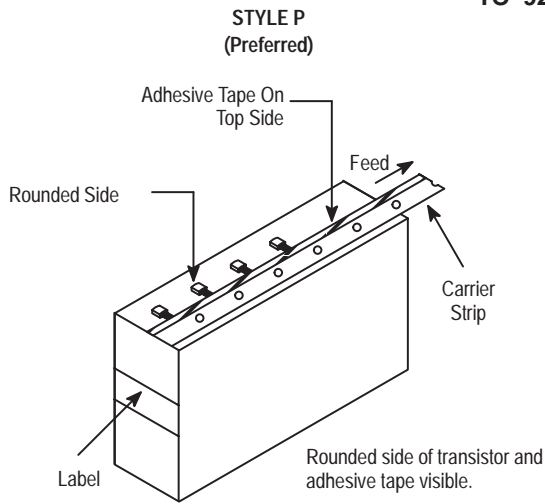


Tape and Reel Configurations (continued)

TO-92 Reel Styles



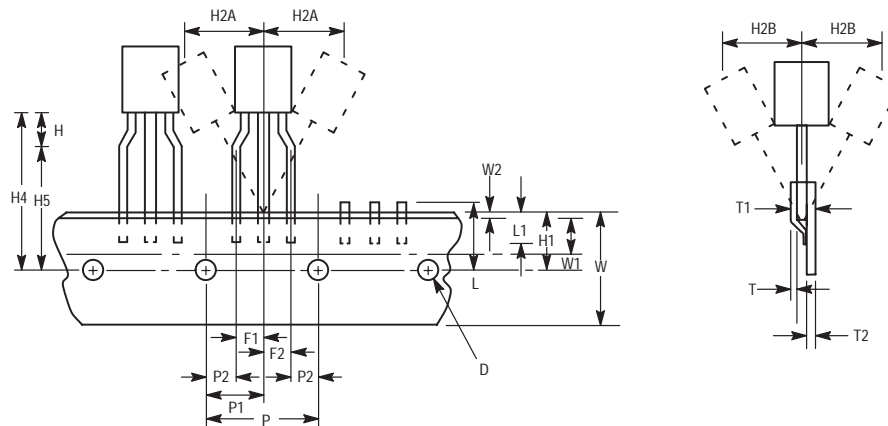
TO-92 Ammo Pack Styles



Style P ammo pack is equivalent to Styles A and B of reel pack dependent on feed orientation from box.

Style M ammo pack is equivalent to Style E of reel pack dependent on feed orientation from box.

TO-92 EIA Radial Tape in Fan Fold Box or On Reel



Tape and Reel Information Table

Package	Tape Width (mm)	Devices ⁽¹⁾ per Reel	Reel Size (inch)	Device Suffix
SO-8, SOP-8	12	2,500	13	R2
SO-14	16	2,500	13	R2
SO-16	16	2,500	13	R2
SO-16L, SO-8+8L WIDE	16	1,000	13	R2
SO-20L WIDE	24	1,000	13	R2
SO-24L WIDE	24	1,000	13	R2
SO-28L WIDE	24	1,000	13	R2
SO-28L WIDE	32	1,000	13	R3
Micro-8	12	2,500	13	R2
PLCC-20	16	1,000	13	R2
PLCC-28	24	500	13	R2
PLCC-44	32	500	13	R2
PLCC-52	32	500	13	R2
PLCC-68	44	250	13	R2
PLCC-84	44	250	13	R2
TO-226AA (TO-92) ⁽²⁾	18	2,000	13	RA, RE, RP, or RM (Ammo Pack) only
DPAK	16	2,500	13	RK
D ² PAK	24	800	13	R4
SOT-23 (5 Pin)	8	3,000	7	TR
SOT-89 (3/5 Pin)	12	1,000	7	T1

⁽¹⁾ Minimum order quantity is 1 reel. Distributors/OEM customers may break lots or reels at their option, however broken reels may not be returned.

⁽²⁾ Integrated circuits in TO-226AA packages are available in Styes A and E only, with optional "Ammo Pack" (Suffix RP or RM). The RA and RP configurations are preferred. For ordering information please contact your local Motorola Semiconductor Sales Office.

Analog MPQ Table

Tape/Reel and Ammo Pack

Package Type	Package Code	MPQ
PLCC		
Case 775	0802	1000/reel
Case 776	0804	500/reel
Case 777	0801	500/reel
SOIC		
Case 751	0095	2500/reel
Case 751A	0096	2500/reel
Case 751B	0097	2500/reel
Case 751G	2003	1000/reel
Case 751D	2005	1000/reel
Case 751E	2008	1000/reel
Case 751F	2009	1000/reel
Micro-8		
Case 846A	-	2500/reel
TO-92		
Case 29	0031	2000/reel
Case 29	0031	2000/Ammo Pack
DPAK		
Case 369A	-	2500/reel
D2PAK		
Case 936	-	800/reel
SOT-23 (5 Pin)		
Case 1212	-	3000/reel
SOT-89 (3 Pin)		
Case 1213	-	1000/reel
SOT-89 (5 Pin)		
Case 1214	-	1000/reel

Packaging Information

In Brief . . .

The packaging availability for each device type is indicated on the individual data sheets and the Selector Guide. All of the outline dimensions for the packages are given in this section.

The maximum power consumption an integrated circuit can tolerate at a given operating ambient temperature can be found from the equation:

$$P_{D(TA)} = \frac{T_{J(max)} - T_A}{R_{\theta JA(Typ)}}$$

where:

$P_{D(TA)}$ = *Power Dissipation allowable at a given operating ambient temperature. This must be greater than the sum of the products of the supply voltages and supply currents at the worst case operating condition.*

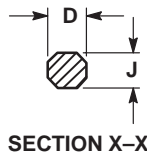
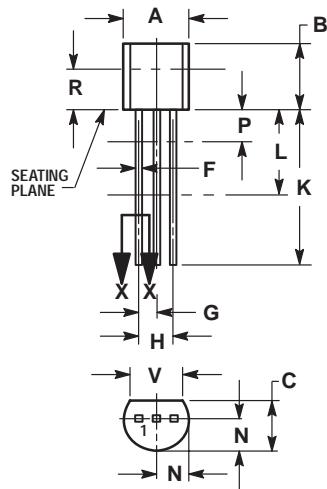
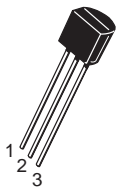
$T_{J(max)}$ = *Maximum operating Junction Temperature as listed in the Maximum Ratings Section. See individual data sheets for $T_{J(max)}$ information.*

T_A = *Maximum desired operating Ambient Temperature*

$R_{\theta JA(Typ)}$ = *Typical Thermal Resistance Junction-to-Ambient*

Case Outline Dimensions

LP, P, Z SUFFIX
CASE 29-04
 Plastic Package
 (TO-226AA/TO-92)
 ISSUE AD

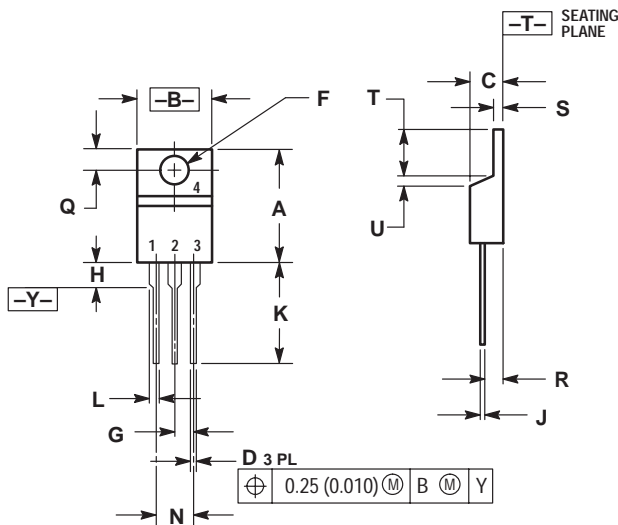
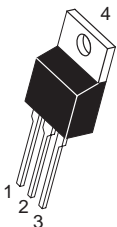


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. DIMENSION F APPLIES BETWEEN P AND L. DIMENSION D AND J APPLY BETWEEN L AND K MINIMUM. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.20
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.022	0.41	0.55
F	0.016	0.019	0.41	0.48
G	0.045	0.055	1.15	1.39
H	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	---	12.70	---
L	0.250	---	6.35	---
N	0.080	0.105	2.04	2.66
P	---	0.100	---	2.54
R	0.115	---	2.93	---
V	0.135	---	3.43	---

KC, T SUFFIX
CASE 221A-06
 Plastic Package
 ISSUE Y

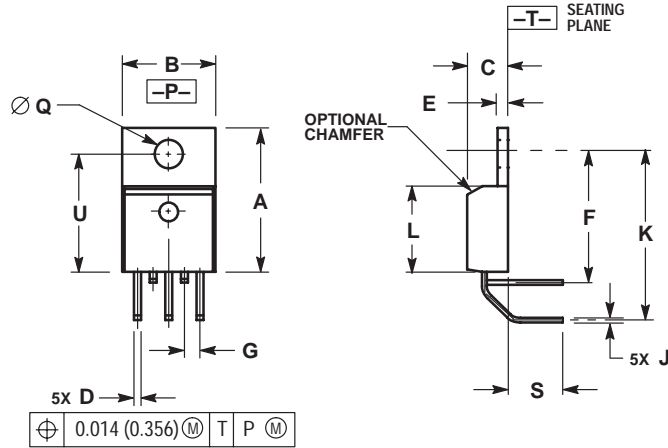
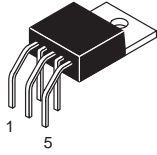


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.560	0.625	14.23	15.87
B	0.380	0.420	9.66	10.66
C	0.140	0.190	3.56	4.82
D	0.020	0.045	0.51	1.14
F	0.139	0.155	3.53	3.93
G	0.100 BSC	---	2.54 BSC	---
H	---	0.280	---	7.11
J	0.012	0.045	0.31	1.14
K	0.500	0.580	12.70	14.73
L	0.045	0.070	1.15	1.77
N	0.200 BSC	---	5.08 BSC	---
Q	0.100	0.135	2.54	3.42
R	0.080	0.115	2.04	2.92
S	0.020	0.055	0.51	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27

TH SUFFIX
CASE 314A-03
 Plastic Package
 ISSUE D

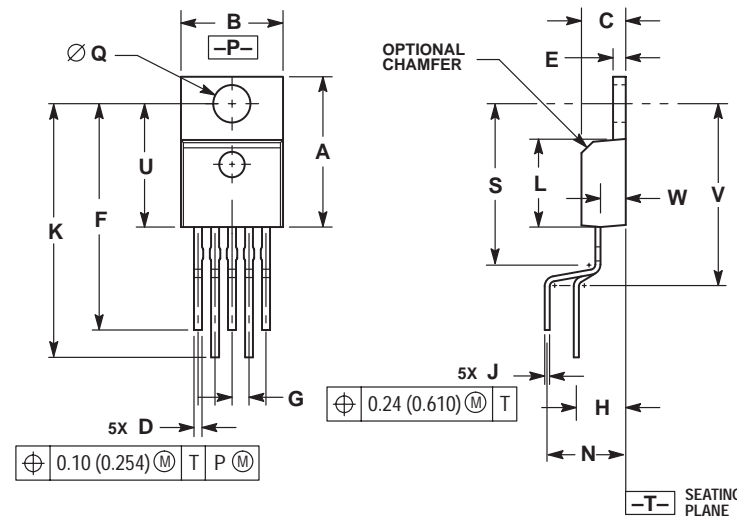
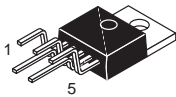


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 0.043 (1.092) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.572	0.613	14.529	15.570
B	0.390	0.415	9.906	10.541
C	0.170	0.180	4.318	4.572
D	0.025	0.038	0.635	0.965
E	0.048	0.055	1.219	1.397
F	0.570	0.585	14.478	14.859
G	0.067 BSC		1.702 BSC	
J	0.015	0.025	0.381	0.635
K	0.730	0.745	18.542	18.923
L	0.320	0.365	8.128	9.271
Q	0.140	0.153	3.556	3.886
S	0.210	0.260	5.334	6.604
U	0.468	0.505	11.888	12.827

T, TV SUFFIX
CASE 314B-05
 Plastic Package
 ISSUE J

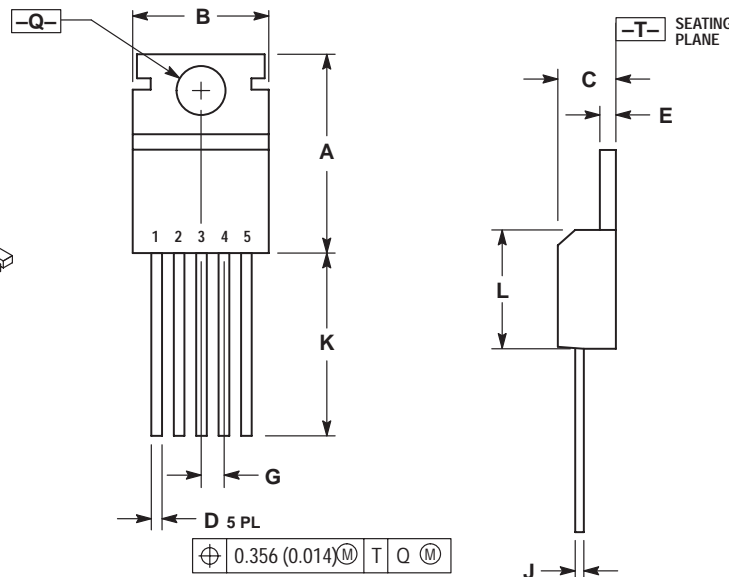
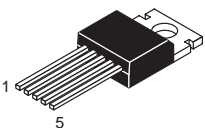


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 0.043 (1.092) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.572	0.613	14.529	15.570
B	0.390	0.415	9.906	10.541
C	0.170	0.180	4.318	4.572
D	0.025	0.038	0.635	0.965
E	0.048	0.055	1.219	1.397
F	0.850	0.935	21.590	23.749
G	0.067 BSC		1.702 BSC	
H	0.166 BSC		4.216 BSC	
J	0.015	0.025	0.381	0.635
K	0.900	1.100	22.860	27.940
L	0.320	0.365	8.128	9.271
N	0.320 BSC		8.128 BSC	
Q	0.140	0.153	3.556	3.886
S	---	0.620	---	15.748
U	0.468	0.505	11.888	12.827
V	---	0.735	---	18.669
W	0.090	0.110	2.286	2.794

T SUFFIX
CASE 314C-01
 Plastic Package
 ISSUE A

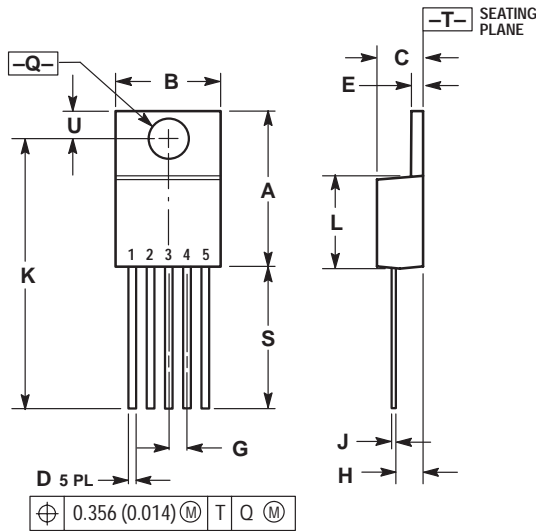
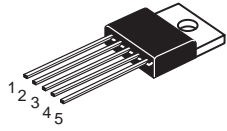


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 10.92 (0.043) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.610	0.625	15.59	15.88
B	0.380	0.420	9.65	10.67
C	0.160	0.190	4.06	4.83
D	0.020	0.040	0.51	1.02
E	0.035	0.055	0.89	1.40
G	0.067 BSC		1.702 BSC	
J	0.015	0.025	0.38	0.64
K	0.500	---	12.70	---
L	0.355	0.370	9.02	9.40
Q	0.139	0.147	3.53	3.73

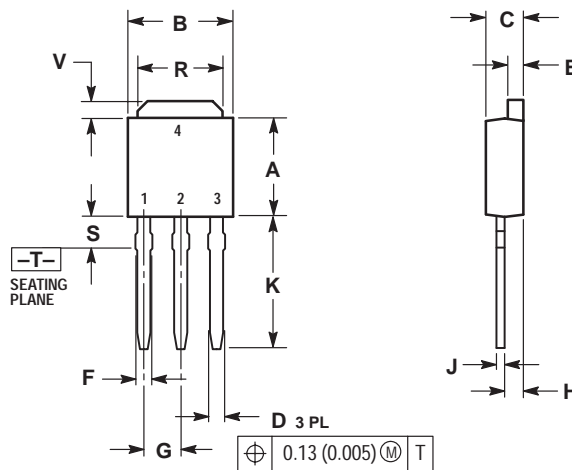
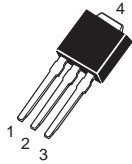
T, T1 SUFFIX
CASE 314D-03
 Plastic Package
 ISSUE D



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 10.92 (0.043) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.572	0.613	14.529	15.570
B	0.390	0.415	9.906	10.541
C	0.170	0.180	4.318	4.572
D	0.025	0.038	0.635	0.965
E	0.048	0.055	1.219	1.397
G	0.067 BSC		1.702 BSC	
H	0.087	0.112	2.210	2.845
J	0.015	0.025	0.381	0.635
K	1.020	1.065	25.908	27.051
L	0.320	0.365	8.128	9.271
Q	0.140	0.153	3.556	3.886
U	0.105	0.117	2.667	2.972
S	0.543	0.582	13.792	14.783

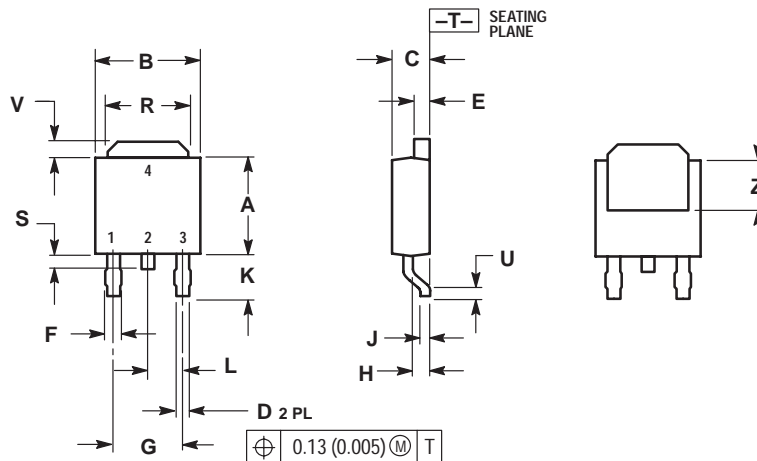
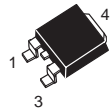
DT-1 SUFFIX
CASE 369-07
 Plastic Package (DPAK)
 ISSUE K



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.235	0.250	5.97	6.35
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.033	0.040	0.84	1.01
F	0.037	0.047	0.94	1.19
G	0.090 BSC		2.29 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.350	0.380	8.89	9.65
R	0.175	0.215	4.45	5.46
S	0.050	0.090	1.27	2.28
V	0.030	0.050	0.77	1.27

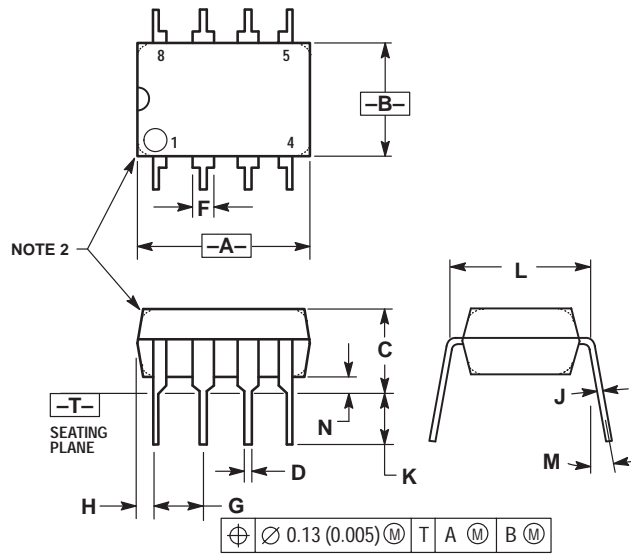
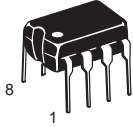
DT SUFFIX
CASE 369A-13
 Plastic Package (DPAK)
 ISSUE Y



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.235	0.250	5.97	6.35
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.033	0.040	0.84	1.01
F	0.037	0.047	0.94	1.19
G	0.180 BSC		4.58 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.102	0.114	2.60	2.89
L	0.090 BSC		2.29 BSC	
R	0.175	0.215	4.45	5.46
S	0.020	0.050	0.51	1.27
U	0.020	---	0.51	---
V	0.030	0.050	0.77	1.27
Z	0.138	---	3.51	---

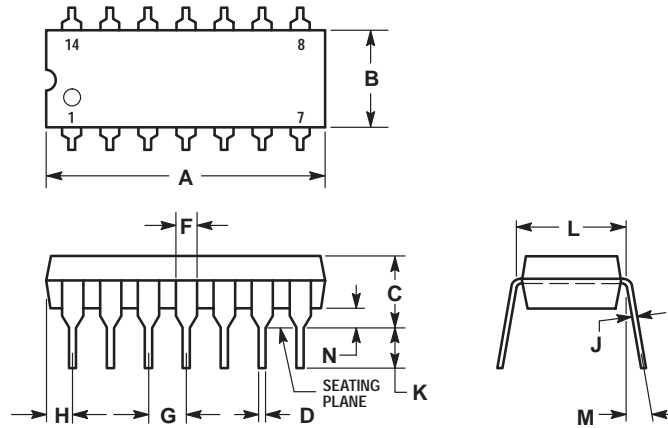
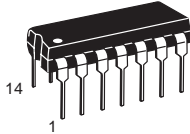
DP1, N, P, P1 SUFFIX
CASE 626-05
 Plastic Package
 ISSUE K



- NOTES:
1. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 2. PACKAGE CONTOUR OPTIONAL (ROUND OR SQUARE CORNERS).
 3. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.40	10.16	0.370	0.400
B	6.10	6.60	0.240	0.260
C	3.94	4.45	0.155	0.175
D	0.38	0.51	0.015	0.020
F	1.02	1.78	0.040	0.070
G	2.54 BSC		0.100 BSC	
H	0.76	1.27	0.030	0.050
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	— 10°		— 10°	
N	0.76	1.01	0.030	0.040

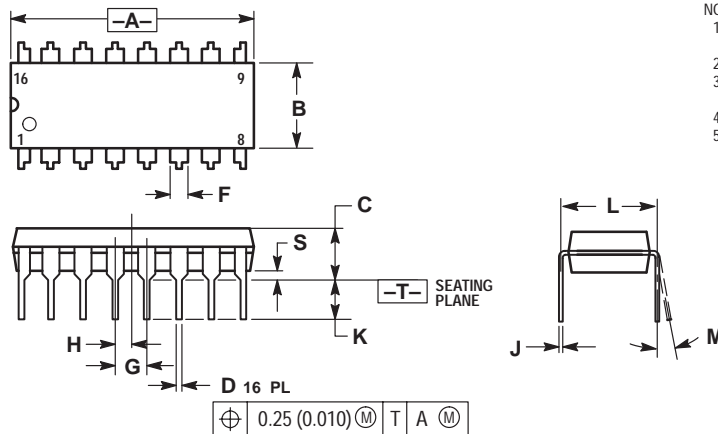
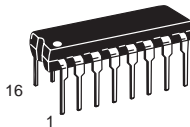
N, P, N-14, P2 SUFFIX
CASE 646-06
 Plastic Package
 ISSUE L



- NOTES:
1. LEADS WITHIN 0.13 (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
 2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 4. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.715	0.770	18.16	19.56
B	0.240	0.260	6.10	6.60
C	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100 BSC		2.54 BSC	
H	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.300 BSC		7.62 BSC	
M	0° 10°		0° 10°	
N	0.015	0.039	0.39	1.01

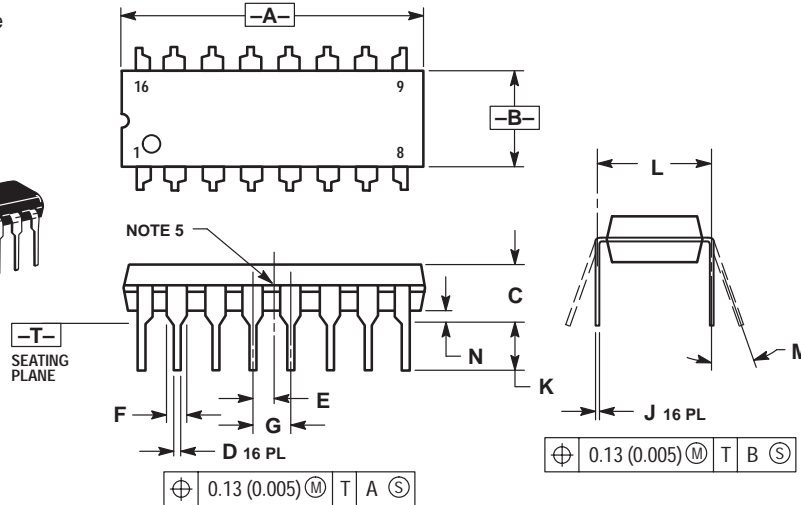
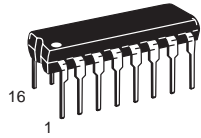
DP2, N, P, PC SUFFIX
CASE 648-08
 Plastic Package
 ISSUE R



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0° 10°		0° 10°	
S	0.020	0.040	0.51	1.01

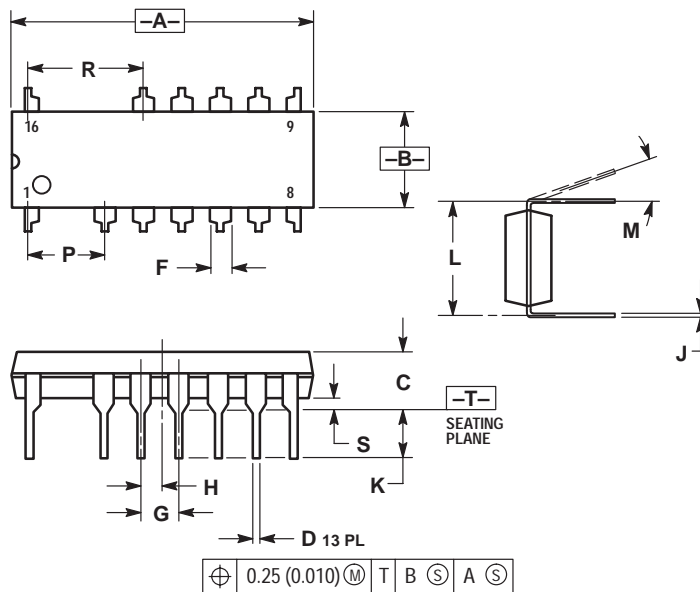
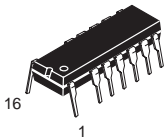
B, P, P2, V SUFFIX
CASE 648C-03
 Plastic Package
 (DIP-16)
 ISSUE C



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. INTERNAL LEAD CONNECTION BETWEEN 4 AND 5, 12 AND 13.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.840	18.80	21.34
B	0.240	0.260	6.10	6.60
C	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
E	0.050 BSC			
F	0.040	0.70	1.02	1.78
G	0.100 BSC			
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.300 BSC			
M	0°	10°	0°	10°
N	0.015	0.040	0.39	1.01

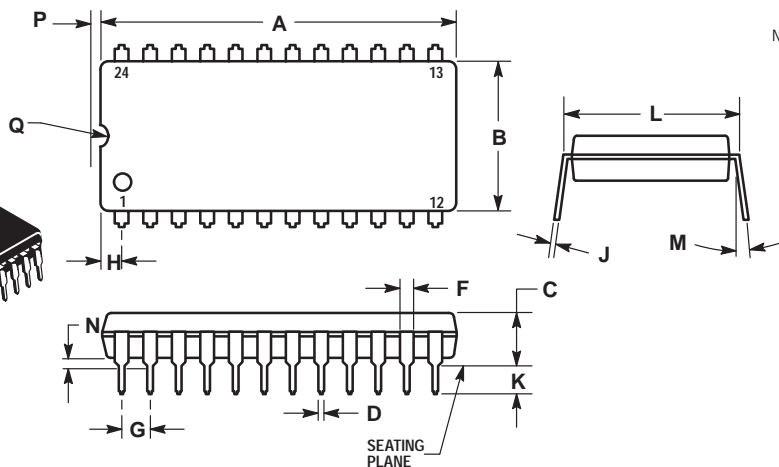
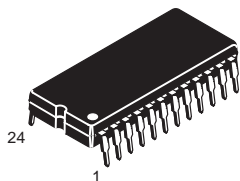
P SUFFIX
CASE 648E-01
 Plastic Package
 (DIP-16)
 ISSUE O



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION A AND B DOES NOT INCLUDE MOLD PROTRUSION.
 5. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.25 (0.010).
 6. ROUNDED CORNER OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.760	18.80	19.30
B	0.245	0.260	6.23	6.60
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.050	0.070	1.27	1.77
G	0.100 BSC			
H	0.050 BSC			
J	0.008	0.015	0.21	0.38
K	0.120	0.140	3.05	3.55
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
P	0.200 BSC			
R	0.300 BSC			
S	0.015	0.035	0.39	0.88

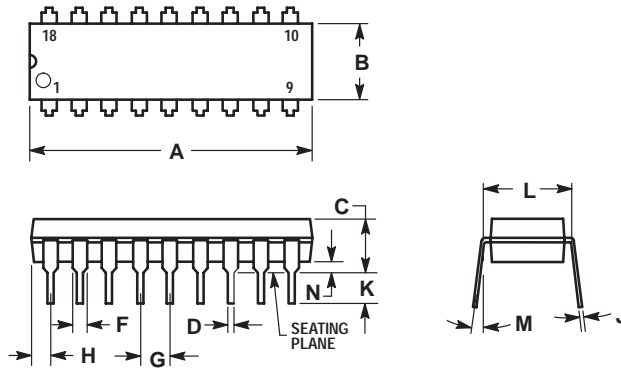
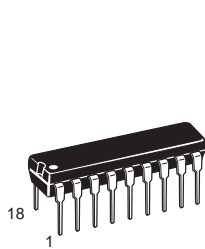
P SUFFIX
CASE 649-03
 Plastic Package
 ISSUE D



- NOTES:
1. LEADS WITHIN 0.13 (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
 2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	31.50	32.13	1.240	1.265
B	13.21	13.72	0.520	0.540
C	4.70	5.21	0.185	0.205
D	0.38	0.51	0.015	0.020
F	1.02	1.52	0.040	0.060
G	2.54 BSC			
H	1.65	2.16	0.065	0.085
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	14.99	15.49	0.590	0.610
M	---	10	---	10°
N	0.51	1.02	0.020	0.040
P	0.13	0.38	0.005	0.015
Q	0.51	0.76	0.020	0.030

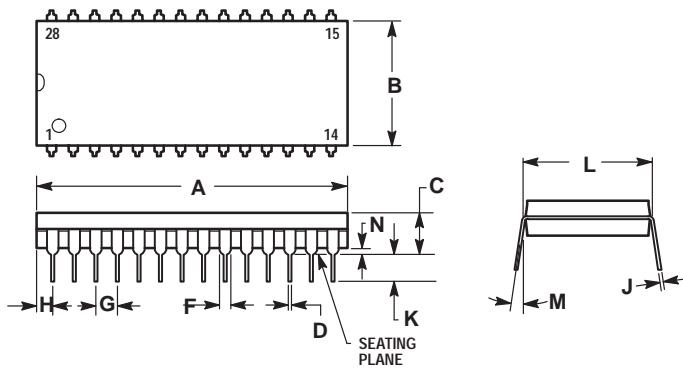
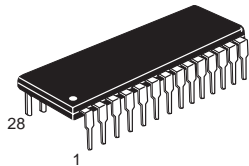
A, B, N, P SUFFIX
CASE 707-02
 Plastic Package
 ISSUE C



- NOTES:
1. POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25 (0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.
 2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	22.22	23.24	0.875	0.915
B	6.10	6.60	0.240	0.260
C	3.56	4.57	0.140	0.180
D	0.36	0.56	0.014	0.022
F	1.27	1.78	0.050	0.070
G	2.54 BSC		0.100 BSC	
H	1.02	1.52	0.040	0.060
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

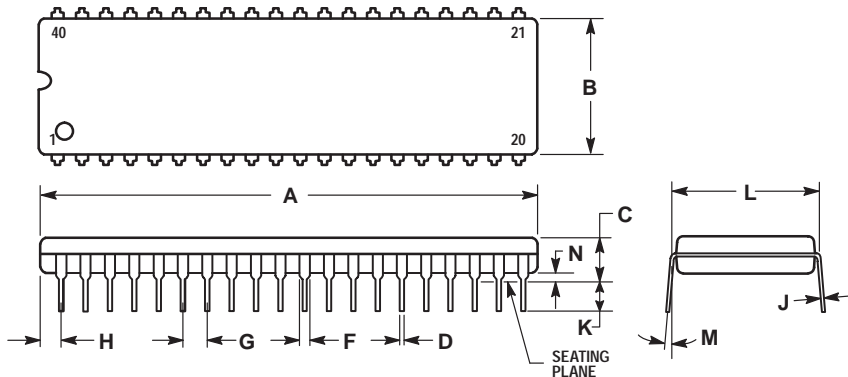
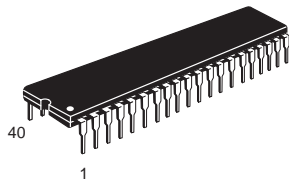
P SUFFIX
CASE 710-02
 Plastic Package
 ISSUE B



- NOTES:
1. POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25 (0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.
 2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	36.45	37.21	1.435	1.465
B	13.72	14.22	0.540	0.560
C	3.94	5.08	0.155	0.200
D	0.36	0.56	0.014	0.022
F	1.02	1.52	0.040	0.060
G	2.54 BSC		0.100 BSC	
H	1.65	2.16	0.065	0.085
J	0.20	0.38	0.008	0.015
K	2.92	3.43	0.115	0.135
L	15.24 BSC		0.600 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

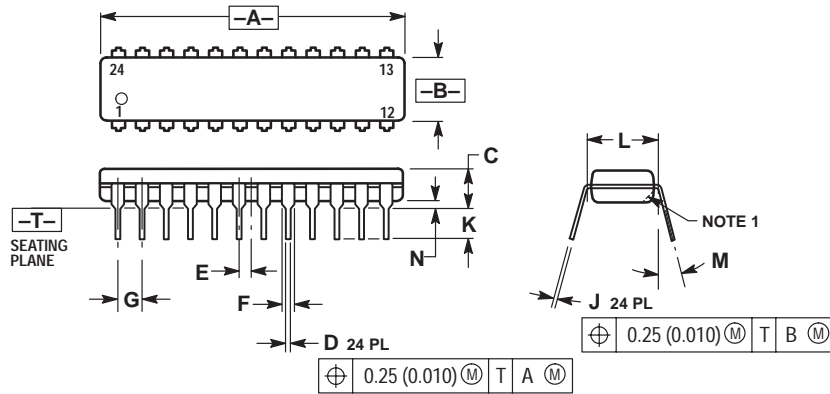
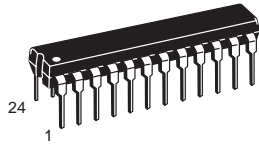
P SUFFIX
CASE 711-03
 Plastic Package
 ISSUE C



- NOTES:
1. POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25 (0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.
 2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	51.69	52.45	2.035	2.065
B	13.72	14.22	0.540	0.560
C	3.94	5.08	0.155	0.200
D	0.36	0.56	0.014	0.022
F	1.02	1.52	0.040	0.060
G	2.54 BSC		0.100 BSC	
H	1.65	2.16	0.065	0.085
J	0.20	0.38	0.008	0.015
K	2.92	3.43	0.115	0.135
L	15.24 BSC		0.600 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

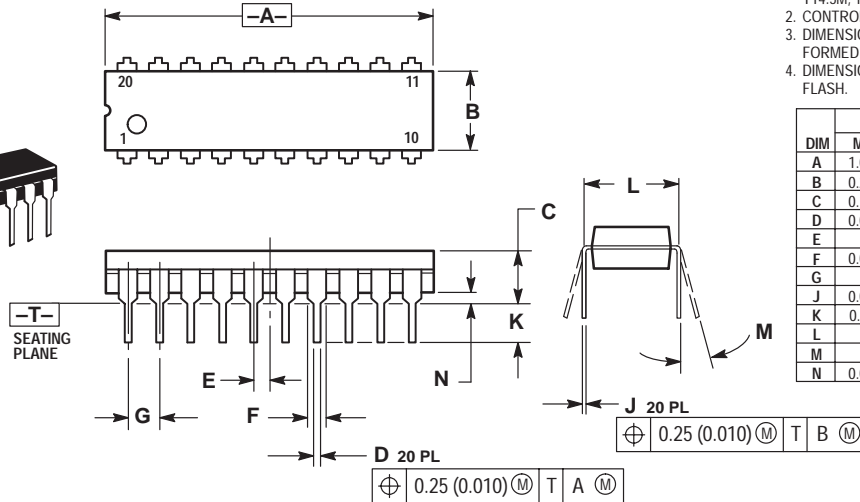
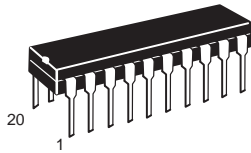
F, P, P-3 SUFFIX
CASE 724-03
 Plastic Package
 (NDIP-24)
 ISSUE D



- NOTES:
1. CHAMFERED CONTOUR OPTIONAL.
 2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 3. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 4. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.230	1.265	31.25	32.13
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.020	0.38	0.51
E	0.050 BSC		1.27 BSC	
F	0.040	0.060	1.02	1.52
G	0.100 BSC		2.54 BSC	
J	0.007	0.012	0.18	0.30
K	0.110	0.140	2.80	3.55
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

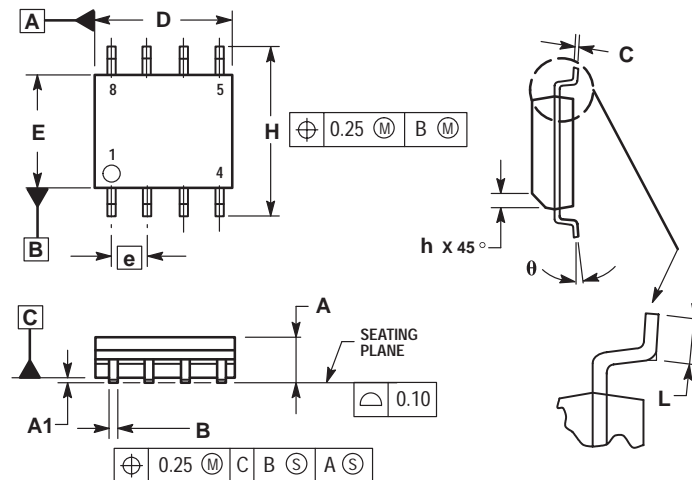
H, P, DP SUFFIX
CASE 738-03
 Plastic Package
 ISSUE E



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.010	1.070	25.66	27.17
B	0.240	0.260	6.10	6.60
C	0.150	0.180	3.81	4.57
D	0.015	0.022	0.39	0.55
E	0.050 BSC		1.27 BSC	
F	0.050	0.070	1.27	1.77
G	0.100 BSC		2.54 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.140	2.80	3.55
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

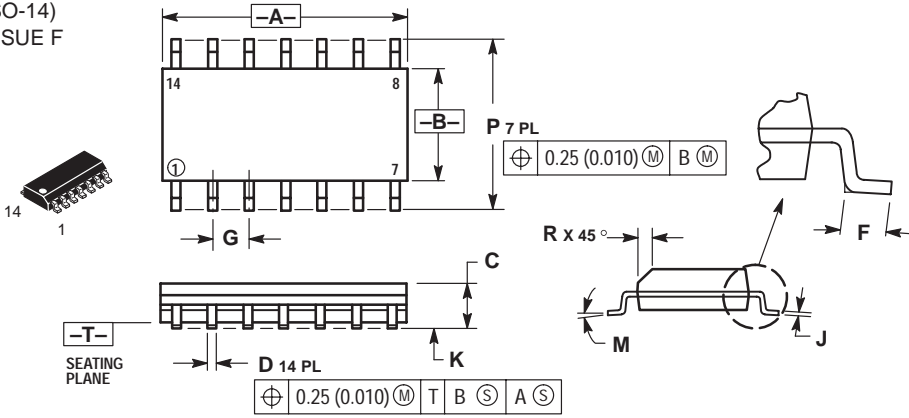
D, D1, D2 SUFFIX
CASE 751-05
 Plastic Package
 (SO-8, SOP-8)
 ISSUE R



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. DIMENSIONS ARE IN MILLIMETERS.
 3. DIMENSION D AND E DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
 5. DIMENSION B DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 TOTAL IN EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS	
	MIN	MAX
A	1.35	1.75
A1	0.10	0.25
B	0.35	0.49
C	0.18	0.25
D	4.80	5.00
E	3.80	4.00
e	1.27 BSC	
H	5.80	6.20
h	0.25	0.50
L	0.40	1.25
θ	0°	7°

D SUFFIX
CASE 751A-03
 Plastic Package
 (SO-14)
 ISSUE F

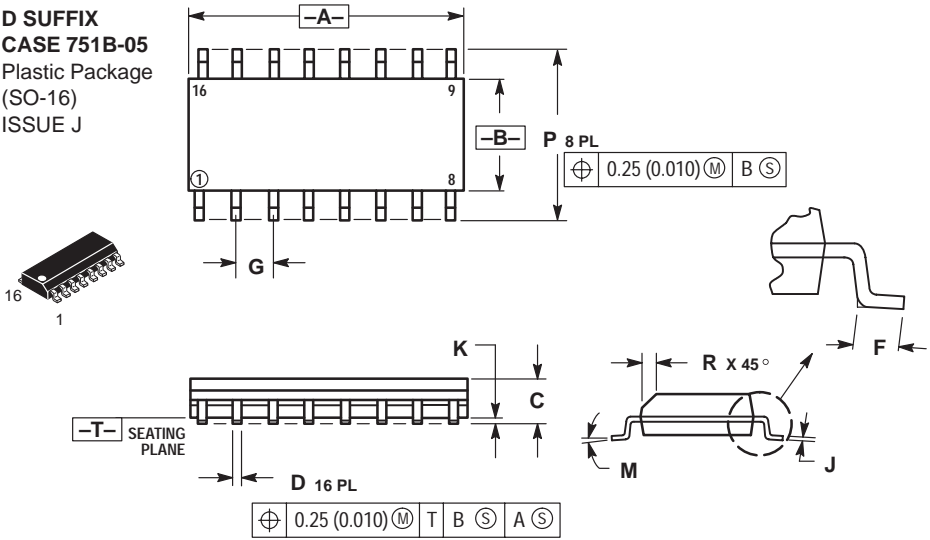


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	8.55	8.75	0.337	0.344
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

D SUFFIX
CASE 751B-05
 Plastic Package
 (SO-16)
 ISSUE J

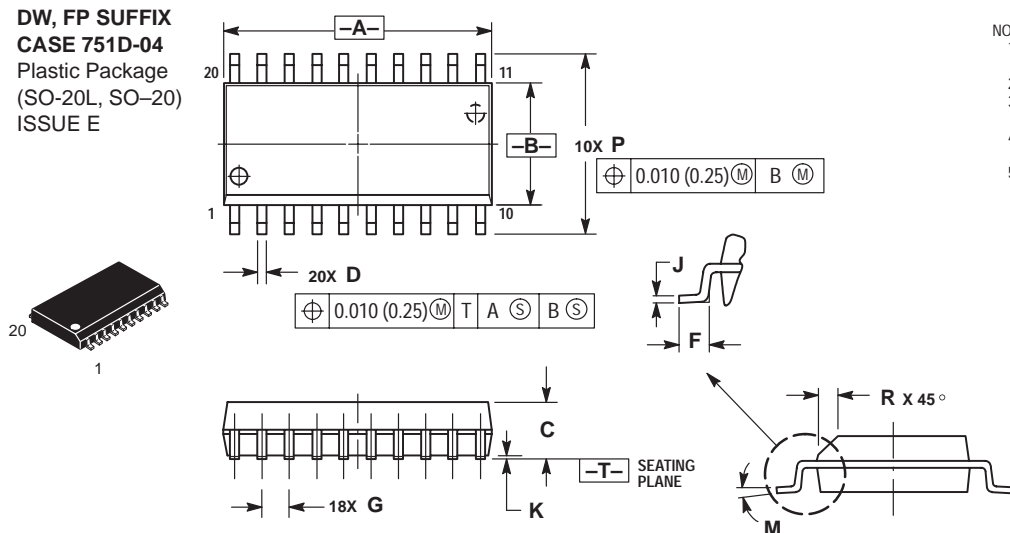


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

DW, FP SUFFIX
CASE 751D-04
 Plastic Package
 (SO-20L, SO-20)
 ISSUE E

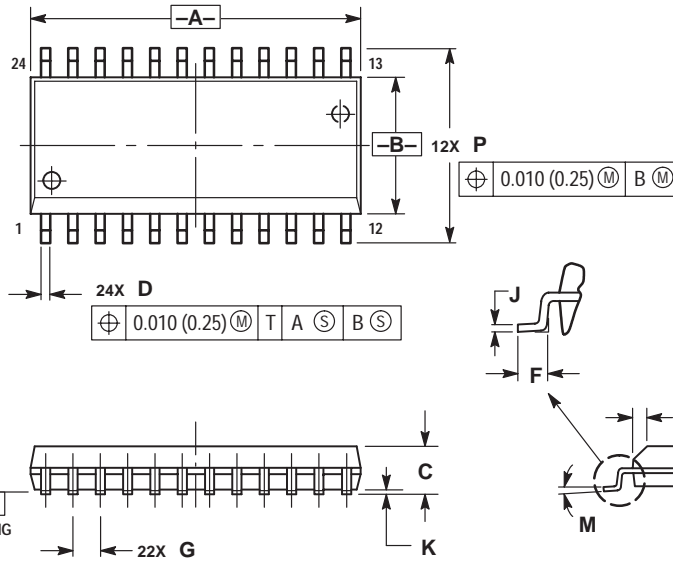
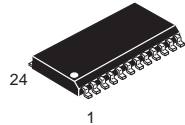


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.150 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	12.65	12.95	0.499	0.510
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

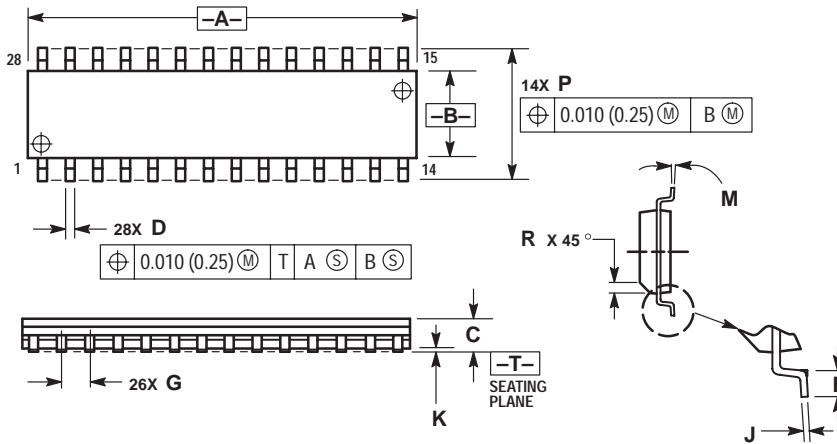
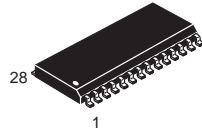
DW SUFFIX
CASE 751E-04
 Plastic Package
 (SO-24L,
 SOP (16+4+4)L)
 ISSUE E



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	15.25	15.54	0.601	0.612
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.41	0.90	0.016	0.035
G	1.27 BSC		0.050 BSC	
J	0.23	0.32	0.009	0.013
K	0.13	0.29	0.005	0.011
M	0°	8°	0°	8°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

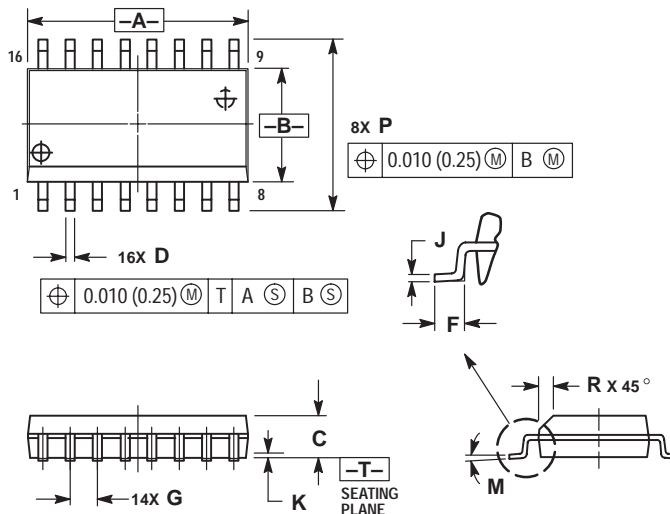
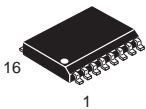
DW SUFFIX
CASE 751F-04
 Plastic Package
 (SO-28L, SOIC-28)
 ISSUE E



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	17.80	18.05	0.701	0.711
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.41	0.90	0.016	0.035
G	1.27 BSC		0.050 BSC	
J	0.23	0.32	0.009	0.013
K	0.13	0.29	0.005	0.011
M	0°	8°	0°	8°
P	10.01	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

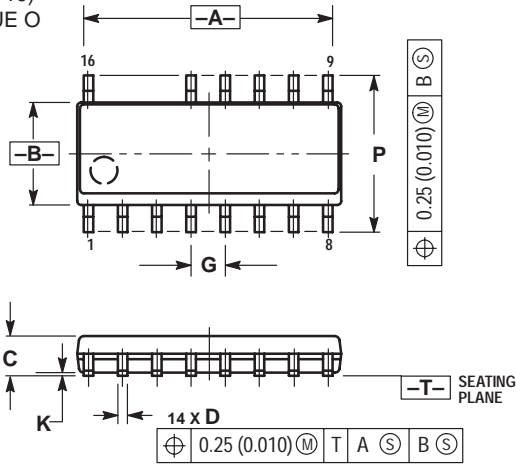
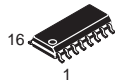
DW SUFFIX
CASE 751G-02
 Plastic Package
 (SO-16L, SOP-16L,
 SOP-8+8L)
 ISSUE A



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	10.15	10.45	0.400	0.411
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

D SUFFIX
CASE 751K-01
 Plastic Package
 (SO-16)
 ISSUE O

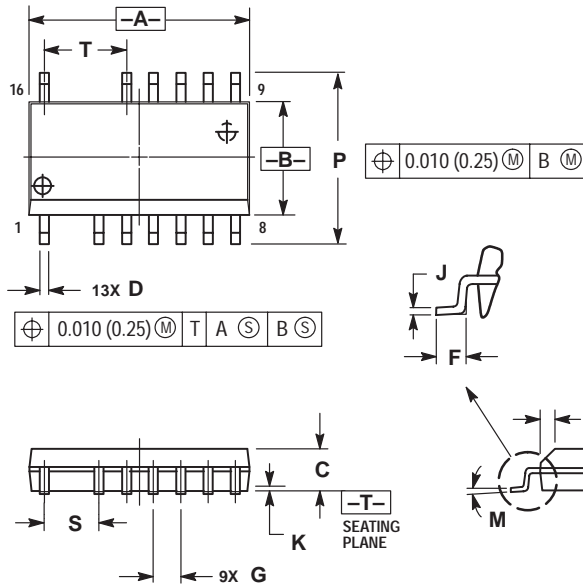
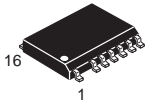


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.368	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

DW SUFFIX
CASE 751N-01
 Plastic Package
 (SOP-16L)
 ISSUE O

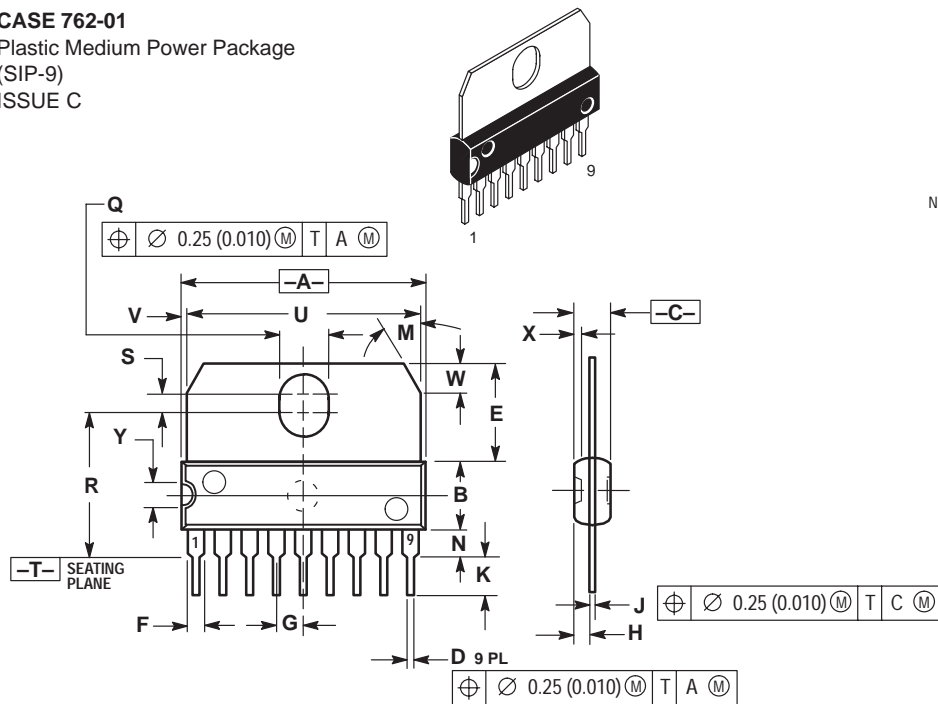


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	10.15	10.45	0.400	0.411
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029
S	2.54 BSC		0.100 BSC	
T	3.81 BSC		0.150 BSC	

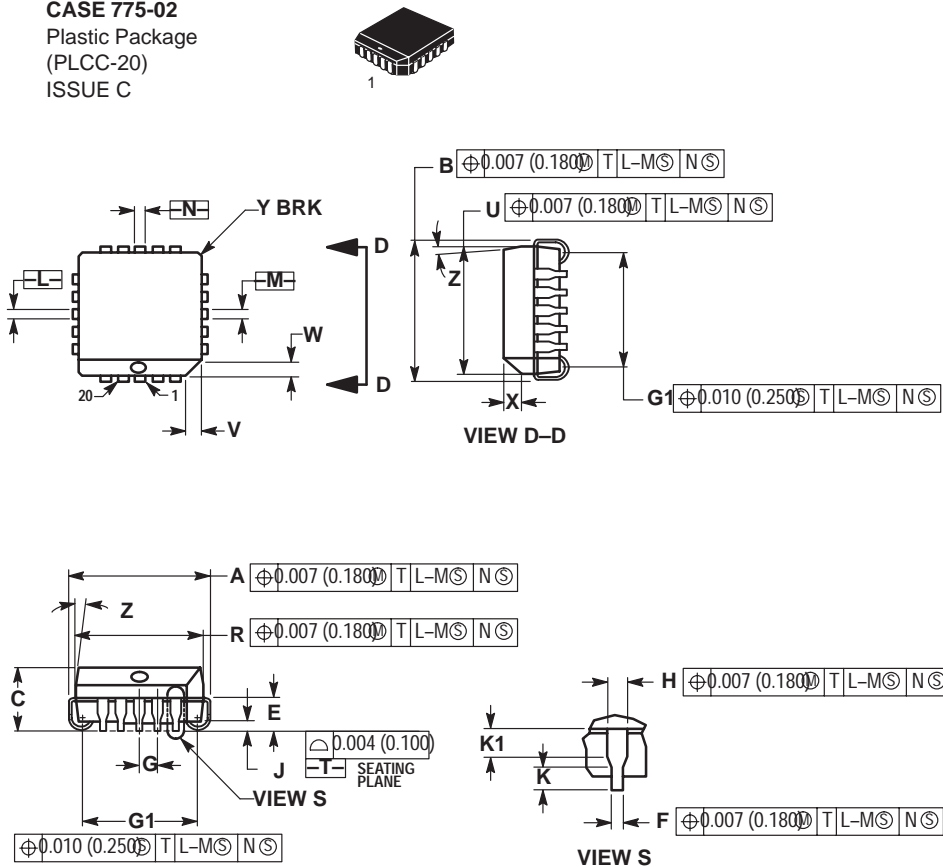
CASE 762-01
 Plastic Medium Power Package
 (SIP-9)
 ISSUE C



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	22.40	23.00	0.873	0.897
B	6.40	6.60	0.252	0.260
C	3.45	3.65	0.135	1.143
D	0.40	0.55	0.015	0.021
E	9.35	9.60	0.368	0.377
F	1.40	1.60	0.055	0.062
G	2.54 BSC		0.100 BSC	
H	1.51	1.71	0.059	0.067
J	0.360	0.400	0.014	0.015
K	3.95	4.20	0.155	0.165
M	30° BSC		30° BSC	
N	2.50	2.70	0.099	0.106
Q	3.15	3.45	0.124	0.135
R	13.60	13.90	0.535	0.547
S	1.65	1.95	0.064	0.076
U	22.00	22.20	0.866	0.874
V	0.55	0.75	0.021	0.029
W	2.89 BSC		0.113 BSC	
X	0.65	0.75	0.025	0.029
Y	2.70	2.80	0.106	0.110

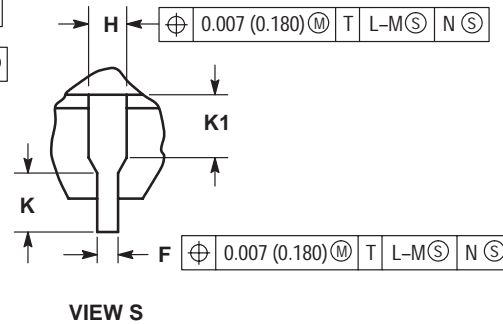
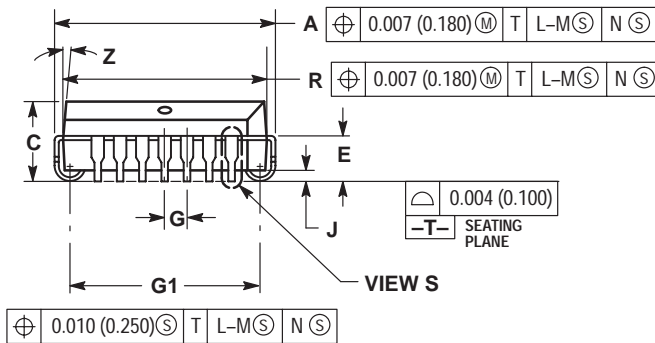
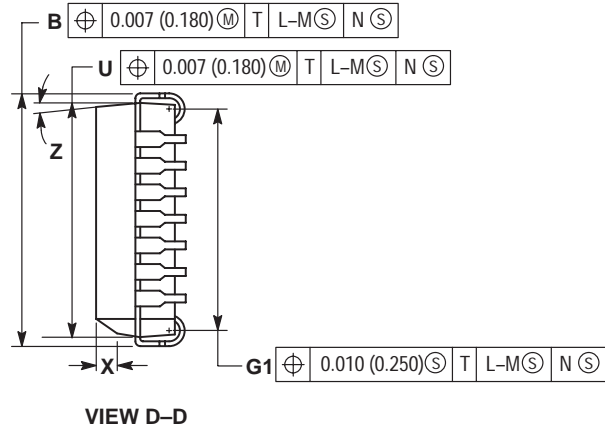
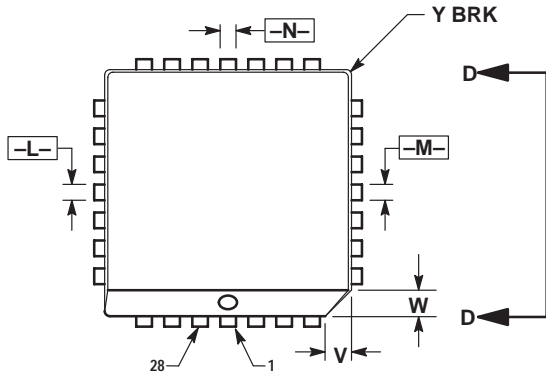
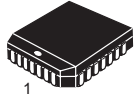
FN SUFFIX
CASE 775-02
 Plastic Package
 (PLCC-20)
 ISSUE C



- NOTES:
 1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
 4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 5. CONTROLLING DIMENSION: INCH.
 6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
 7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.385	0.395	9.78	10.03
B	0.385	0.395	9.78	10.03
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2°	10°	---	10°
G1	0.310	0.330	7.88	8.38
K1	0.040	---	1.02	---

FN SUFFIX
CASE 776-02
 Plastic Package
 (PLCC-28)
 ISSUE D

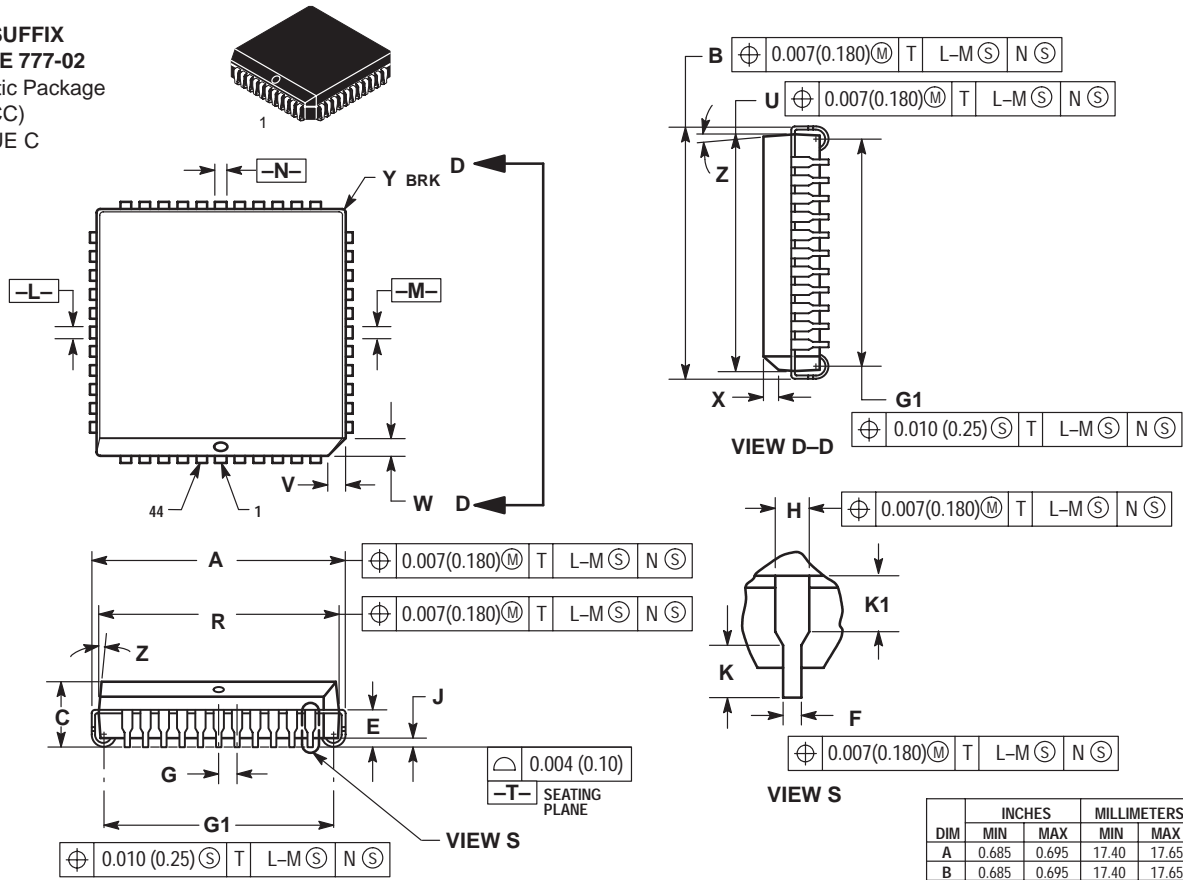


NOTES:

- DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
- DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
- DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.485	0.495	12.32	12.57
B	0.485	0.495	12.32	12.57
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.450	0.456	11.43	11.58
U	0.450	0.456	11.43	11.58
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2°	10°	2°	10°
G1	0.410	0.430	10.42	10.92
K1	0.040	---	1.02	---

FN SUFFIX
CASE 777-02
 Plastic Package
 (PLCC)
 ISSUE C

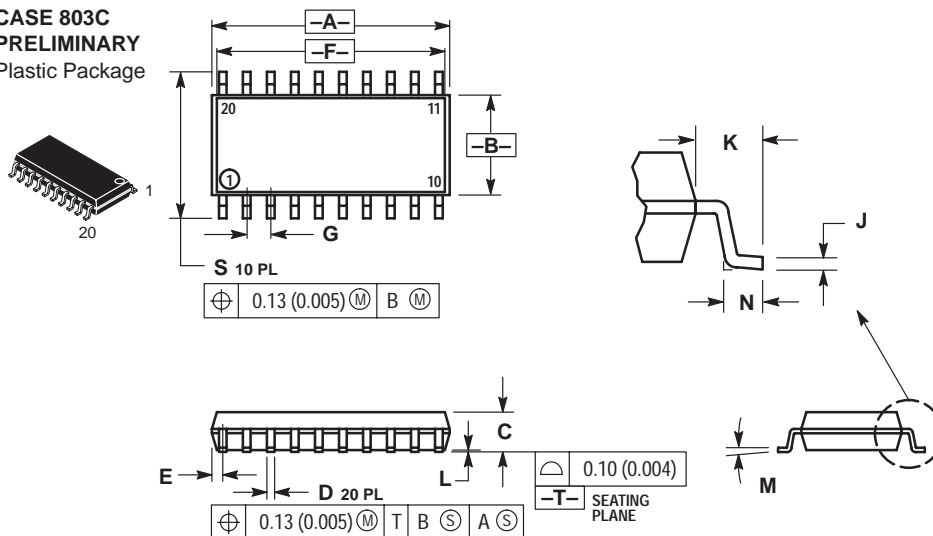


- NOTES:
- DATUMS -L-, -M-, AND -N- ARE DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
 - DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
 - DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.25) PER SIDE.
 - DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 - CONTROLLING DIMENSION: INCH.

- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.685	0.695	17.40	17.65
B	0.685	0.695	17.40	17.65
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.650	0.656	16.51	16.66
U	0.650	0.656	16.51	16.66
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2°	10°	2°	10°
G1	0.610	0.630	15.50	16.00
K1	0.040	---	1.02	---

M SUFFIX
CASE 803C
 PRELIMINARY
 Plastic Package

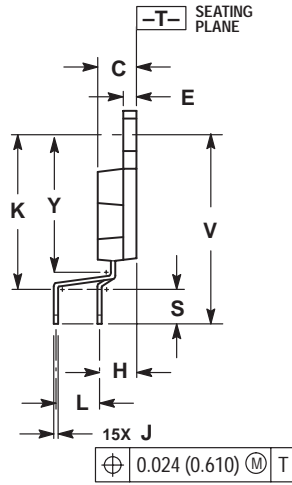
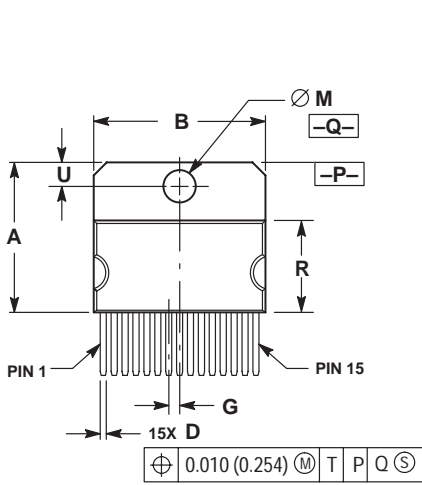
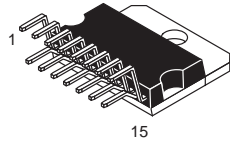


- NOTES:
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 - CONTROLLING DIMENSION: MILLIMETER.
 - DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 - MAXIMUM MOLD PROTRUSION 0.15 (0.008) PER SIDE.
 - DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.006) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	12.35	12.80	0.486	0.504
B	5.10	5.45	0.201	0.215
C	1.95	2.05	0.077	0.081
D	0.35	0.50	0.014	0.020
E	---	0.81	---	0.032
F	12.40*		0.488*	
G	1.15	1.39	0.045	0.055
H	0.59	0.81	0.023	0.032
J	0.18	0.27	0.007	0.011
K	1.10	1.50	0.043	0.059
L	0.05	0.20	0.001	0.008
M	0°	10°	0°	10°
N	0.50	0.85	0.020	0.033
S	7.40	8.20	0.291	0.323

*APPROXIMATE

TV SUFFIX
CASE 821C-04
 Plastic Package
 (15-Pin ZIP)
 ISSUE D

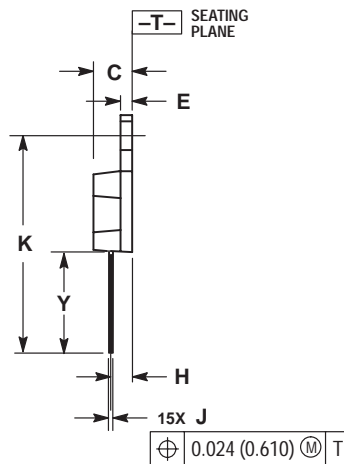
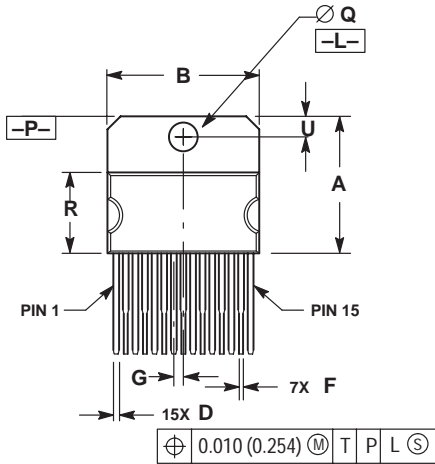
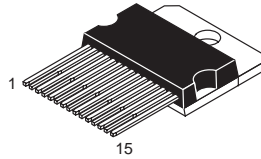


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION R DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
5. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.010 (0.250).
6. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.003 (0.076) TOTAL IN EXCESS OF THE D DIMENSION, AT MAXIMUM MATERIAL CONDITION.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.684	0.694	17.374	17.627
B	0.784	0.792	19.914	20.116
C	0.173	0.181	4.395	4.597
D	0.024	0.031	0.610	0.787
E	0.058	0.062	1.473	1.574
G	0.050 BSC		1.270 BSC	
H	0.169 BSC		4.293 BSC	
J	0.018	0.024	0.458	0.609
K	0.700	0.710	17.780	18.034
L	0.200 BSC		5.080 BSC	
M	0.148	0.151	3.760	3.835
R	0.416	0.426	10.567	10.820
S	0.157	0.167	3.988	4.242
U	0.105	0.115	2.667	2.921
V	0.868 REF		22.047 REF	
Y	0.625	0.639	15.875	16.231

T SUFFIX
CASE 821D-03
 Plastic Package
 ISSUE C

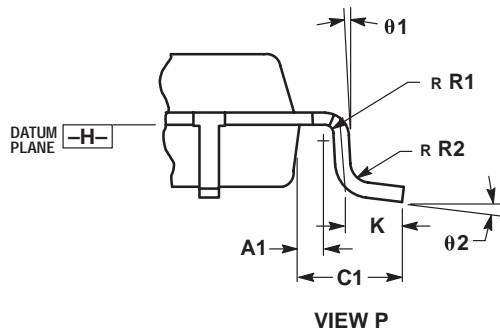
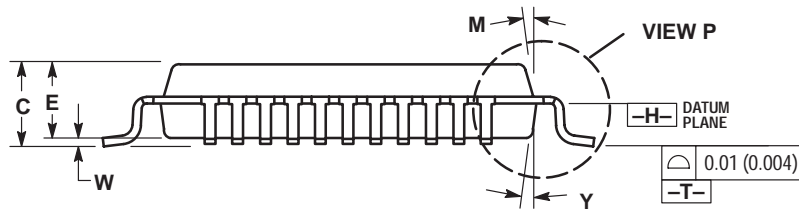
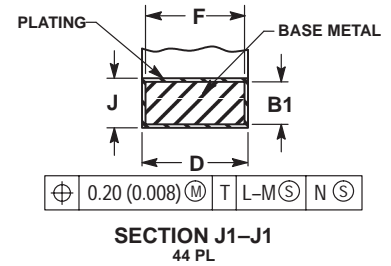
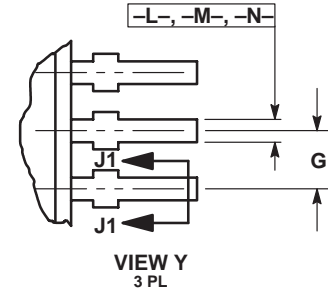
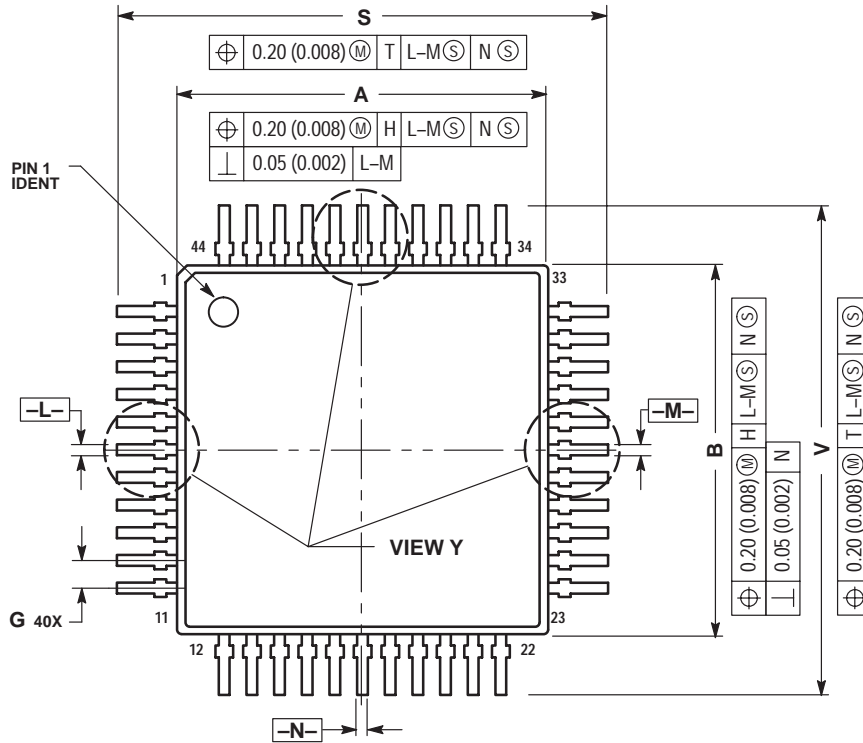
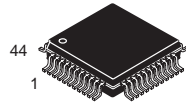


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION R DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
5. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.010 (0.250).
6. DELETED
7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.003 (0.076) TOTAL IN EXCESS OF THE D DIMENSION, AT MAXIMUM MATERIAL CONDITION.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.681	0.694	17.298	17.627
B	0.784	0.792	19.914	20.116
C	0.173	0.181	4.395	4.597
D	0.024	0.031	0.610	0.787
E	0.058	0.062	1.473	1.574
F	0.016	0.023	0.407	0.584
G	0.050 BSC		1.270 BSC	
H	0.110 BSC		2.794 BSC	
J	0.018	0.024	0.458	0.609
K	1.078	1.086	27.382	27.584
Q	0.148	0.151	3.760	3.835
R	0.416	0.426	10.567	10.820
U	0.110 BSC		2.794 BSC	
Y	0.503 REF		12.776 REF	

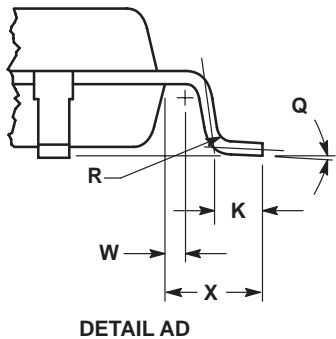
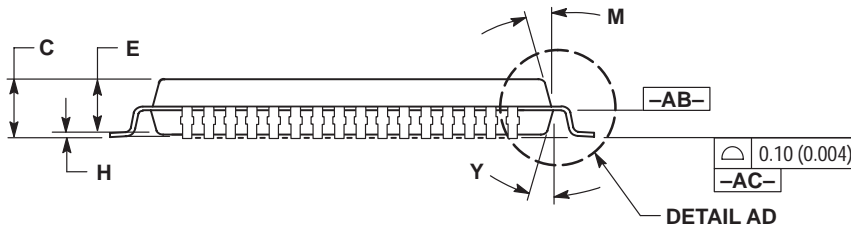
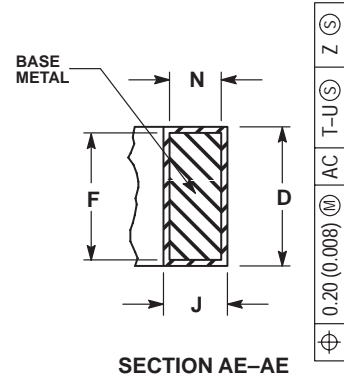
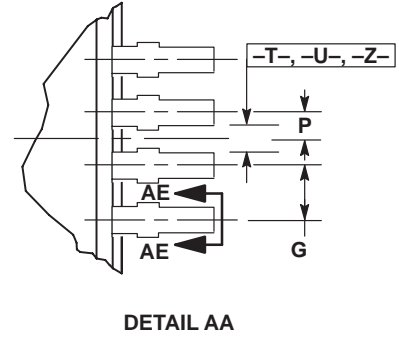
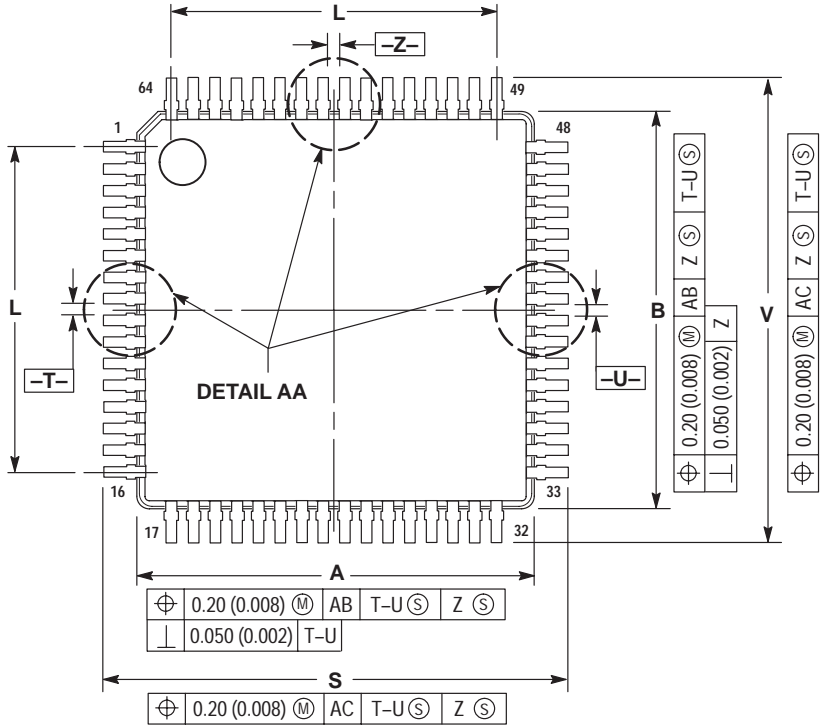
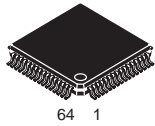
FB SUFFIX
CASE 824E-02
 Plastic Package
 (QFP)
 ISSUE A



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DATUM PLANE -H- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
 4. DATUMS -L-, -M- AND -N- TO BE DETERMINED AT DATUM PLANE -H-.
 5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -T-.
 6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
 7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.530 (0.021).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.90	10.10	0.390	0.398
B	9.90	10.10	0.390	0.398
C	2.00	2.21	0.079	0.087
D	0.30	0.45	0.0118	0.0177
E	2.00	2.10	0.079	0.083
F	0.30	0.40	0.012	0.016
G	0.80 BSC		0.031 BSC	
J	0.13	0.23	0.005	0.009
K	0.65	0.95	0.026	0.037
M	5° 10°		5° 10°	
S	12.95	13.45	0.510	0.530
V	12.95	13.45	0.510	0.530
W	0.000	0.210	0.000	0.008
Y	5° 10°		5° 10°	
A1	0.450 REF		0.018 REF	
B1	0.130	0.170	0.005	0.007
C1	1.600 REF		0.063 REF	
R1	0.130	0.300	0.005	0.012
R2	0.130	0.300	0.005	0.012
theta 1	5° 10°		5° 10°	
theta 2	0° 7°		0° 7°	

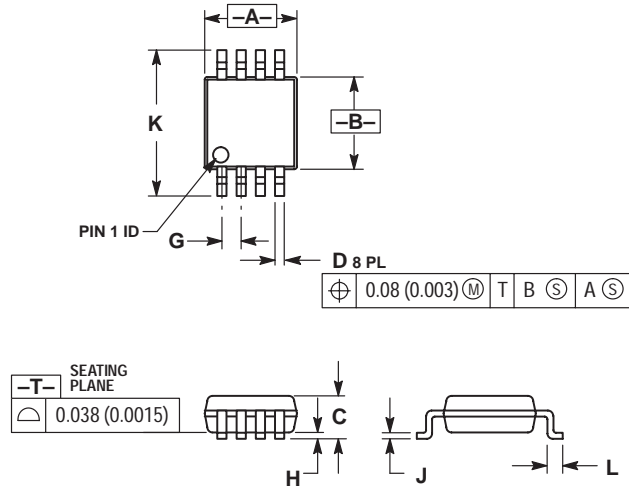
FB SUFFIX
CASE 840F-01
 Plastic Package
 ISSUE O



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
 4. DATUMS -T-, -U- AND -Z- TO BE DETERMINED AT DATUM PLANE -AC-.
 5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -AC-.
 6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.
 7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.350 (0.014).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.950	10.050	0.392	0.396
B	9.950	10.050	0.392	0.396
C	1.400	1.600	0.055	0.063
D	0.170	0.270	0.007	0.011
E	1.350	1.450	0.053	0.057
F	0.170	0.230	0.007	0.009
G	0.500 BSC		0.020 BSC	
H	0.050	0.150	0.002	0.006
J	0.090	0.200	0.004	0.008
K	0.450	0.550	0.018	0.022
L	7.500 BSC		0.295 BSC	
M	12° REF		12° REF	
N	0.090	0.160	0.004	0.006
P	0.250 BSC		0.010 BSC	
Q	1°	5°	1°	5°
R	0.100	0.200	0.004	0.008
S	11.900	12.100	0.469	0.476
V	11.900	12.100	0.469	0.476
W	0.200 REF		0.008 REF	
X	1.000 REF		0.039 REF	
Y	12° REF		12° REF	

DM SUFFIX
CASE 846A-02
 Plastic Package
 (Micro-8)
 ISSUE C

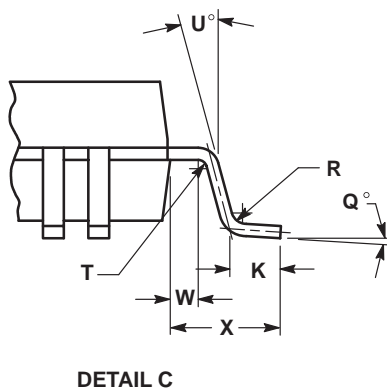
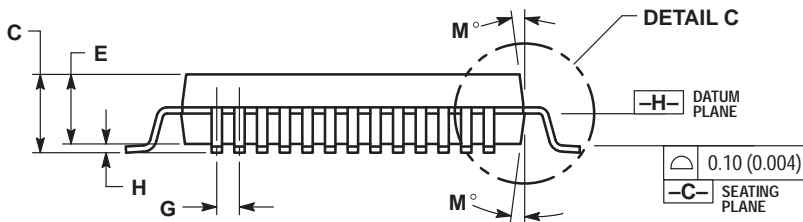
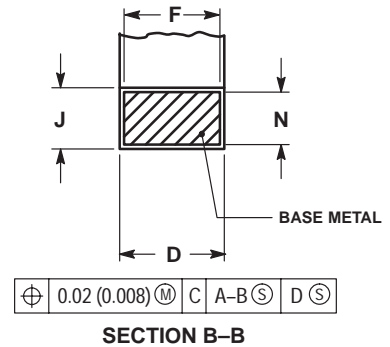
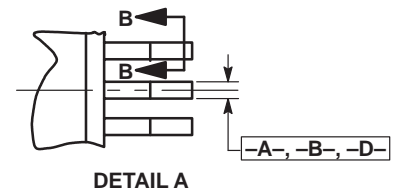
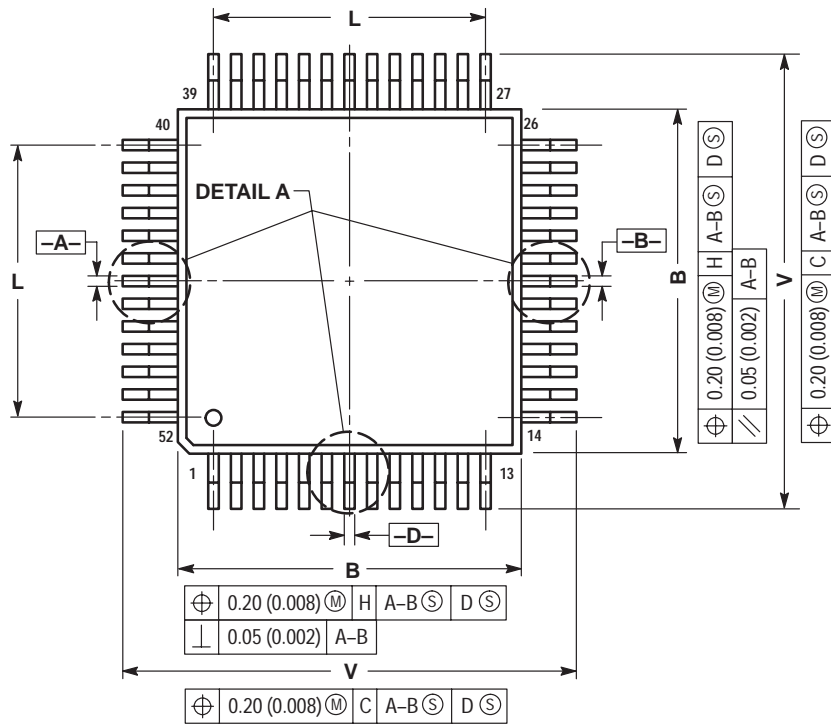
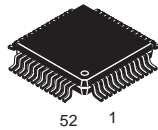


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	2.90	3.10	0.114	0.122
C	---	1.10	---	0.043
D	0.25	0.40	0.010	0.016
G	0.65 BSC		0.026 BSC	
H	0.05	0.15	0.002	0.006
J	0.13	0.23	0.005	0.009
K	4.75	5.05	0.187	0.199
L	0.40	0.70	0.016	0.028

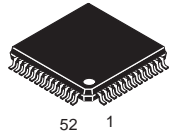
FB SUFFIX
CASE 848B-04
 Plastic Package
 (TQFP-52)
 ISSUE C



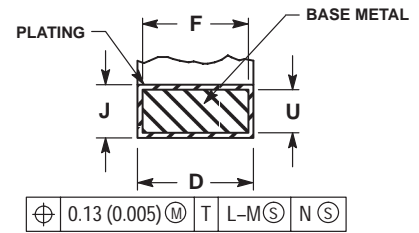
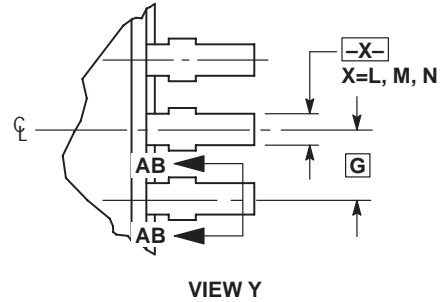
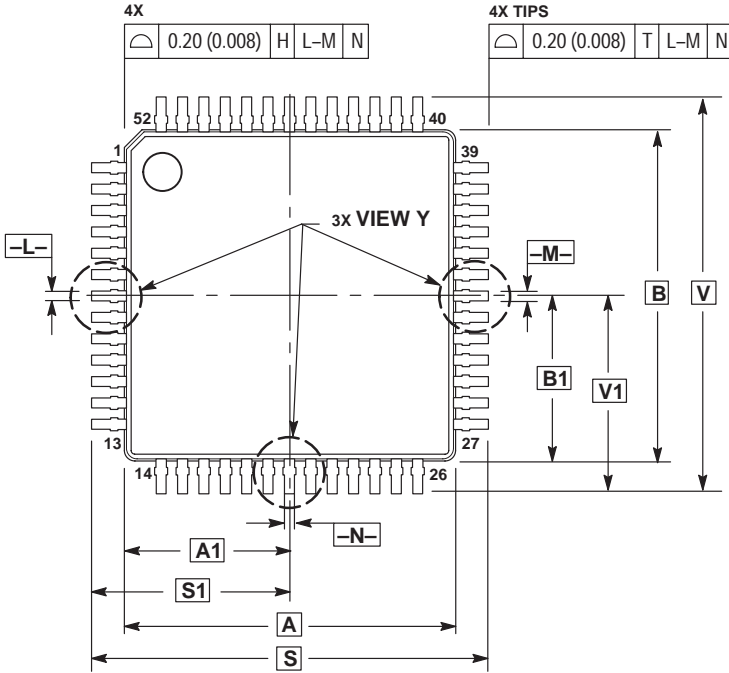
- NOTES:
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 - CONTROLLING DIMENSION: MILLIMETER.
 - DATUM PLANE -H- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
 - DATUMS -A-, -B- AND -D- TO BE DETERMINED AT DATUM PLANE -H-.
 - DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -C-.
 - DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
 - DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.90	10.10	0.390	0.398
B	9.90	10.10	0.390	0.398
C	2.10	2.45	0.083	0.096
D	0.22	0.38	0.009	0.015
E	2.00	2.10	0.079	0.083
F	0.22	0.33	0.009	0.013
G	0.65 BSC		0.026 BSC	
H	--- 0.25		--- 0.010	
J	0.13	0.23	0.005	0.009
K	0.65	0.95	0.026	0.037
L	7.80 REF		0.307 REF	
M	5°	10°	5°	10°
N	0.13	0.17	0.005	0.007
Q	0°	7°	0°	7°
R	0.13	0.30	0.005	0.012
S	12.95	13.45	0.510	0.530
T	0.13	---	0.005	---
U	0°	---	0°	---
V	12.95	13.45	0.510	0.530
W	0.35	0.45	0.014	0.018
X	1.6 REF		0.063 REF	

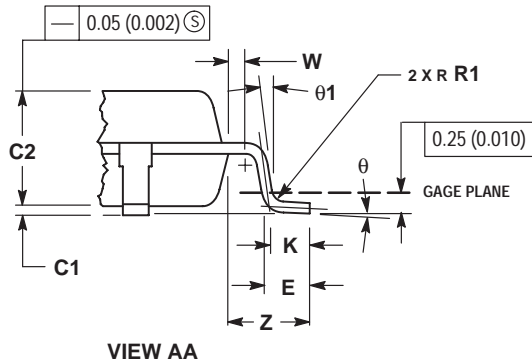
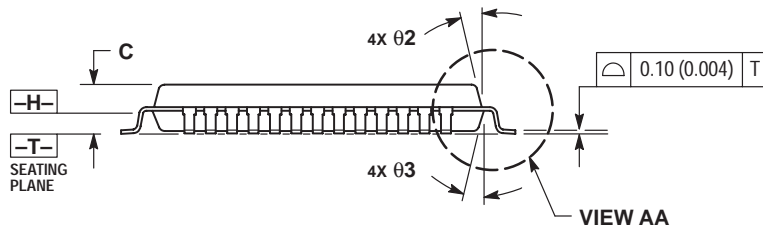
FB SUFFIX
CASE 848D-03
 Plastic Package
 ISSUE C



52 1



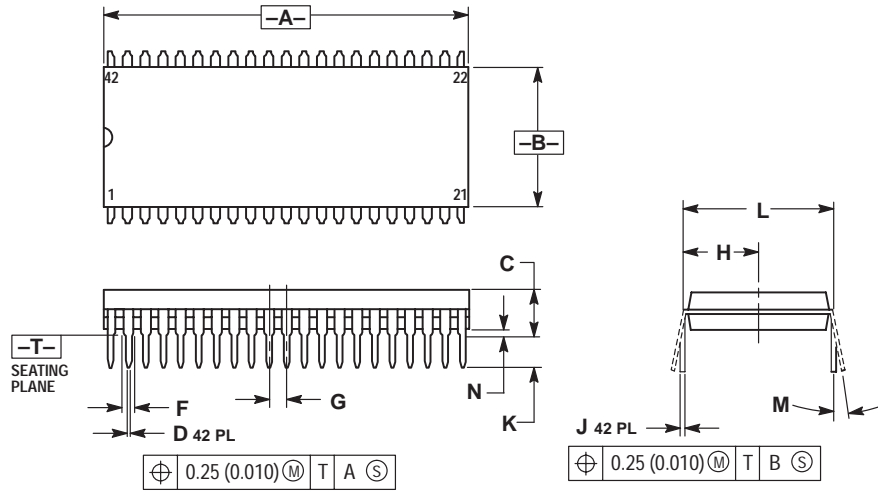
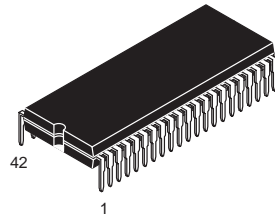
SECTION AB-AB
 ROTATED 90° CLOCKWISE



- NOTES:**
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DATUM PLANE -H- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
 4. DATUMS -L-, -M- AND -N- TO BE DETERMINED AT DATUM PLANE -H-.
 5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -T-.
 6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO NOT INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
 7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.46 (0.018). MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION 0.07 (0.003).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	10.00 BSC	0.394 BSC		
A1	5.00 BSC	0.197 BSC		
B	10.00 BSC	0.394 BSC		
B1	5.00 BSC	0.197 BSC		
C	---	1.70	---	0.067
C1	0.05	0.20	0.002	0.008
C2	1.30	1.50	0.051	0.059
D	0.20	0.40	0.008	0.016
E	0.45	0.75	0.018	0.030
F	0.22	0.35	0.009	0.014
G	0.65 BSC	0.026 BSC		
J	0.07	0.20	0.003	0.008
K	0.50 REF	0.020 REF		
R1	0.08	0.20	0.003	0.008
S	12.00 BSC	0.472 BSC		
S1	6.00 BSC	0.236 BSC		
U	0.09	0.16	0.004	0.006
V	12.00 BSC	0.472 BSC		
V1	6.00 BSC	0.236 BSC		
W	0.20 REF	0.008 REF		
Z	1.00 REF	0.039 REF		
theta	0°	7°	0°	7°
theta1	0°	---	0°	---
theta2	12° REF	12° REF		
theta3	5°	13°	5°	13°

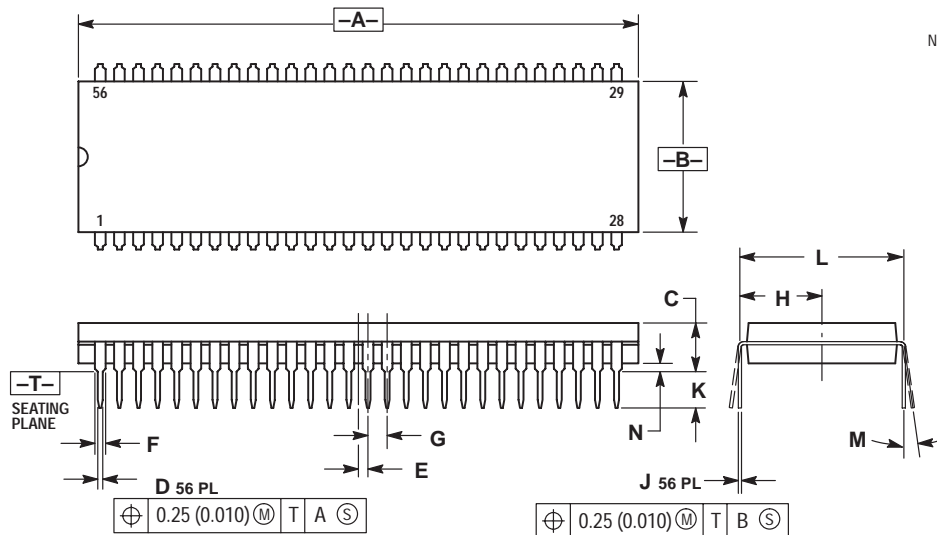
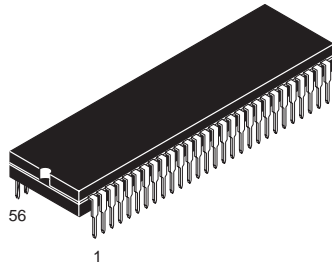
B SUFFIX
CASE 858-01
 Plastic Package
 ISSUE O



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH. MAXIMUM MOLD FLASH 0.25 (0.010).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.435	1.465	36.45	37.21
B	0.540	0.560	13.72	14.22
C	0.155	0.200	3.94	5.08
D	0.014	0.022	0.36	0.56
F	0.032	0.046	0.81	1.17
G	0.070 BSC		1.778 BSC	
H	0.300 BSC		7.62 BSC	
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.600 BSC		15.24 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.02

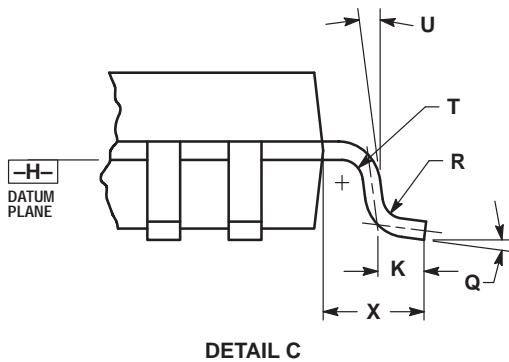
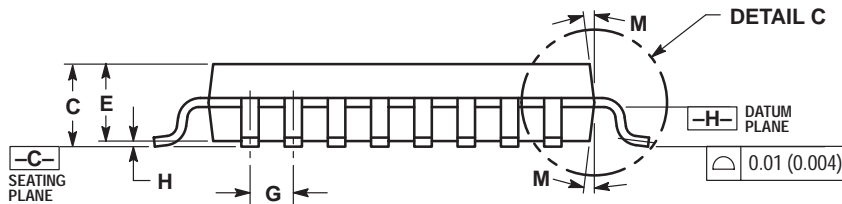
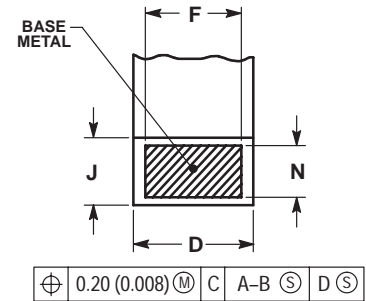
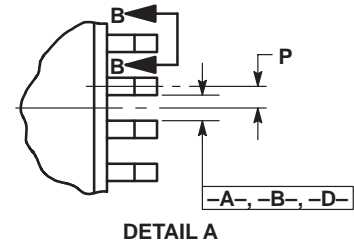
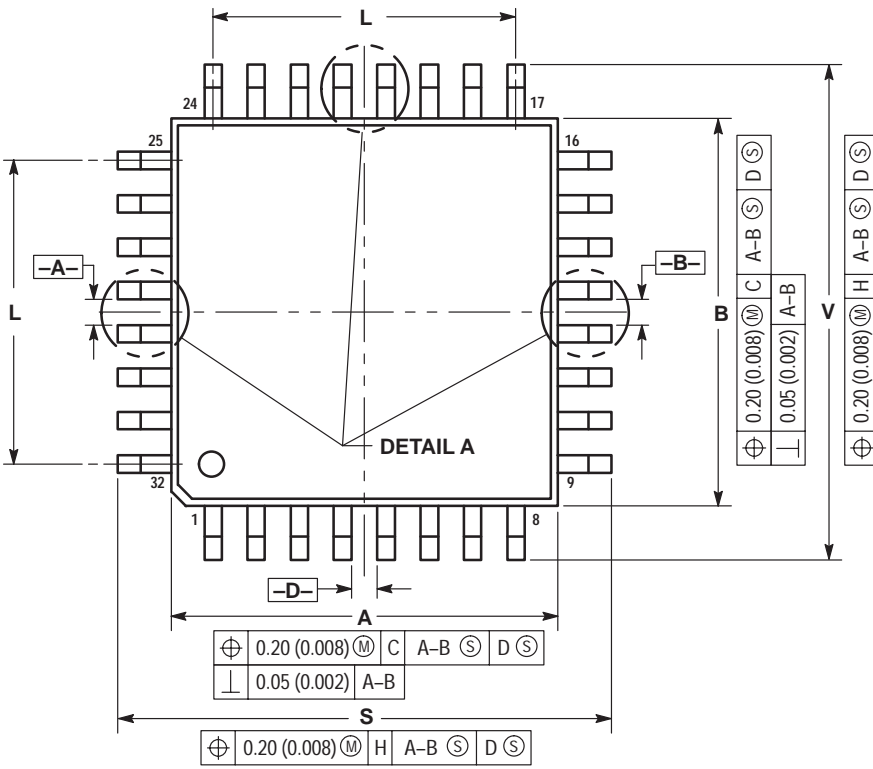
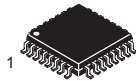
B SUFFIX
CASE 859-01
 Plastic Package
 (SDIP)
 ISSUE O



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH. MAXIMUM MOLD FLASH 0.25 (0.010)

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	2.035	2.065	51.69	52.45
B	0.540	0.560	13.72	14.22
C	0.155	0.200	3.94	5.08
D	0.014	0.022	0.36	0.56
E	0.035 BSC		0.89 BSC	
F	0.032	0.046	0.81	1.17
G	0.070 BSC		1.778 BSC	
H	0.300 BSC		7.62 BSC	
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.600 BSC		15.24 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.02

FB, FTB SUFFIX
CASE 873-01
 Plastic Package
 (TQFP-32)
 ISSUE A

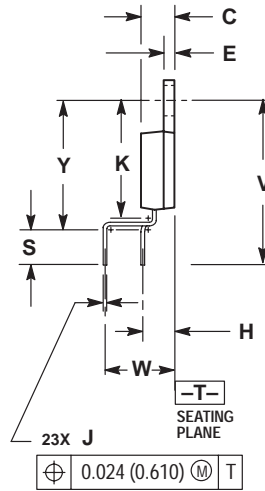
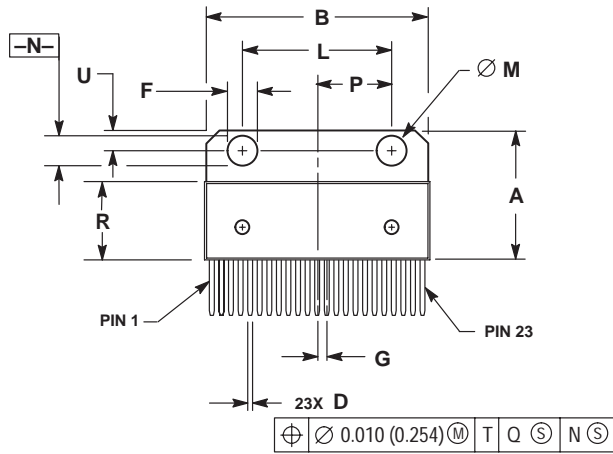
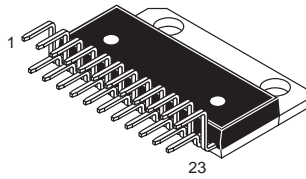


NOTES:

- DIMENSION AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
- DATUM PLANE -H- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
- DATUMS -A-, -B- AND -D- TO BE DETERMINED AT DATUM PLANE -H-.
- DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -C-.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.95	7.10	0.274	0.280
B	6.95	7.10	0.274	0.280
C	1.40	1.60	0.055	0.063
D	0.273	0.373	0.010	0.015
E	1.30	1.50	0.051	0.059
F	0.273	---	0.010	---
G	0.80	BSC	0.031	BSC
H	---	0.20	---	0.008
J	0.119	0.197	0.005	0.008
K	0.33	0.57	0.013	0.022
L	5.6	REF	0.220	REF
M	6°	8°	6°	8°
N	0.119	0.135	0.005	0.005
P	0.40	BSC	0.016	BSC
Q	5°	10°	5°	10°
R	0.15	0.25	0.006	0.010
S	8.85	9.15	0.348	0.360
T	0.15	0.25	0.006	0.010
U	5°	11°	5°	11°
V	8.85	9.15	0.348	0.360
X	1.00	REF	0.039	REF

T SUFFIX
CASE 894-03
 Plastic Package
 (23-Pin SZIP)
 ISSUE B

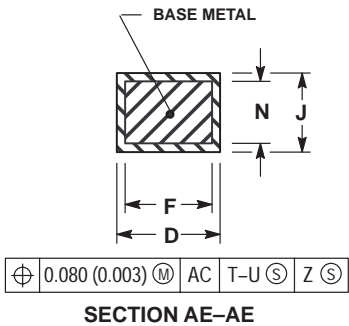
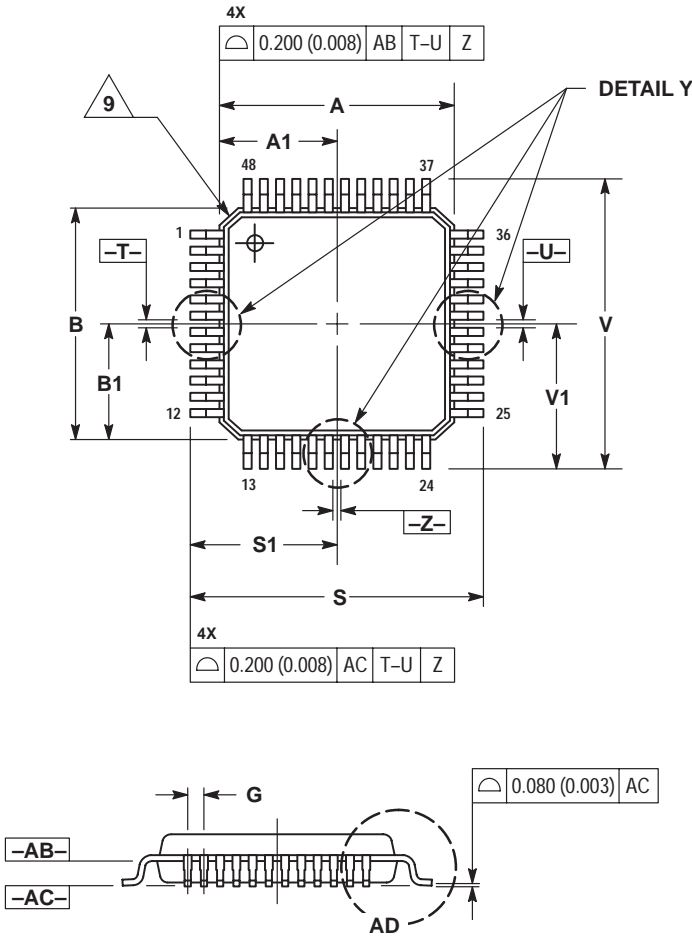
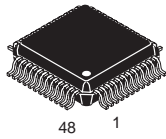


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION R DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
5. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.010 (0.250).
6. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.003 (0.076) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.684	0.694	17.374	17.627
B	1.183	1.193	30.048	30.302
C	0.175	0.179	4.445	4.547
D	0.026	0.031	0.660	0.787
E	0.058	0.062	1.473	1.574
F	0.165	0.175	4.191	4.445
G	0.050 BSC		1.270 BSC	
H	0.169 BSC		4.293 BSC	
J	0.014	0.020	0.356	0.508
K	0.625	0.639	15.875	16.231
L	0.770	0.790	19.558	20.066
M	0.148	0.152	3.760	3.861
N	0.148	0.152	3.760	3.861
P	0.390 BSC		9.906 BSC	
R	0.416	0.424	10.566	10.770
S	0.157	0.167	3.988	4.242
U	0.105	0.115	2.667	2.921
V	0.868 REF		22.047 REF	
W	0.200 BSC		5.080 BSC	
Y	0.700	0.710	17.780	18.034

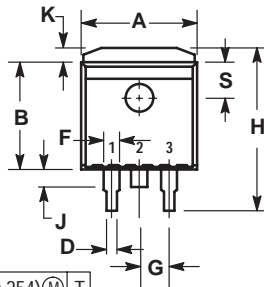
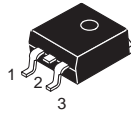
FTA SUFFIX
CASE 932-02
 Plastic Package
 (TQFP-48)
 ISSUE D



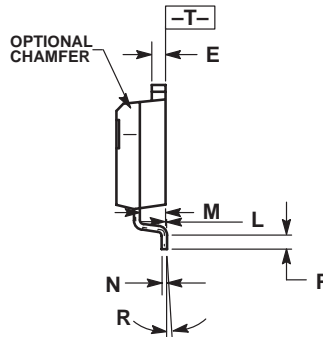
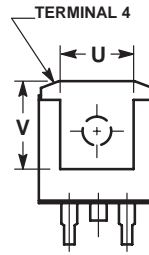
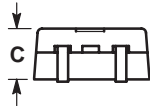
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
 4. DATUMS -T-, -U-, AND -Z- TO BE DETERMINED AT DATUM PLANE -AB-.
 5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -AC-.
 6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.
 7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.350 (0.014).
 8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076 (0.0003).
 9. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	7.000 BSC		0.276 BSC	
A1	3.500 BSC		0.138 BSC	
B	7.000 BSC		0.276 BSC	
B1	3.500 BSC		0.138 BSC	
C	1.400	1.600	0.055	0.063
D	0.170	0.270	0.007	0.011
E	1.350	1.450	0.053	0.057
F	0.170	0.230	0.007	0.009
G	0.500 BASIC		0.020 BASIC	
H	0.050	0.150	0.002	0.006
J	0.090	0.200	0.004	0.008
K	0.500	0.700	0.020	0.028
M	12° REF		12° REF	
N	0.090	0.160	0.004	0.006
P	0.250 BASIC		0.010 BASIC	
Q	1°	5°	1°	5°
R	0.150	0.250	0.006	0.010
S	9.000 BSC		0.354 BSC	
S1	4.500 BSC		0.177 BSC	
V	9.000 BSC		0.354 BSC	
V1	4.500 BSC		0.177 BSC	
W	0.200 REF		0.008 REF	
X	1.000 REF		0.039 REF	

D2T SUFFIX
CASE 936-03
 Plastic Package
 ISSUE B



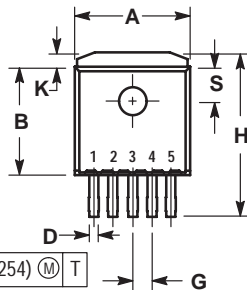
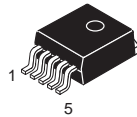
⊕ 0.010 (0.254) Ⓜ T



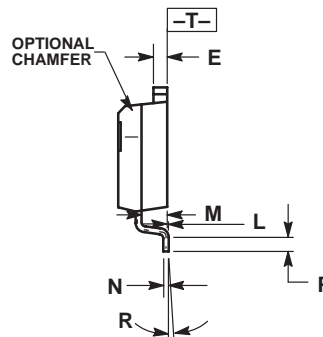
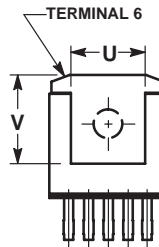
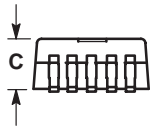
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. TAB CONTOUR OPTIONAL WITHIN DIMENSIONS A AND K.
 4. DIMENSIONS U AND V ESTABLISH A MINIMUM MOUNTING SURFACE FOR TERMINAL 4.
 5. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.025 (0.635) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.386	0.403	9.804	10.236
B	0.356	0.368	9.042	9.347
C	0.170	0.180	4.318	4.572
D	0.026	0.036	0.660	0.914
E	0.045	0.055	1.143	1.397
F	0.051 REF		1.295 REF	
G	0.100 BSC		2.540 BSC	
H	0.539	0.579	13.691	14.707
J	0.125 MAX		3.175 MAX	
K	0.050 REF		1.270 REF	
L	0.000	0.010	0.000	0.254
M	0.088	0.102	2.235	2.591
N	0.018	0.026	0.457	0.660
P	0.058	0.078	1.473	1.981
R	5° REF		5° REF	
S	0.116 REF		2.946 REF	
U	0.200 MIN		5.080 MIN	
V	0.250 MIN		6.350 MIN	

D2T SUFFIX
CASE 936A-02
 Plastic Package
 (D²PAK)
 ISSUE A



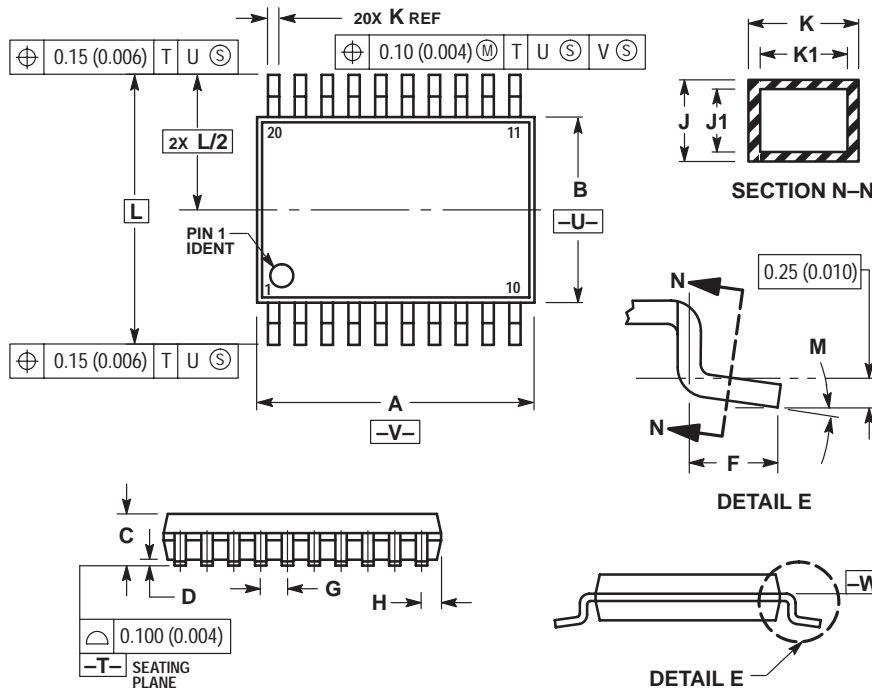
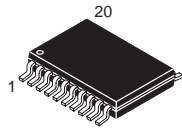
⊕ 0.010 (0.254) Ⓜ T



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. TAB CONTOUR OPTIONAL WITHIN DIMENSIONS A AND K.
 4. DIMENSIONS U AND V ESTABLISH A MINIMUM MOUNTING SURFACE FOR TERMINAL 6.
 5. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.025 (0.635) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.386	0.403	9.804	10.236
B	0.356	0.368	9.042	9.347
C	0.170	0.180	4.318	4.572
D	0.026	0.036	0.660	0.914
E	0.045	0.055	1.143	1.397
G	0.067 BSC		1.702 BSC	
H	0.539	0.579	13.691	14.707
K	0.050 REF		1.270 REF	
L	0.000	0.010	0.000	0.254
M	0.088	0.102	2.235	2.591
N	0.018	0.026	0.457	0.660
P	0.058	0.078	1.473	1.981
R	5° REF		5° REF	
S	0.116 REF		2.946 REF	
U	0.200 MIN		5.080 MIN	
V	0.250 MIN		6.350 MIN	

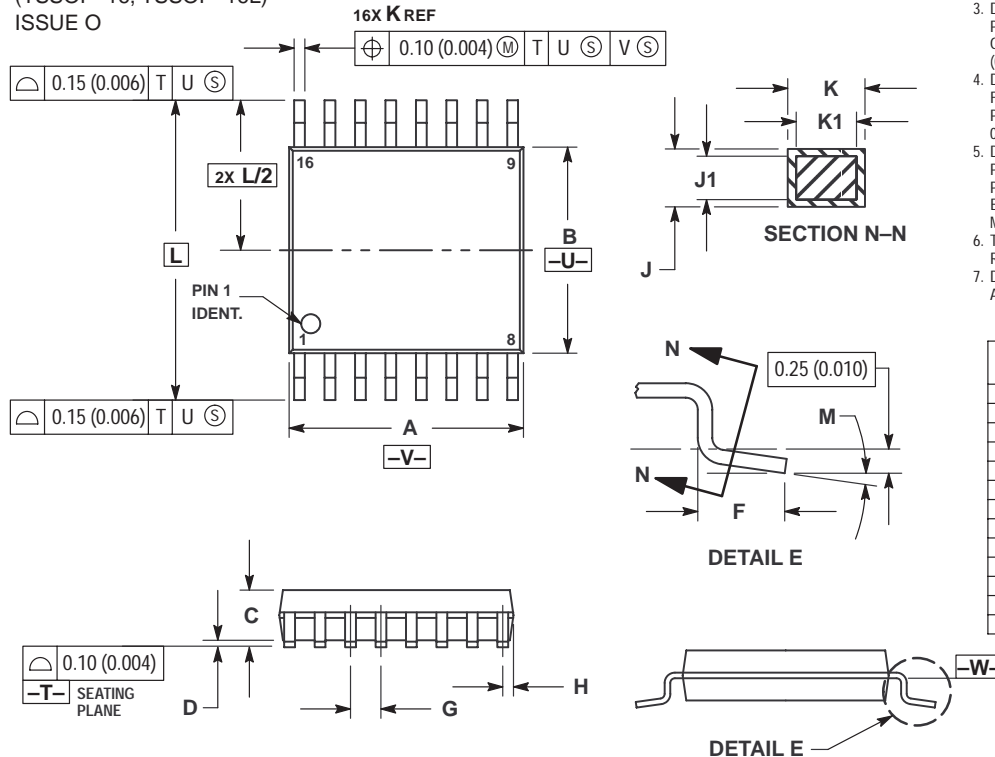
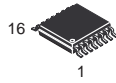
DT, DTB SUFFIX
CASE 948E-02
 Plastic Package
 (TSSOP-20)
 ISSUE A



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.40	6.60	0.252	0.260
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

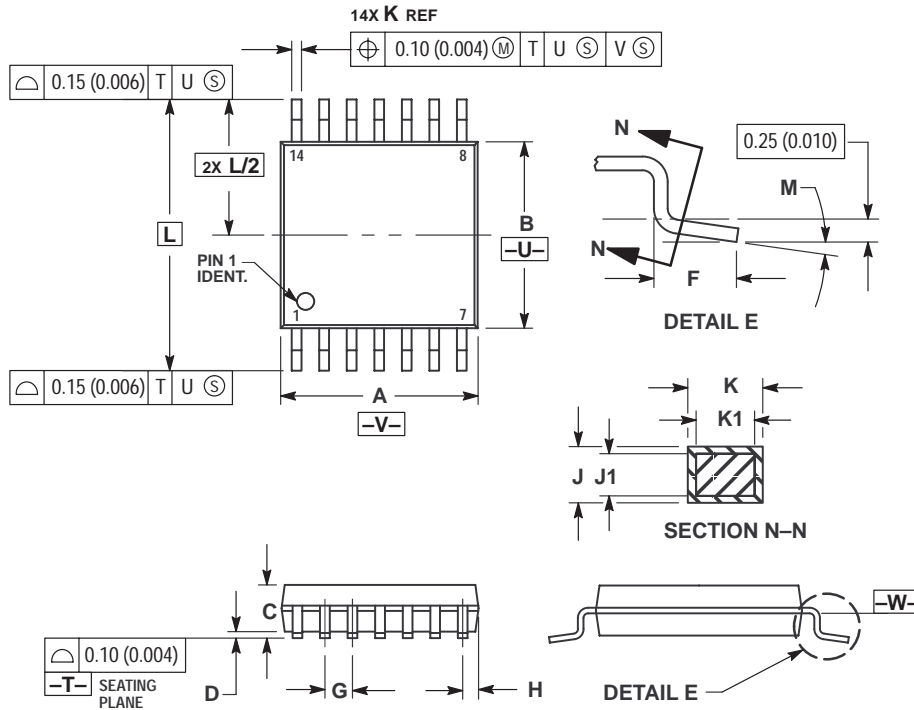
DTB SUFFIX
CASE 948F-01
 Plastic Package
 (TSSOP-16, TSSOP-16L)
 ISSUE O



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

DTB SUFFIX
CASE 948G-01
 Plastic Package
 (TSSOP-14)
 ISSUE O

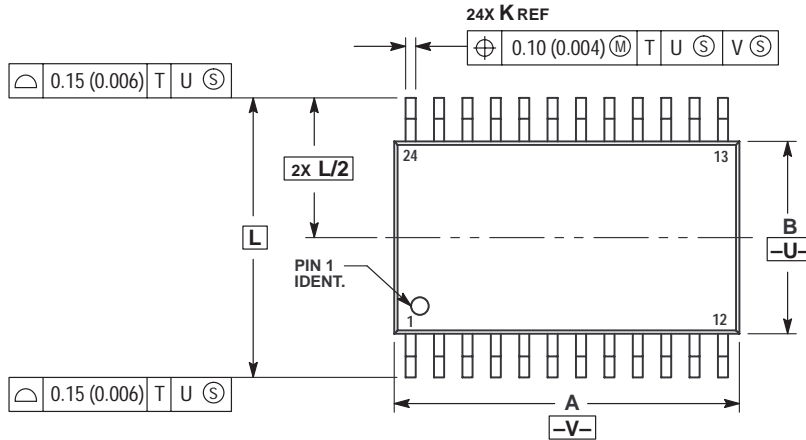
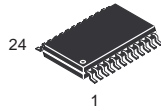


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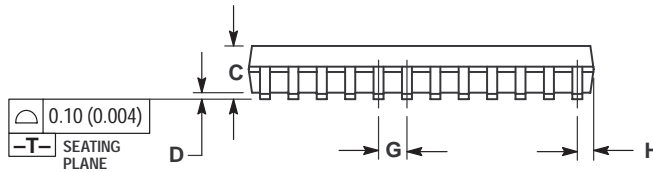
- 1 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2 CONTROLLING DIMENSION: MILLIMETER.
- 3 DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- 4 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- 5 DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 6 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- 7 DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

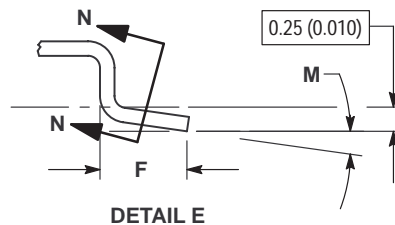
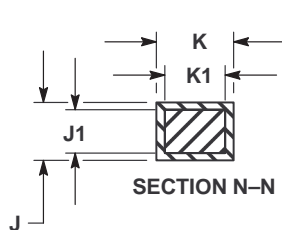
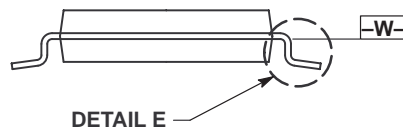
DTB SUFFIX
CASE 948H-01
 Plastic Package
 ISSUE O



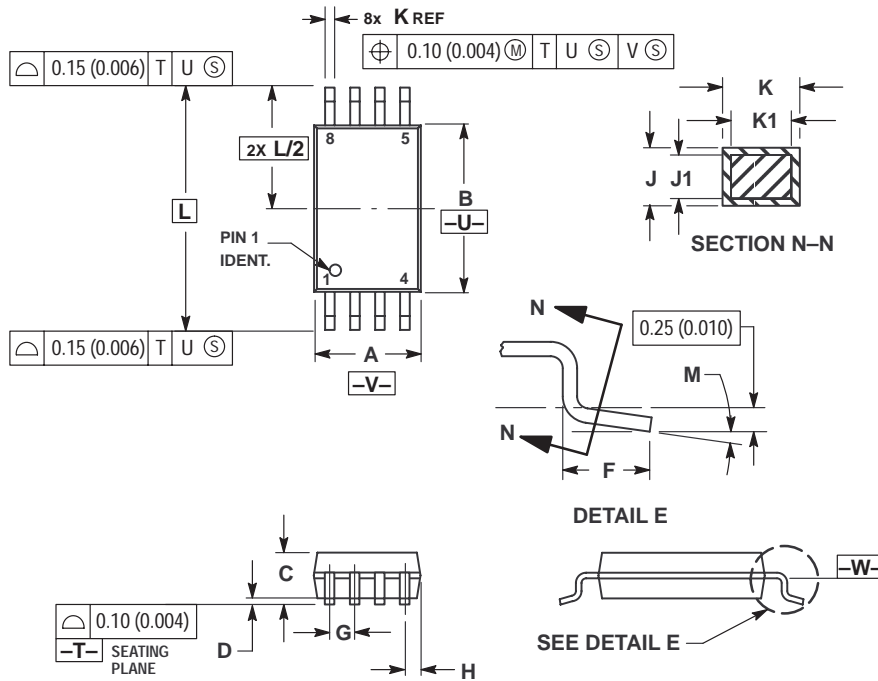
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	7.70	7.90	0.303	0.311
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°



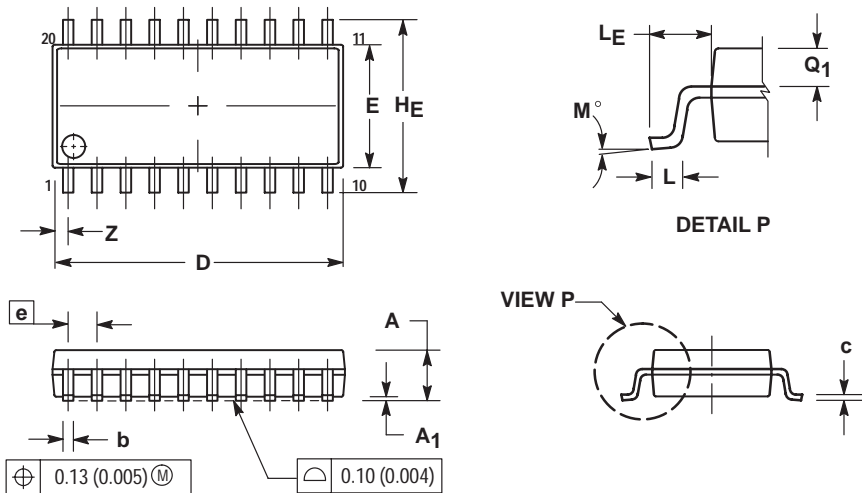
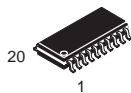
DTB SUFFIX
CASE 948J-01
 Plastic Package
 (TSSOP-8)
 ISSUE O



- NOTES:
- 1 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 - 2 CONTROLLING DIMENSION: MILLIMETER.
 - 3 DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 - 4 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 - 5 DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 - 6 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 - 7 DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

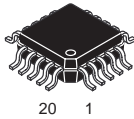
M SUFFIX
CASE 967-01
 Plastic Package
 (EIAJ-20)
 ISSUE O



- NOTES:
- 1 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 - 2 CONTROLLING DIMENSION: MILLIMETER.
 - 3 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 - 4 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 - 5 THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	12.35	12.80	0.486	0.504
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q1	0.70	0.90	0.028	0.035
Z	---	0.81	---	0.032

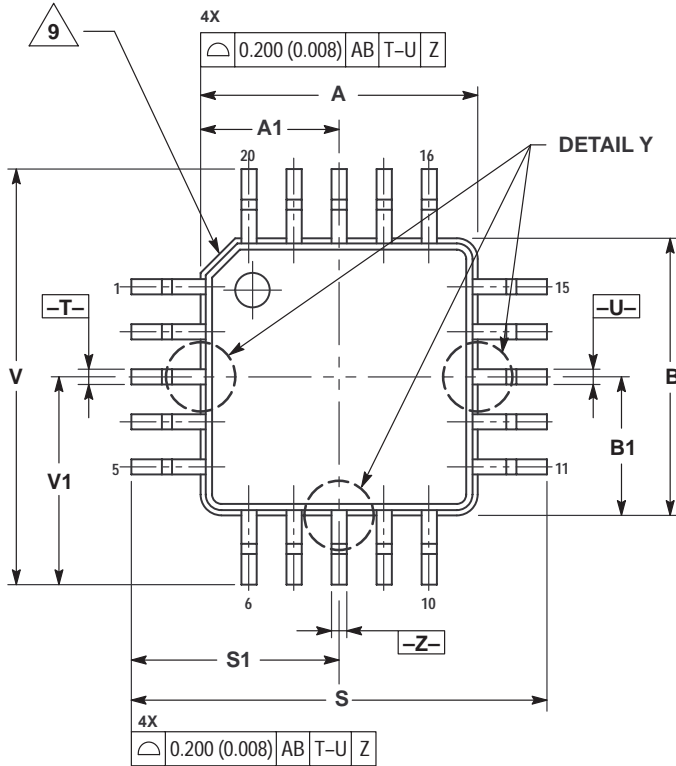
FTB SUFFIX
CASE 976-01
 Plastic Package
 (TQFP-20)
 ISSUE O



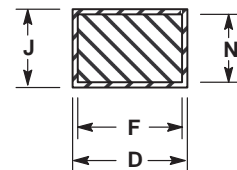
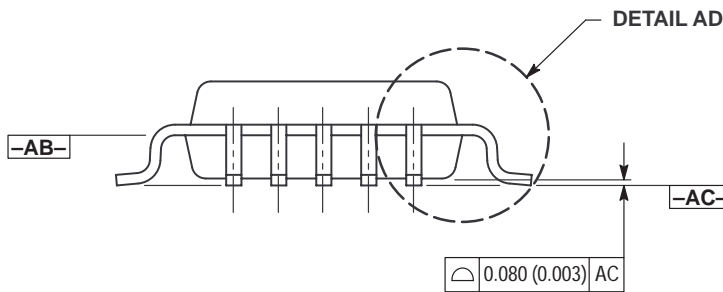
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NOTES:

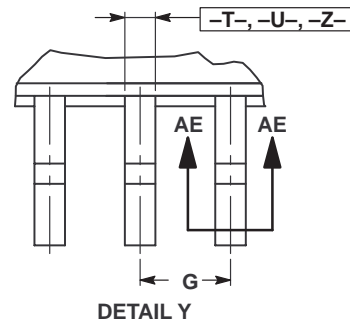
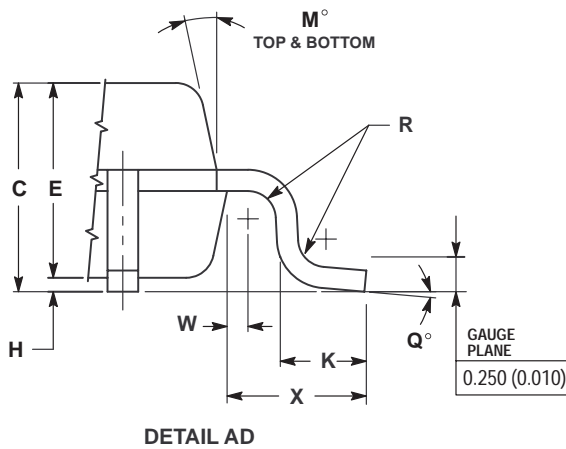
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS -T-, -U-, AND -Z- TO BE DETERMINED AT DATUM PLANE -AB-.
5. DIMENSIONS S AND V TO BE DETERMINED AT DATUM PLANE -AC-.
6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.
7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.350 (0.014).
8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076 (0.0003).
9. EXACT SHAPE OF EACH CORNER IS OPTIONAL.



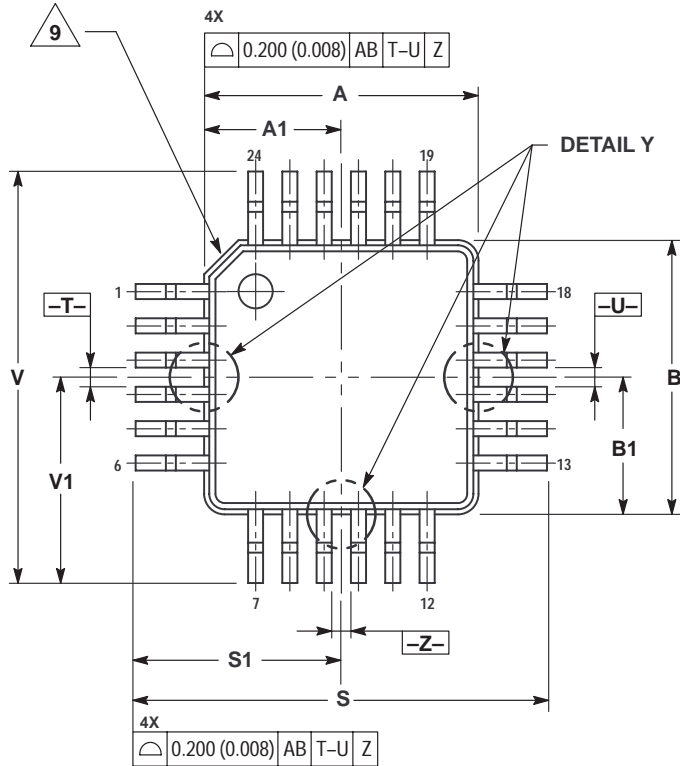
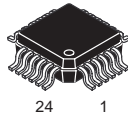
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.000	BSC	0.157	BSC
A1	2.000	BSC	0.079	BSC
B	4.000	BSC	0.157	BSC
B1	2.000	BSC	0.079	BSC
C	1.400	1.600	0.055	0.063
D	0.170	0.270	0.007	0.011
E	1.350	1.450	0.053	0.057
F	0.170	0.230	0.007	0.009
G	0.650	BSC	0.026	BSC
H	0.050	0.150	0.002	0.006
J	0.090	0.200	0.004	0.008
K	0.500	0.700	0.020	0.028
M	12°	REF	12°	REF
N	0.090	0.160	0.004	0.006
P	0.250	BSC	0.010	BSC
Q	1°	5°	1°	5°
R	0.150	0.250	0.006	0.010
S	6.000	BSC	0.236	BSC
S1	3.000	BSC	0.118	BSC
V	6.000	BSC	0.236	BSC
V1	3.000	BSC	0.118	BSC
W	0.200	REF	0.008	REF
X	1.000	REF	0.039	REF



SECTION AE-AE

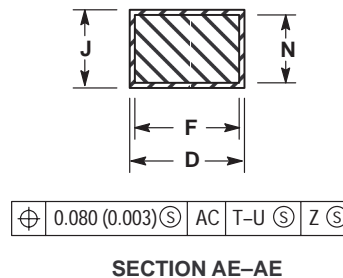
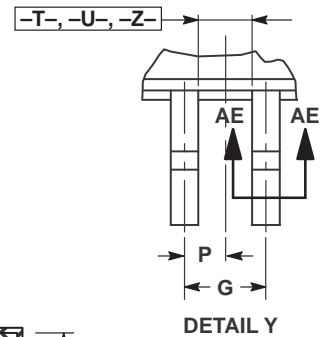
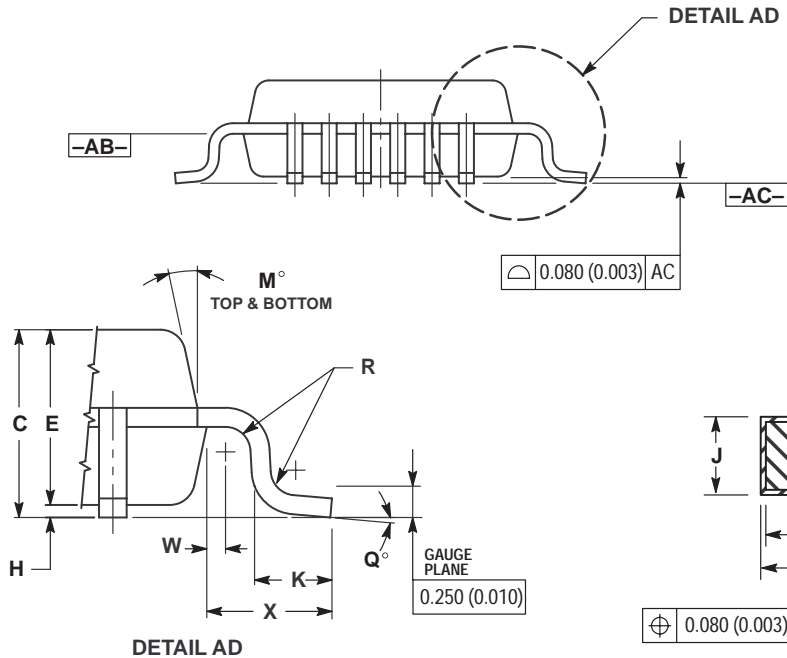


FTA SUFFIX
CASE 977-01
Plastic Package
ISSUE O

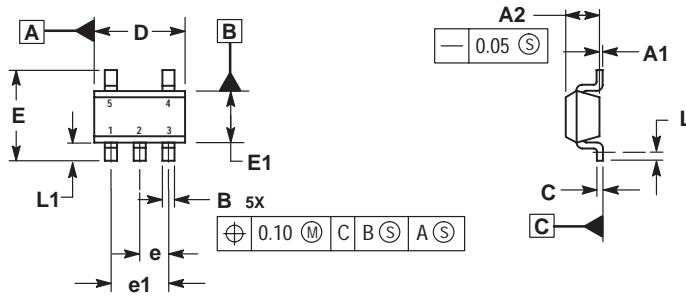


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
 4. DATUMS -T-, -U-, AND -Z- TO BE DETERMINED AT DATUM PLANE -AB-.
 5. DIMENSIONS S AND V TO BE DETERMINED AT DATUM PLANE -AC-.
 6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.
 7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.350 (0.014).
 8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076 (0.0003).
 9. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.000 BSC		0.157 BSC	
A1	2.000 BSC		0.079 BSC	
B	4.000 BSC		0.157 BSC	
B1	2.000 BSC		0.079 BSC	
C	1.400	1.600	0.055	0.063
D	0.170	0.270	0.007	0.011
E	1.350	1.450	0.053	0.057
F	0.170	0.230	0.007	0.009
G	0.500 BSC		0.020 BSC	
H	0.050	0.150	0.002	0.006
J	0.090	0.200	0.004	0.008
K	0.500	0.700	0.020	0.028
M	12° REF		12° REF	
N	0.090	0.160	0.004	0.006
P	0.250 BSC		0.010 BSC	
Q	1°	5°	1°	5°
R	0.150	0.250	0.006	0.010
S	6.000 BSC		0.236 BSC	
S1	3.000 BSC		0.118 BSC	
V	6.000 BSC		0.236 BSC	
V1	3.000 BSC		0.118 BSC	
W	0.200 REF		0.008 REF	
X	1.000 REF		0.039 REF	



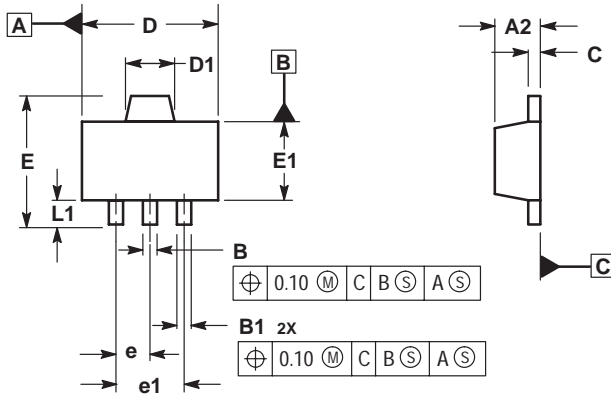
N SUFFIX
CASE 1212-01
 Plastic Package
 (SOT-23)
 ISSUE O



- NOTES:
 1. DIMENSIONS ARE IN MILLIMETERS.
 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
 3. DATUM C IS A SEATING PLANE.

MILLIMETERS		
DIM	MIN	MAX
A1	0.00	0.10
A2	1.00	1.30
B	0.30	0.50
C	0.10	0.25
D	2.80	3.00
E	2.50	3.10
E1	1.50	1.80
e	0.95 BSC	
e1	1.90 BSC	
L	0.20	----
L1	0.45	0.75

H SUFFIX
CASE 1213-01
 Plastic Package
 (SOT-89)
 ISSUE O



- NOTES:
 1. DIMENSIONS ARE IN MILLIMETERS.
 2. INTERPRET DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
 3. DATUM C IS A SEATING PLANE.

MILLIMETERS		
DIM	MIN	MAX
A2	1.40	1.60
B	0.37	0.57
B1	0.32	0.52
C	0.30	0.50
D	4.40	4.60
D1	1.50	1.70
E	----	4.25
E1	2.40	2.60
e	1.50 BSC	
e1	3.00 BSC	
L1	0.80	----